

SERVICE MANUAL

MODEL	JP	E3	E2	EK	EA	E1	E1C	E1K
RCD-N9	✓		✓				✓	

NETWORK CD RECIEVER

• For purposes of improvement, specifications and design are subject to change without notice.

• Please use this service manual with referring to the operating instructions without fail.

• Some illustrations using in this service manual are slightly different from the actual set.

DENON

D&M Holdings Inc.

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ABOUT THIS MANUAL

Read the following information before using the service manual.

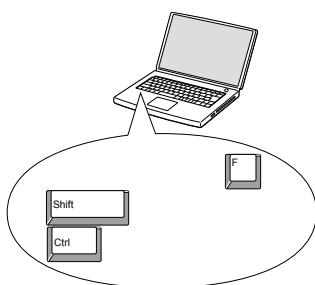
What you can do with this manual

Search for a Ref. No. (phrase) (Ctrl+Shift+F)

You can use the search function in Acrobat Reader to search for a Ref. No. in schematic diagrams, printed wiring circuit diagrams, block diagrams, and parts lists.

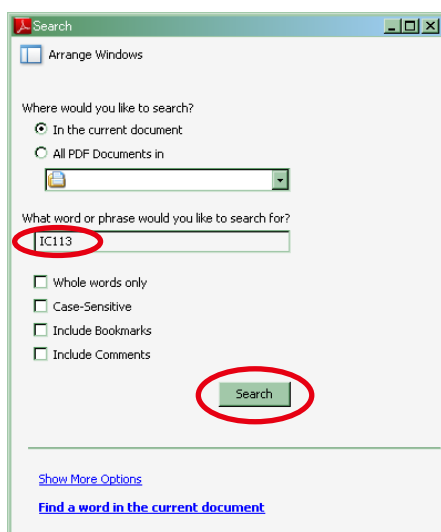
1. Press **Ctrl+Shift+F** on the keyboard.

- The Search window appears.



2. Enter the Ref. No. you want to search for in the Search window, and then click the **Search** button.

- A list of search results appears.



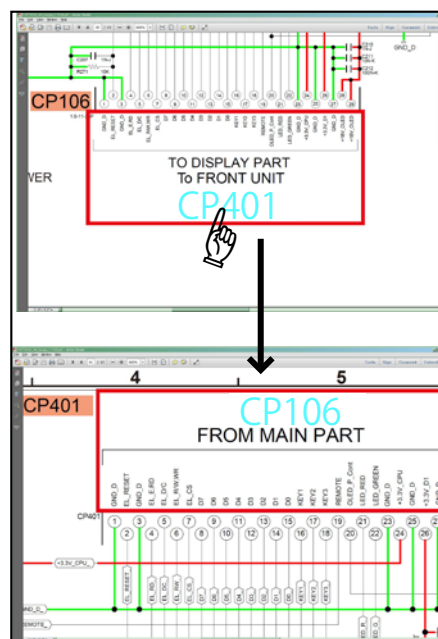
3. Click an item on the list.

- The screen jumps to the page for that item, and the search phrase is displayed.

Jump to the target of a schematic diagram connector

Click the Ref. No. of the target connector in the red box around a schematic diagram connector.

- The screen jumps to the target connector.



- Page magnification stays the same as before the jump.

Using Adobe Reader (Windows version)

Add notes to this data (Sign)

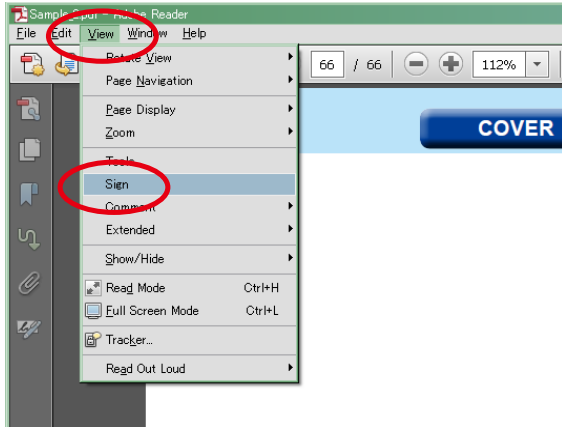
The Sign function lets you add notes to the data in this manual.

Save the file once you have finished adding notes.

[Example using Adobe Reader X]

On the "**View**" menu, click "**Sign**".

- The Sign pane appears.



[Example using Adobe Reader 9]

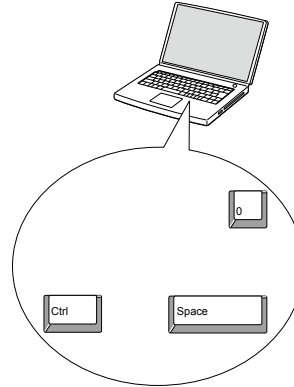
On the "**Document**" menu, click "**Sign**".

Magnify schematic / printed circuit board diagrams - 1

(Ctrl+Space, mouse operation)

Press **Ctrl+Space** on the keyboard and drag the mouse to select the area you want to view.

- The selected area is magnified.

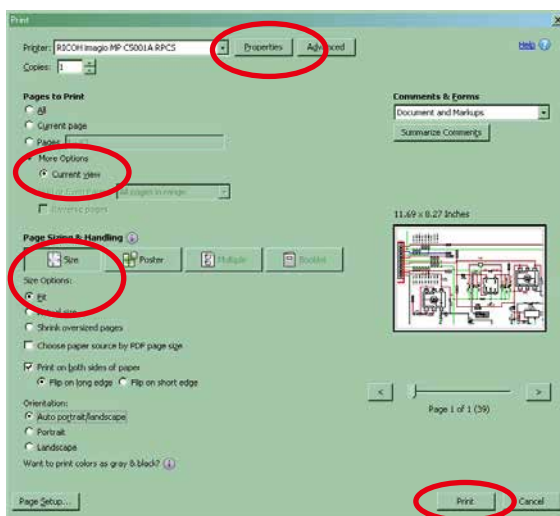


- When you want to move the area shown, hold down **Space** and drag the mouse.
- When you want to show a full page view, press **Ctrl+0** on the keyboard.

Print a magnified part of the manual

The Properties dialog box and functions will vary depending on your printer.

1. Drag the mouse to magnify the part you want to print.
2. On the "**File**" menu, click "**Print**".
3. Configure the following settings in the Print dialog box.



4. Click the **Print** button to start printing.

• Properties

Click this button and check that the printer is set to a suitable paper size.

• Page to print

Select the following checkbox.

"More Options" : "Current View"

• Page Sizing & Handling

Select the following checkbox.

"Size" / "Size Options" : "Fit"

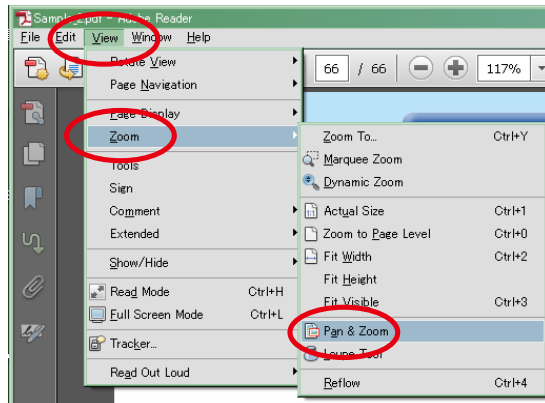
Magnify schematic / printed circuit board diagrams - 2

(Pan & Zoom function)

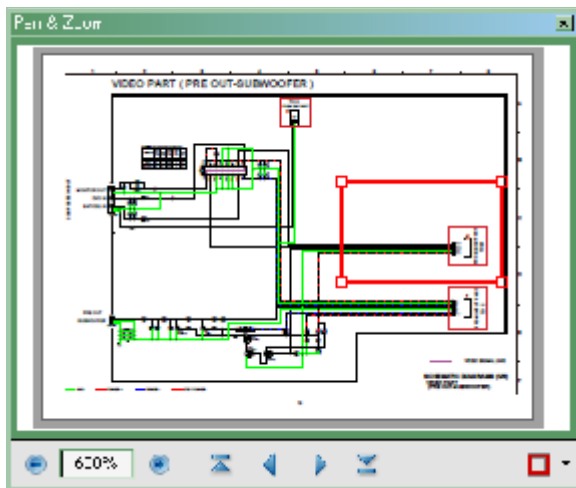
The Pan & Zoom function lets you see which part of a magnified diagram is being shown in a separate window.

[Example using Adobe Reader X]

On the "View" menu, point to "Zoom", and then click "Pan & Zoom".



- The Pan & Zoom window appears on the screen.



[Example using Adobe Reader 9]

On the "Tools" menu, point to "Select & Zoom", and then click "Pan & Zoom Window".

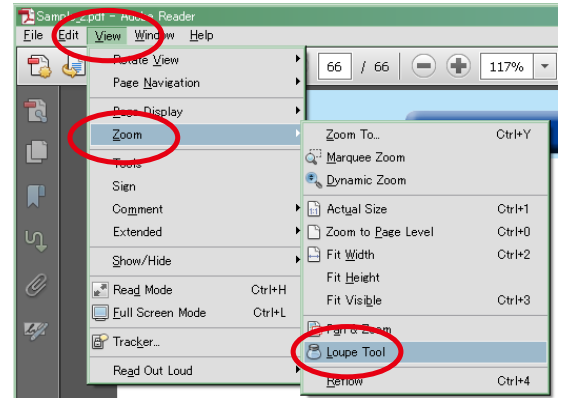
Magnify schematic / printed circuit board diagrams - 3

(Loupe Tool function)

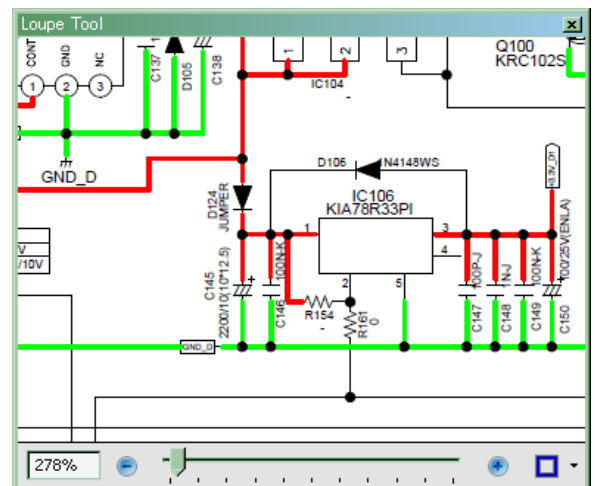
The Loupe Tool function lets you magnify a specific part of a diagram in a separate window.

[Example using Adobe Reader X]

On the "View" menu, point to "Zoom", and then click "Loupe Tool".



- The Loupe Tool window appears on the screen.



[Example using Adobe Reader 9]

On the "Tools" menu, point to "Select & Zoom", and then click "Loupe Tool Window".

SAFETY PRECAUTIONS

The following items should be checked for continued protection of the customer and the service technician.

leakage current check

Before returning the set to the customer, be sure to carry out either (1) a leakage current check or (2) a line to chassis resistance check. If the leakage current exceeds 0.5 milliamps, or if the resistance from chassis to either side of the power cord is less than 460 kohms, the set is defective.

Be sure to test for leakage current with the AC plug in both polarities, in addition, when the set's power is in each state (on, off and standby mode), if applicable.

CAUTION Please heed the following cautions and instructions during servicing and inspection.

⊙ Heed the cautions!

Cautions which are delicate in particular for servicing are labeled on the cabinets, the parts and the chassis, etc. Be sure to heed these cautions and the cautions described in the handling instructions.

⊙ Cautions concerning electric shock!

- (1) An AC voltage is impressed on this set, so if you touch internal metal parts when the set is energized, you may get an electric shock. Avoid getting an electric shock, by using an isolating transformer and wearing gloves when servicing while the set is energized, or by unplugging the power cord when replacing parts, for example.
- (2) There are high voltage parts inside. Handle with extra care when the set is energized.

⊙ Caution concerning disassembly and assembly!

Through great care is taken when parts were manufactured from sheet metal, there may be burrs on the edges of parts. The burrs could cause injury if fingers are moved across them in some rare cases. Wear gloves to protect your hands.

⊙ Use only designated parts!

The set's parts have specific safety properties (fire resistance, voltage resistance, etc.). Be sure to use parts which have the same properties for replacement. The burrs have the same properties. In particular, for the important safety parts that are indicated by the ⚠ mark on schematic diagrams and parts lists, be sure to use the designated parts.

⊙ Be sure to mount parts and arrange the wires as they were originally placed!

For safety reasons, some parts use tapes, tubes or other insulating materials, and some parts are mounted away from the surface of printed circuit boards. Care is also taken with the positions of the wires by arranging them and using clamps to keep them away from heating and high voltage parts, so be sure to set everything back as it was originally placed.

⊙ Make a safety check after servicing!

Check that all screws, parts and wires removed or disconnected when servicing have been put back in their original positions, check that no serviced parts have deteriorate the area around. Then make an insulation check on the external metal connectors and between the blades of the power plug, and otherwise check that safety is ensured.

(Insulation check procedure)

Unplug the power cord from the power outlet, disconnect the antenna, plugs, etc., and on the power. Using a 500V insulation resistance tester, check that the insulation resistance value between the inplug and the externally exposed metal parts (antenna terminal, headphones terminal, input terminal, etc.) is 1MΩ or greater. If it is less, the set must be inspected and repaired.

CAUTION Concerning important safety parts

Many of the electric and the structural parts used in the set have special safety properties. In most cases these properties are difficult to distinguish by sight, and the use of replacement parts with higher ratings (rated power and withstand voltage) does not necessarily guarantee that safety performance will be preserved. Parts with safety properties are indicated as shown below on the wiring diagrams and the parts list in this service manual. Be sure to replace them with the parts which have the designated part number.

- (1) Schematic diagrams.....Indicated by the ⚠ mark.
- (2) Parts lists.....Indicated by the ⚠ mark.

The use of parts other than the designated parts could cause electric shocks, fires or other dangerous situations.

NOTE FOR SCHEMATIC DIAGRAM

WARNING:

Parts indicated by the $\triangle$ mark have critical characteristics. Use ONLY replacement parts recommended by the manufacturer.

CAUTION:

Before returning the set to the customer, be sure to carry out either (1) a leakage current check or (2) a line to chassis resistance check. If the leakage current exceeds 0.5 milliamps, or if the resistance from chassis to either side of the power cord is less than 460 kohms, the set is defective.

WARNING:

DO NOT return the set to the customer unless the problem is identified and remedied.

NOTICE:

ALL RESISTANCE VALUES IN OHM. k=1,000 OHM / M=1,000,000 OHM

ALL CAPACITANCE VALUES ARE EXPRESSED IN MICRO FARAD, UNLESS OTHERWISE INDICATED. P INDICATES MICRO-MICRO FARAD. EACH VOLTAGE AND CURRENT ARE MEASURED AT NO SIGNAL INPUT CONDITION. CIRCUIT AND PARTS ARE SUBJECT TO CHANGE WITHOUT PRIOR NOTICE.

NOTE FOR PARTS LIST

1. Parts indicated by "nsp" on this table cannot be supplied.
2. When ordering a part, make a clear distinction between "1" and "I" (i) to avoid mis-supplying.
3. A part ordered without specifying its part number can not be supplied.
4. Part indicated by "★" mark is not illustrated in the exploded view.

WARNING: Parts indicated by the $\triangle$ mark have critical characteristics. Use ONLY replacement parts recommended by the manufacturer.

INSTRUCTIONS FOR HANDLING SEMI-CONDUCTORS AND OPTICAL UNIT

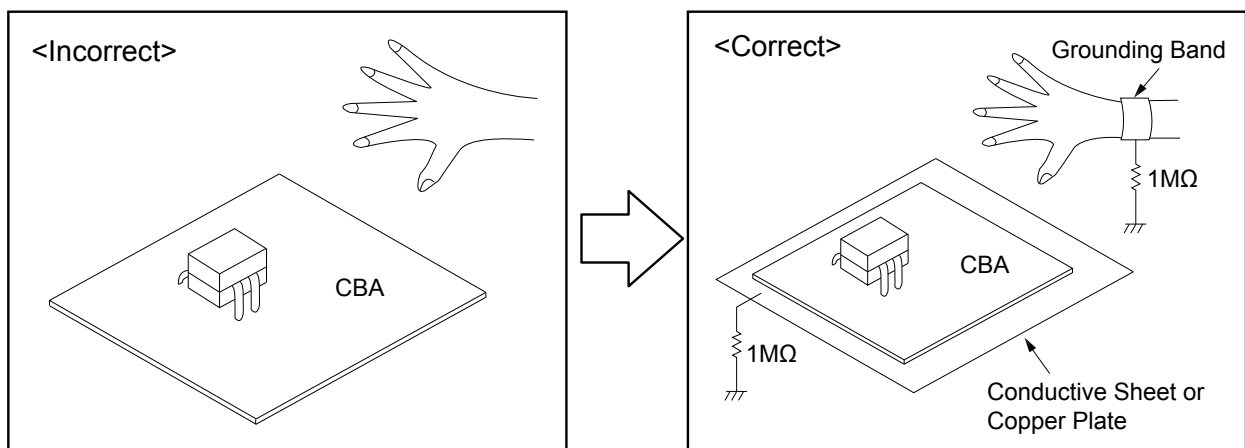
Electrostatic breakdown of the semi-conductors or optical pickup may occur due to a potential difference caused by electrostatic charge during unpacking or repair work.

1. Ground for Human Body

Be sure to wear a grounding band (1 M Ω) that is properly grounded to remove any static electricity that may be charged on the body.

2. Ground for Workbench

Be sure to place a conductive sheet or copper plate with proper grounding (1 M Ω) on the workbench or other surface, where the semi-conductors are to be placed. Because the static electricity charge on clothing will not escape through the body grounding band, be careful to avoid contacting semi-conductors with your clothing



(GB) WARNING

All ICs and many other semi-conductors are susceptible to electrostatic discharges (ESD). Careless handling during repair can reduce life drastically.
When repairing, make sure that you are connected with the same potential as the mass of the set via a wrist wrap with resistance.
Keep components and tools also at this potential.



(NL) WAARSCHUWING

Alle IC's en vele andere halfgeleiders zijn gevoelig voor elektrostatische ontladingen (ESD). Onzorgvuldig behandelen tijdens reparatie kan de levensduur drastisch doen verminderen. Zorg ervoor dat u tijdens reparatie via een polsband met weerstand verbonden bent met apparaat. Houd componenten en hulpmiddelen ook op ditzelfde potentiaal.

(F) ATTENTION

Tous les IC et beaucoup d'autres semiconducteurs sont sensibles aux décharges statiques (ESD). Leur longévité pourrait être considérablement écourtée par le fait qu'aucune précaution n'est prise à leur manipulation.
Lors de réparations, s'assurer de bien être relié au même potentiel que la masse de l'appareil et enfiler le bracelet serti d'une résistance de sécurité.
Veiller à ce que les composants ainsi que les outils que l'on utilise soient également à ce potentiel.

(D) WARNUNG

Alle IC und viele andere Halbleiter sind empfindlich gegen elektrostatische Entladungen (ESD).
Unvorsichtige Behandlung bei der Reparatur kann die Lebensdauer drastisch vermindern. Sorgen Sie dafür, dass Sie im Reparaturfall dem Massepotential des Gerätes verbunden sind.
Halten Sie Bauteile und Hilfsmittel ebenfalls über ein Pulsarmband mit Widerstand mit auf diesem Potential.

(I) AVVERTIMENTO

Tutti IC e parecchi semi-conduttori sono sensibili alle scariche statiche (ESD).
La loro longevità potrebbe essere fortemente ridotta in caso di non osservazione della più grande cautela alla loro manipolazione.
Durante le riparazioni occorre quindi essere collegato allo stesso potenziale che quello della massa dell'apparecchio tramite un braccialetto a resistenza.
Assicurarsi che i componenti e anche gli utensili con quali si lavora siano anche a questo potenziale.

(GB)

Safety regulations require that the set be restored to its original condition and that parts which are identical with those specified be used.

(D)

Bei jeder Reparatur sind die geltenden Sicherheitsvorschriften zu beachten. Der Originalzustand des Geräts darf nicht verändert werden. Für Reparaturen sind Original-Ersatzteile zu verwenden.

(NL)

Veiligheidsbepalingen vereisen, dat het apparaat in zijn oorspronkelijke toestand wordt terug gebracht en dat onderdelen, identiek aan de gespecificeerde worden toegepast.

(I)

Le norme di sicurezza esigono che l'apparecchio venga rimesso nelle condizioni originali e che siano utilizzati pezzi di ricambio identici a quelli specificati.

"Pour votre sécurité, ces documents doivent être utilisés par des spécialistes agréés, seuls habilités à réparer votre appareil en panne."

(F)

Les normes de sécurité exigent que l'appareil soit remis à l'état d'origine et que soient utilisées les pièces de rechange identiques à celles spécifiées.

LASER SAFETY

This unit employs a laser. Only a qualified service person should remove the cover or attempt to service this device, due to possible eye injury.



USE OF CONTROLS OR ADJUSTMENTS OR PERFORMANCE OF PROCEDURE OTHER THAN THOSE SPECIFIED HEREIN MAY RESULT IN HAZARDOUS RADIATION EXPOSURE.

AVOID DIRECT EXPOSURE TO BEAM

WARNING

**The use of optical instruments with this product will increase eye hazard.
Repair handling should take place as much as possible with a disc loaded inside the player**

WARNING LOCATION: INSIDE ON LASER COVERSIELD

CAUTION VISIBLE AND INVISIBLE LASER RADIATION WHEN OPEN AVOID EXPOSURE TO BEAM
ADVARSEL SYNLIG OG USYNLIG LASERSTRÅLING VED ÅBNING UNDGÅ UDSÆTTELSE FOR STRÅLING
ADVARSEL SYNLIG OG USYNLIG LASERSTRÅLING NÅR DEKSEL Å PNES UNNGÅ EKSPONERING FOR STRÅLEN
VARNING SYNLIG OCH OSYNLIG LASERSTRÅLNING NÅR DENNA DEL ÅR ÖPPNAD BETRAKTA EJ STRÅLEN
VARO! AVATT AESSA OLET ALTTIINA NÄKYVÄLLE JA NÄKYMÄTTÖMÄLLE LASER SÄTEILYLLE. ÄLÄ KATSO SÄTEESEEN
VORSICHT SICHTBARE UND UNSICHTBARE LASERSTRAHLUNG WENN ABDECKUNG GEÖFFNET NICHT DEM STRAHL AUSSETZEN
DANGER VISIBLE AND INVISIBLE LASER RADIATION WHEN OPEN AVOID DIRECT EXPOSURE TO BEAM
ATTENTION RAYONNEMENT LASER VISIBLE ET INVISIBLE EN CAS D'OUVERTURE EXPOSITION DANGEREUSE AU FAISCEAU

100301DM

TECHNICAL SPECIFICATIONS

□ Audio section

• CD player section

Playable frequency response : 10Hz – 20kHz

Wow & flutter : Below measurable limits ($\pm 0.001\%$)

Sampling frequency : 44.1kHz

• Audio section

Rated output : 2-channel
65W+65W (4 Ω , 1kHz, THD+N 0.7%)

Dynamic power : 80W+80W (4 Ω , 1kHz, THD+N 10%)

Output terminals : **Speaker : 4-16 Ω (impedance)**
Compatible with headphones/stereo headphones

Input sensitivity/impedance : Analog In : 200mV/22k Ω

Total harmonic distortion (1kHz, 5W, 4 Ω) : Analog In : 0.1%

S/N Ratio (10W, 4 Ω , IHF-A) : Analog In : 90dB

Tone control : SDB : +8dB (100Hz)
Bass : ± 10 dB (100Hz)
Treble : ± 10 dB (10Hz)

Frequency response : Analog In : 10Hz – 40kHz (± 3 dB)

□ Tuner section

Receiving Range : for E2, E1C: FM 87.50MHz – 108.00MHz
for JP: FM 76.00MHz – 90.00MHz
for E2, E1C: AM 522kHz – 1611kHz
for JP: AM 522kHz – 1629kHz

Effective sensitivity : FM 1.2 μ V/75 Ω
AM 20 μ V

FM Channel separation : 42dB (1kHz)

FM S/N ratio : Monaural: 70dB
Stereo: 70dB

FM THD+N (1kHz) : Monaural: 0.4%
Stereo: 0.4%

□ Wireless LAN section

Network type (wireless LAN standard) : Conforming to IEEE 802.11b
Conforming to IEEE 802.11g
Conforming to IEEE 802.11n (Wi-Fi® compliant)*1

Security : WEP 64bit, WEP 128bit
WPA/WPA2-PSK(AES)
WPA/WPA2-PSK(TKIP)

Radio frequency : 2.4GHz

No. of channels : 1 – 13 ch

*1 The Wi-Fi® CERTIFIED Logo and the Wi-Fi CERTIFIED On-Product Logo are registered trademarks of the Wi-Fi Alliance.

□ Bluetooth section

Communications system : Bluetooth Version 2.1 + EDR (Enhanced Data Rate)

Transmission power : Maximum 2.5 mW (Class 2)

Maximum communication r : Approx. 32.8ft/10m in line of sight

Frequency band : 2.4 GHz band

Modulation scheme : FHSS (Frequency-Hopping Spread Spectrum)

Supported profiles : A2DP 1.2 (Advanced Audio Distribution Profile)
AVRCP 1.4 (Audio Video Remote Control Profile)

Corresponding codec : SBC, AAC

Transmission range (A2DP) : 20 Hz - 20,000 Hz

□ Clock/Alarm/Sleep

Clock type : Power line frequency synchronized method (Within ± 60 seconds per month)

Alarm : Once alarm/Everyday alarm : One system each

Sleep : Sleep timer : Max. 90 minutes

□ General

Power supply : (for E2) : AC 230 V, 50 Hz / 60Hz
(for E1C) : AC 220V, 50Hz
(for JP) : AC 100V, 50/60Hz

Power consumption : 55W

Power consumption in standby mode : 0.3W

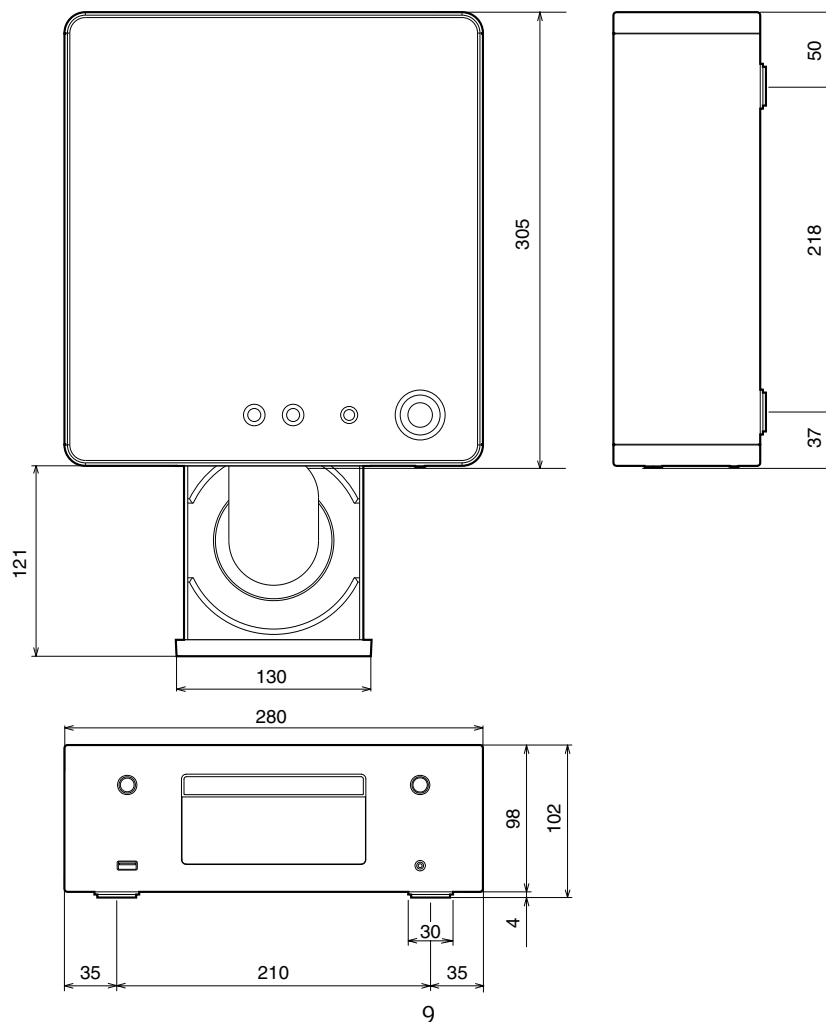
Power consumption in "Network Control"-"On" mode: 3W

For purposes of improvement, specifications and design are subject to change without notice.

DIMENSION

Unit : mm

Weight : 3.2 kg



PRECAUTIONS DURING SERVICE

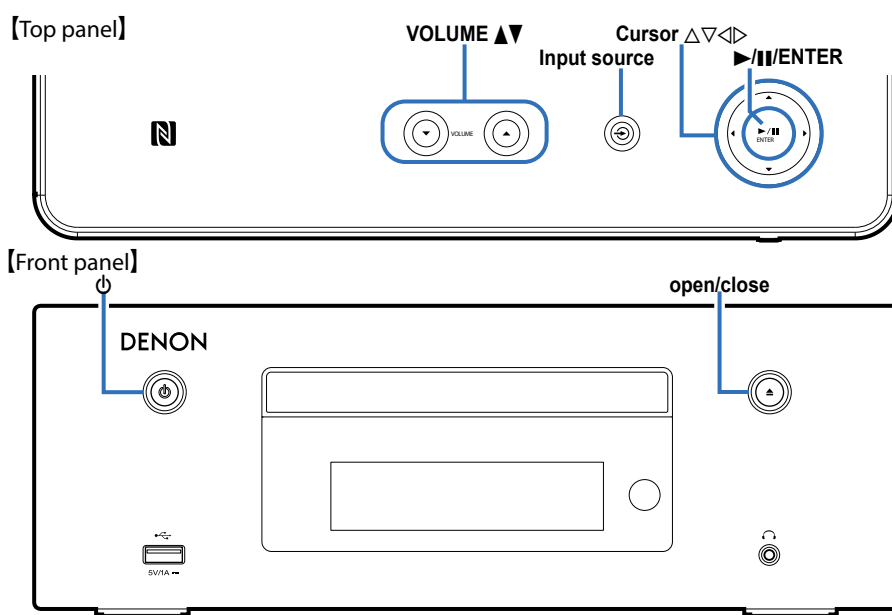
Initializing This Unit

Initialize this unit if you have replaced the microcomputer, one of the parts around the microcomputer, or the digital PCB.

1. In "**STANDBY**" status, press and hold the "**CURSOR** △" and "**INPUT SOURCE**" buttons along with the power operation button to turn on the power. (Factory Initialization Mode)
2. Press the power button "⏻" to turn off the power.
3. In "**STANDBY**" status, press and hold the "**VOLUME** ▲" and "**VOLUME** ▼" buttons along with the power operation button to turn on the power. (User Initialization Mode)
4. Wait for more than 90 seconds after "**Initialized**" is displayed and then turn the power off. ⚠
(During this time, start and initialize the network devices.)

NOTE :

Initializing the device restores settings configured by the user to the factory settings. Take note of your settings beforehand and reconfigure them after initialization.



JIG FOR SERVICING

Measuring Disc :
 CD/TCD-784
 CD-R/TCD-R082W
 CD-RW/TCD-W082W

* See "MEASURING METHOD AND WAVEFORMS".

Procedure after Replacing the WLAN MODULE

When replaced of the WLAN MODULE(CY920-C), confirm contents of the following.

Caution WLAN MODULE and NFC MODULE are supplied in a set so that the BT ADDRESS matches.
 If one module is faulty, replace the entire set.

- (1) When replacing the WLAN MODULE, use the "Part No." corresponding to your region in the table below.

MODULE Name	Remarks	Part No.
CY920 MODULE ASSY	E2 / JP	943189101050D

- (2) Update the firmware using a USB flash drive.

(See 33 page)

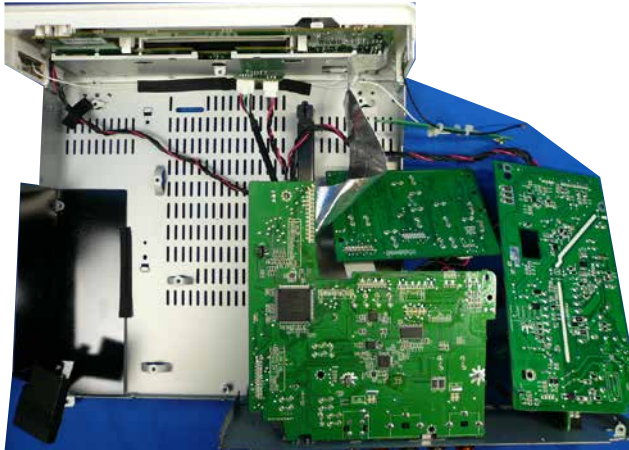
- (3) When replacing the modules, replace the MAC address label on the bottom of the unit with the new one.

Measurement of Board Test Points

You can measure board test points easily by turning over the main board while leaving it screwed to the back panel as shown in the figure below.

Disassembly Procedure (See "DISASSEMBLY" for details on the disassembly procedure)

1. Remove all of the screws from the MAIN PCB, SMPS PCB, CD Mecha, CD Foot, NET PCB, USB PCB and chassis (CD Mecha and CD Foot are for the RCD-N9 only).
2. Remove the SMPS PCB, CD Mecha and CD Foot (CD Mecha and CD Foot are for the RCD-N9 only).
3. Remove the molded parts from the back panel.
4. Raise the MAIN PCB, slide the entire back panel to the rear, and remove everything from the back panel to PCB as a set.

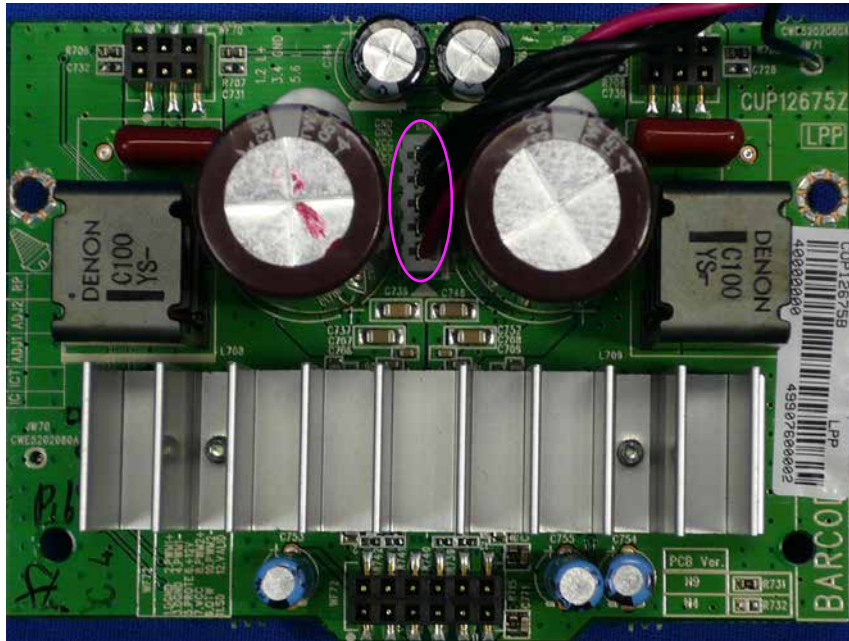


Removing the AMP PCB from the MAIN PCB

Be careful of the following two points when removing and reattaching the AMP PCB to the MAIN PCB.

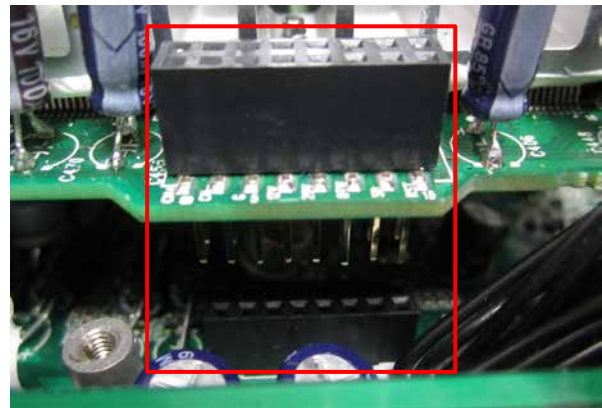
1. Wait for approximately 5 minutes after turning the power off before removing the wire connector that connects the SMPS PCB and AMP PCB.

When connected to the SMPS PCB wire connector, a surge current may occur due to the charge stored in the AMP PCB causing damage to the D-AMP IC70.



2. When attaching the AMP PCB to the MAIN PCB connector, insert the connector pins into the AMP PCB beforehand, and securely connect while checking that the position is correct.

If the MAIN PCB and AMP PCB terminals are connected incorrectly (if the connection pins are misaligned), the PWM Processor IC23, D-AMP IC70 may be damaged by the charge stored in the condenser.



NOTE HANDLING AND REPLACEMENT OF THE LASER PICK-UP

1. Protection of the LD

Short a part of the LD circuit by soldering. After connection to a circuit, remove the short solder.

2. Precautions when handling the laser CD mechanism

- Handle the laser pick-up so that it is not exposed to dust.
- Do not leave the laser pick-up bare. Be sure to cover it.
- If dust adheres on lens of the pick-up, blow it off with a blower brush.
- Do not shock the laser pick-up.
- Do not watch the light of the laser pick-up.

3. Cautions on assembling and adjustment

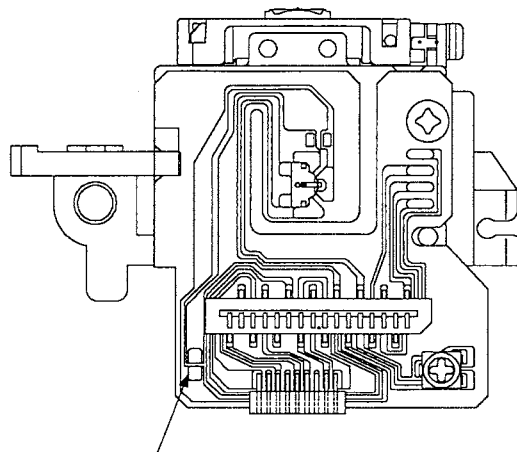
- Be sure that to the bench, jig, head of soldering iron (with ceramic) and measuring instruments are well grounded.
- Workers who handle the laser pick-up must be grounded.
- The finished mechanism (prior to anchoring in the set) should be protected against static electricity and dust.

The mechanism must be stored that damaging outside forces are not received.

- When carrying the finished mechanism, hold it by the chassis body.
- Avoid using and storing in areas where there is corrosive gas (e.g. H₂S, SO₂, NO₂, Cl₂) or other harmful gas in the air, or areas with substances that emit harmful gases (particularly organic silicon, cyanide, formalin or phenol substances). Take particular care to ensure that there are none of the above substances in the set. Otherwise, the motor may stop running.

4. Determining whether the laser pick-up is defective

- Check the Iop(Laser drive current). Check Iop in "SPECIAL Mode". (See [28 page](#))
- If the present Iop (current) value becomes more than 50mA, replace the Traverse unit with a new one.
- No mechanical adjustment is necessary after the replacement.

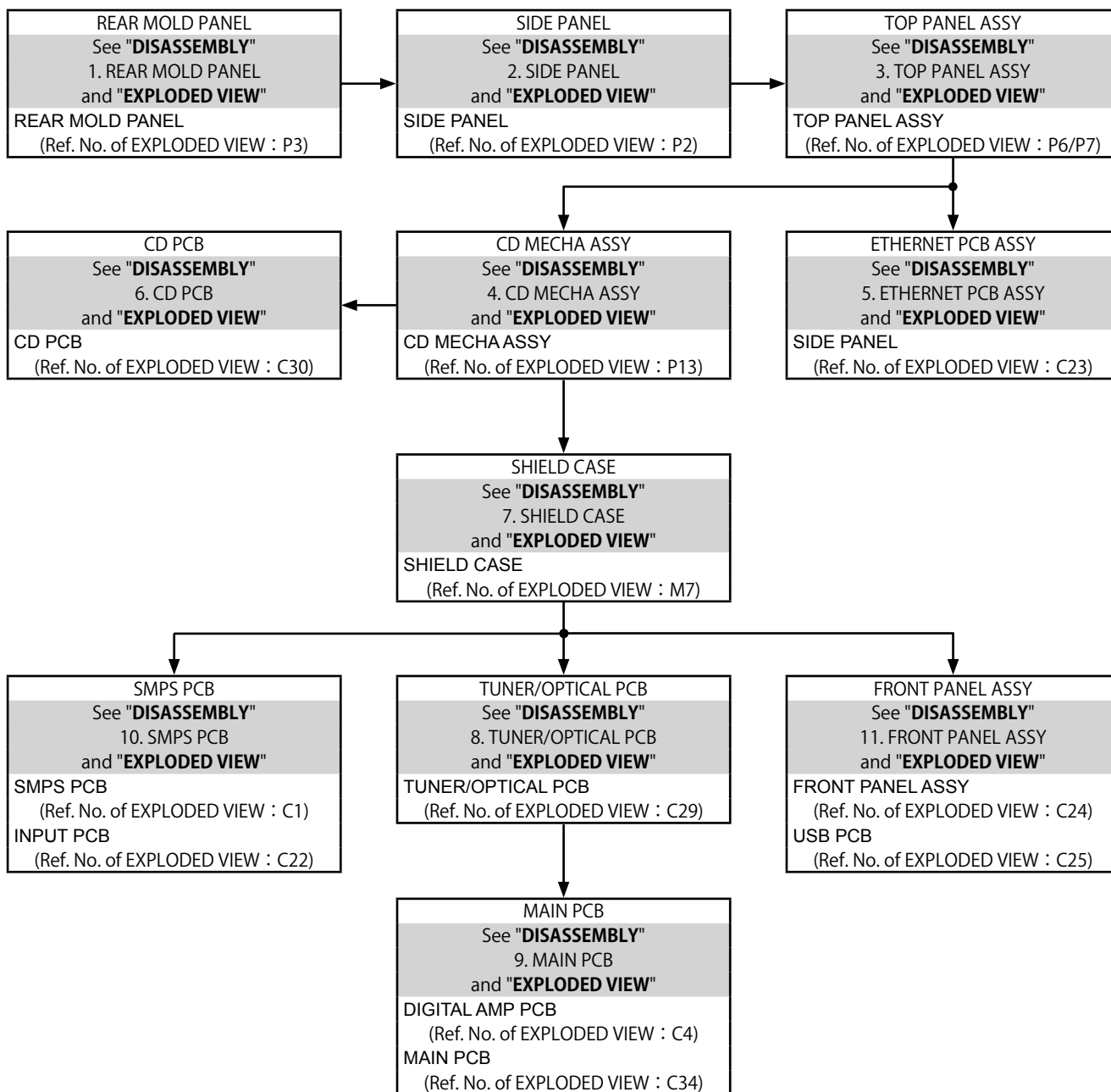


Protective soldering place for laser diode.

(Connect the connectors and remove them before powering the APC circuit.)

DISASSEMBLY

- Remove each part in the order of the arrows below.
- Reassemble removed parts in the reverse order.
- Read "**Precautions During Work**" before reassembling removed parts.
- If wire bundles are removed or moved during adjustment or part replacement, reshape the wires after completing the work. Failure to shape the wires correctly may cause problems such as noise.

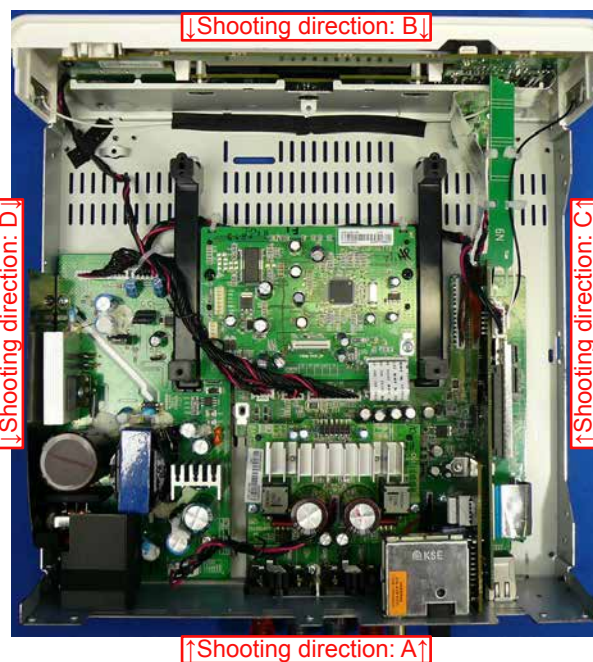
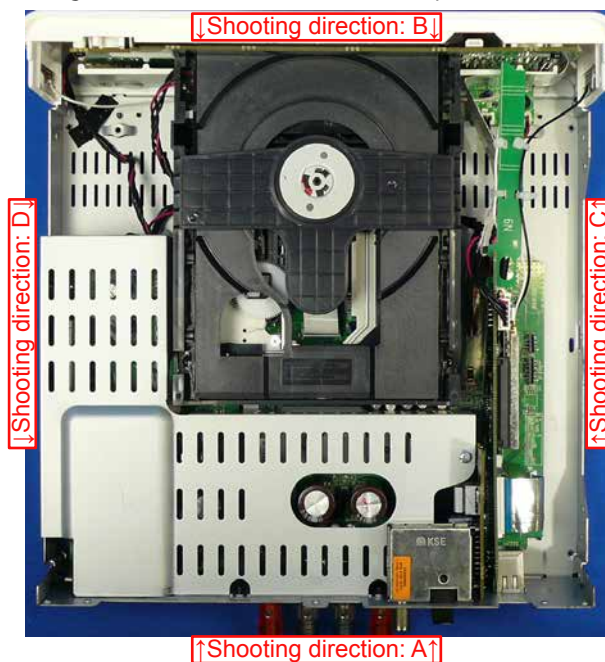


Explanatory Photos for DISASSEMBLY

- The angles from which the photos are taken are shown by "Photo angle : A, B, C, D".
- See the diagram below about the shooting direction of each photograph.
- Photographs with no shooting direction indicated were taken from the top of the unit.
- The photograph is RCD-N9WT model.

The viewpoint of each photograph

(Shooting direction : X) [View from the top]



1. REAR MOLD PANEL

Proceeding : **REAR MOLD PANEL**

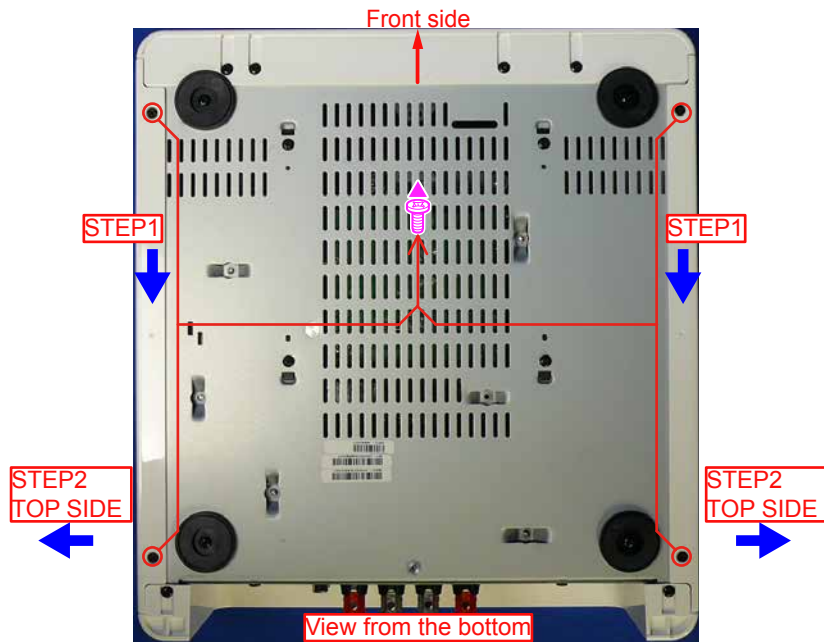
- (1) Remove the screws.



2. SIDE PANEL

Proceeding : REAR MOLD PANEL → SIDE PANEL

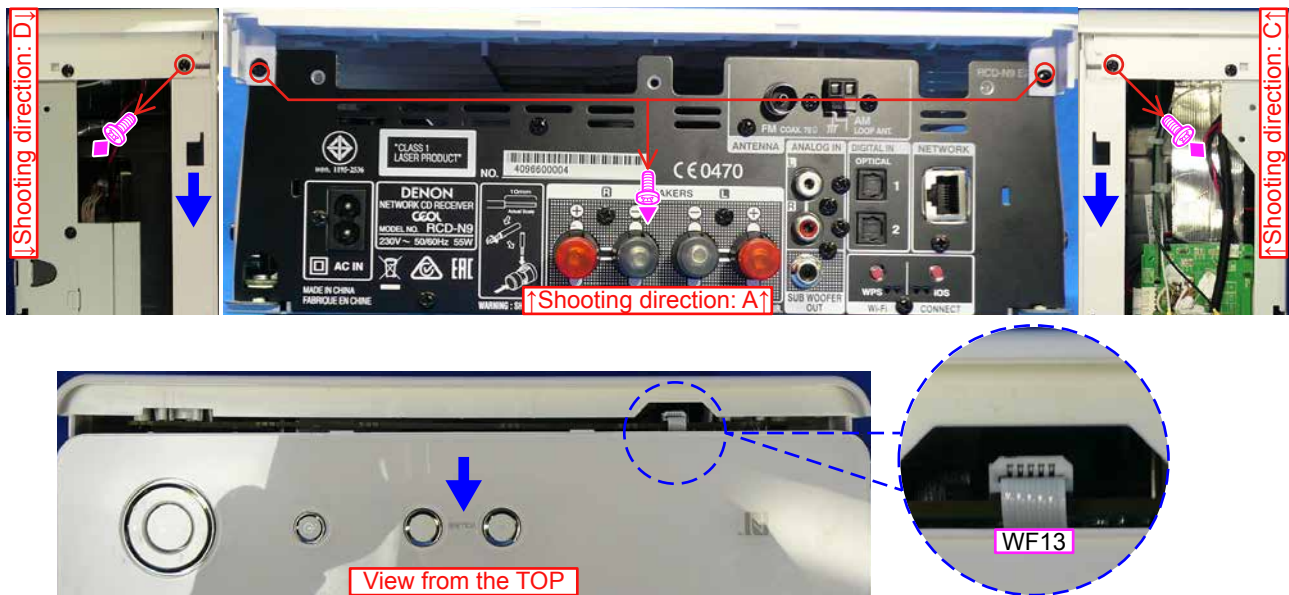
(1) Remove the screws.



3. TOP PANEL ASSY

Proceeding : REAR MOLD PANEL → SIDE PANEL → TOP PANEL ASSY

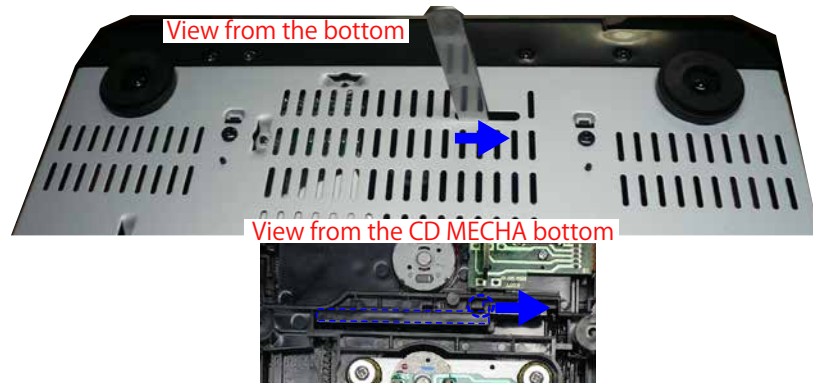
(1) Remove the screws. Remove the FFC.



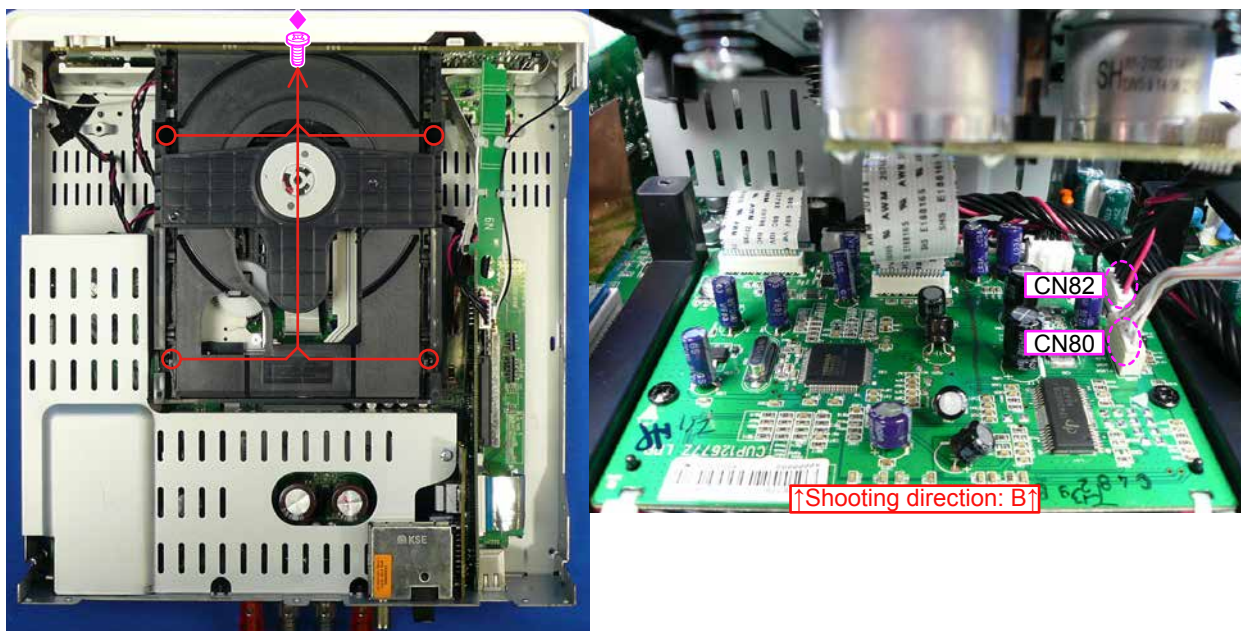
4. CD MECHA ASSY

Proceeding : REAR MOLD PANEL → SIDE PANEL → TOP PANEL ASSY → CD MECHA ASSY

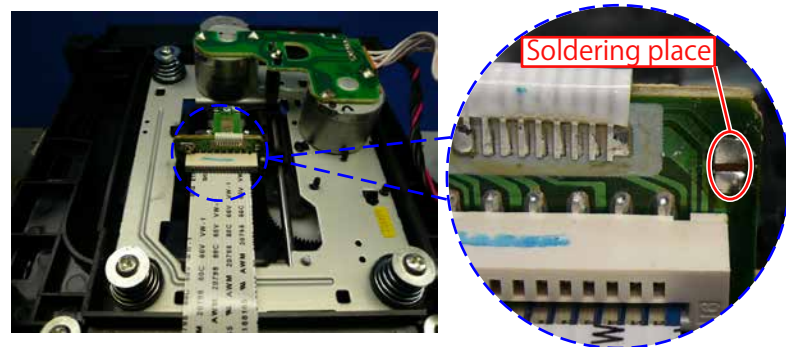
- (1) Tray is opened and CD DOOR is removed.



- (2) Remove the screws. Remove the connector.



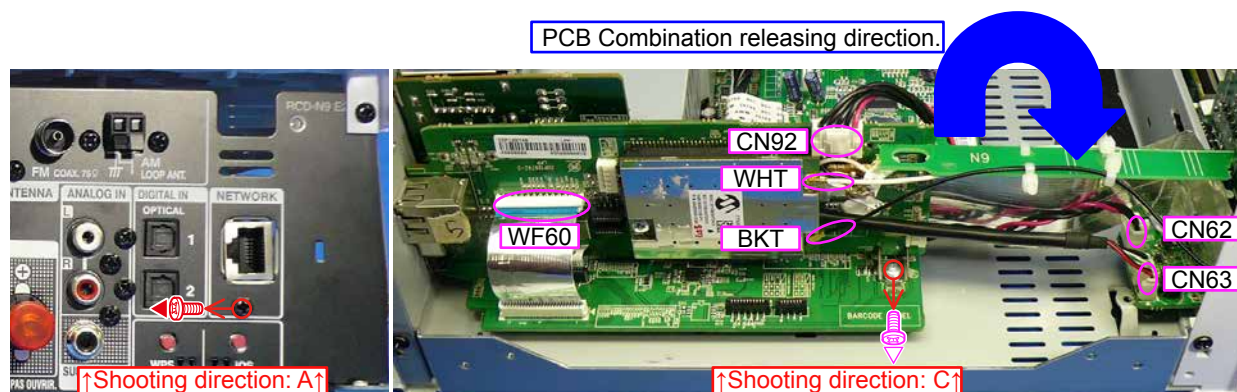
- (3) Laser short-circuit in Pick-up of CD MECHANISM ASS'Y, then disconnect the connector wires and FFC cable. Be sure to wear a grounding band.



5. ETHERNET PCB ASSY

Proceeding : REAR MOLD PANEL → SIDE PANEL → TOP PANEL ASSY → ETHERNET PCB ASSY

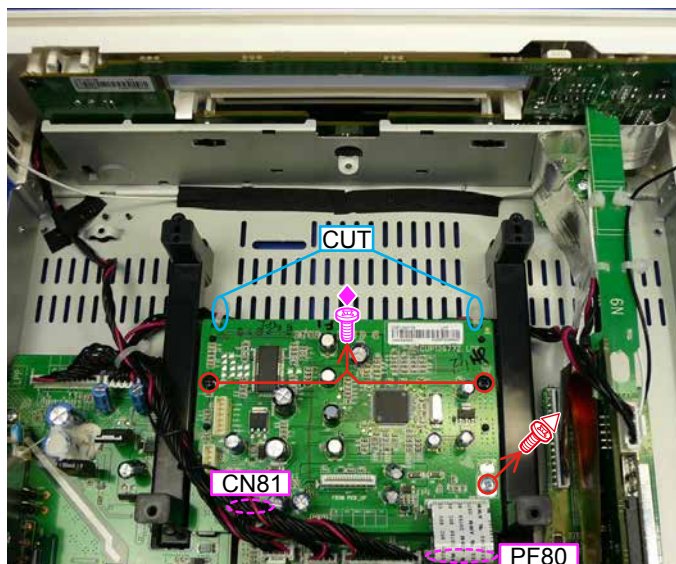
(1) Remove the screws. Remove the connector wire and FFC.



6. CD PCB

Proceeding : REAR MOLD PANEL → SIDE PANEL → TOP PANEL ASSY → CD MECHA ASSY → CD PCB

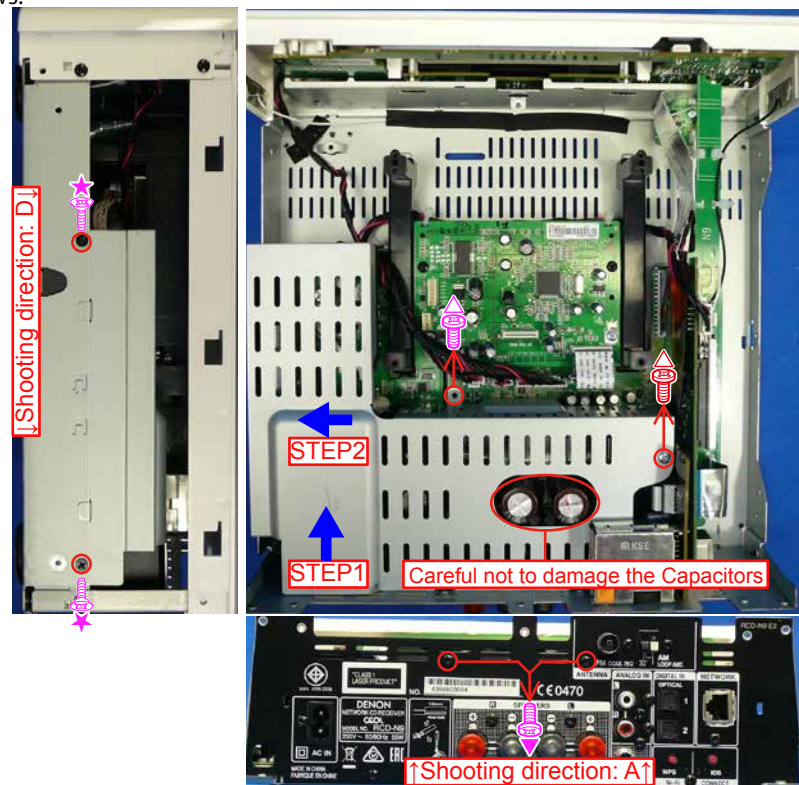
(1) Cut the wire clamp, then remove the connector wires and FFC.



7. SHIELD CASE

Proceeding : REAR MOLD PANEL → SIDE PANEL → TOP PANEL ASSY → CD MECHA ASSY → SHIELD CASE

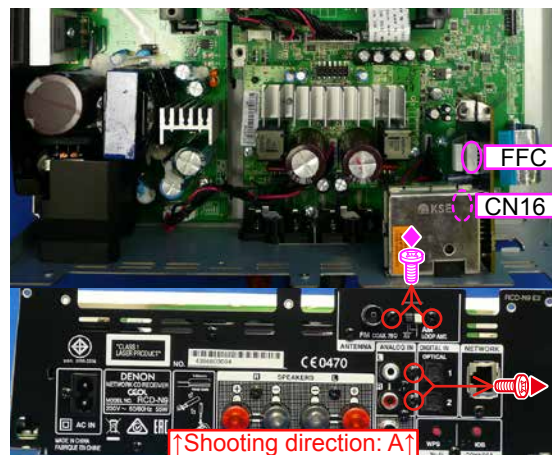
(1) Remove the screws.



8. TUNER/OPTICAL PCB

Proceeding : REAR MOLD PANEL → SIDE PANEL → TOP PANEL ASSY → CD MECHA ASSY → SHIELD CASE
→ TUNER/OPTICAL PCB

(1) Remove the screws. Remove the connector wire and FFC.



9. MAIN PCB

Proceeding : REAR MOLD PANEL → SIDE PANEL → TOP PANEL ASSY → CD MECHA ASSY → SHIELD CASE
→ MAIN PCB

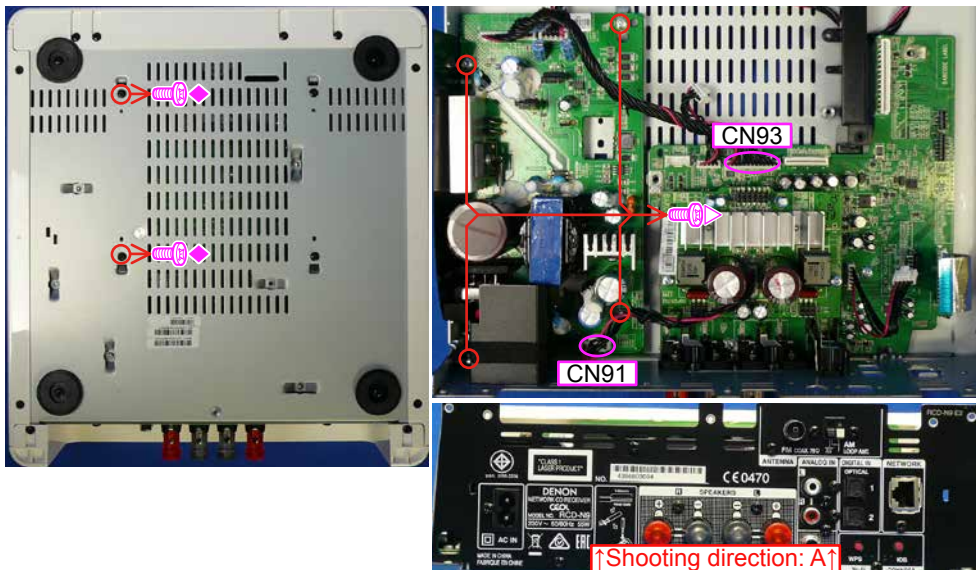
(1) Remove the connector wire. Remove the screws.



10. SMPS PCB

Proceeding : REAR MOLD PANEL → SIDE PANEL → TOP PANEL ASSY → CD MECHA ASSY → SHIELD CASE
→ SMPS PCB

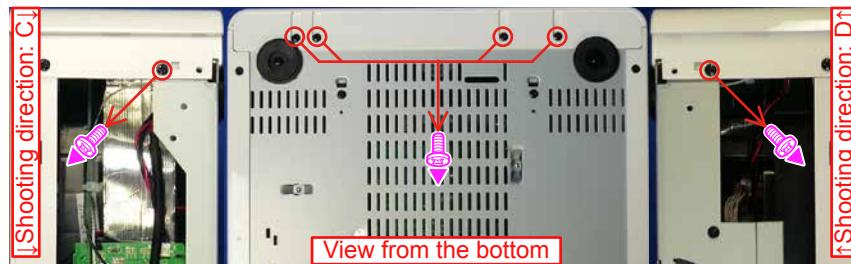
(1) Remove the screws. Remove the SUPPORT, MECA - L. Remove the connector wire.



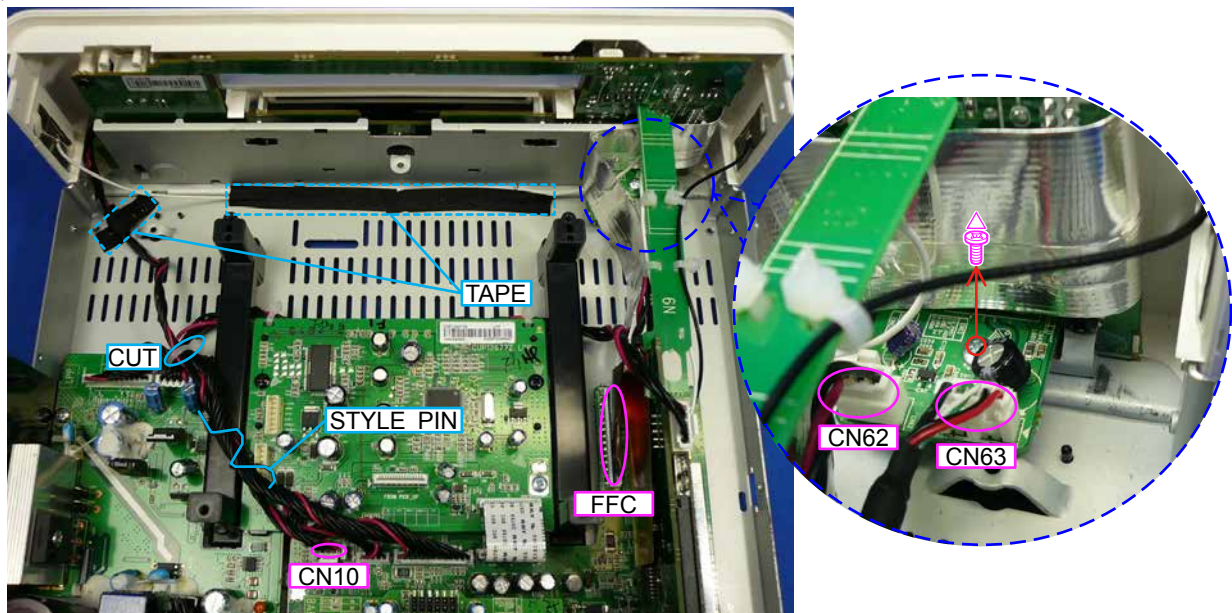
11. FRONT PANEL ASSY

Proceeding : REAR MOLD PANEL → SIDE PANEL → TOP PANEL ASSY → CD MECHA ASSY → SHIELD CASE
→ FRONT PANEL ASSY

(1) Remove the screws.



(2) Remove the connector wire and FFC. Remove the screws.



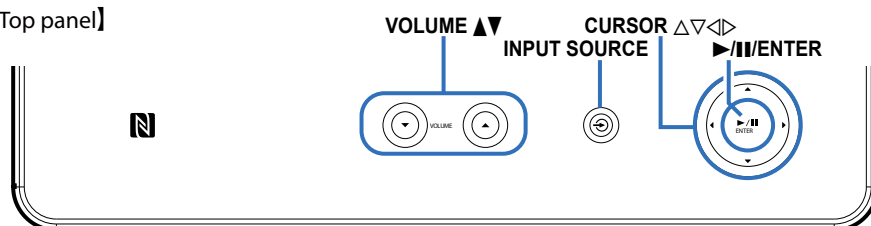
SPECIAL MODE

Special Mode Configuration Buttons

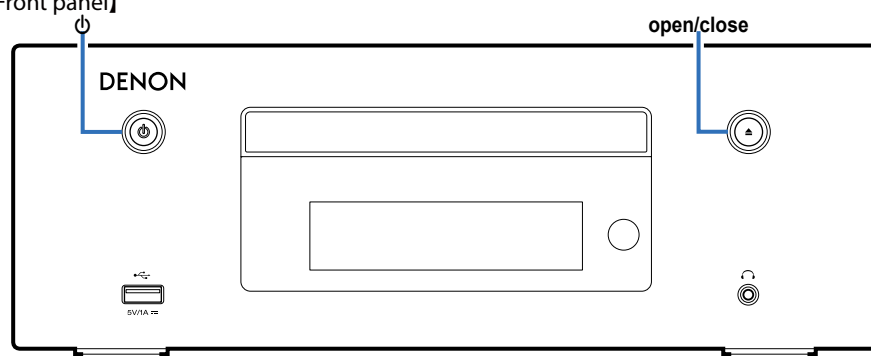
- ※ No. 1 : In "STANDBY" status, press and hold the "A" and "B" buttons along with the power operation button for at least three seconds.
- ※ No. 2 - 6 : In "STANDBY" status, press and hold the "A" and "B" buttons along with the power operation button to turn on the power.
- ※ No. 7, 8 : While holding down the "A" and "B" buttons, insert the AC plug, turn on the power and wait at least three seconds. If the "ON/STANDBY" button is lit, the unit enters this mode.

No.	Mode	Button A	Button B	Contents
1	Version Display Mode	CURSOR Δ	-	The firmware version is indicated in the display. (See 24 page)
2	Factory Initialization Mode	CURSOR Δ	INPUT SOURCE	Restores settings to the default settings. (See 23 page) ※Can't erase the Recently Played list. ※ Be sure to do the "User Initialization" after the "Factory Initialization".
3	User Initialization Mode	VOLUME ▲	VOLUME ▼	Differences with factory initialization are as below. •Does not clear the version information such as rewriting failed log. •Does not clear the history of protection. •Network devices are started and initialized. (See 24 page)
4	CD Test mode	CURSOR ◁	VOLUME ▲	Servo adjustment, Leaser current, ON time (See 26 page)
5	Protection History Display Mode	CURSOR ◁	INPUT SOURCE	Displays the protection occurrence history. (See 29 page)
6	USB UPDATE	CURSOR ▷	INPUT SOURCE	Switches this unit to USB Update mode. (See 33 page)
7	Forced USB All Device Write Mode	CURSOR Δ	▶/II/ENTER	Mode used when this unit cannot be recovered. Forcibly switches this unit to USB update mode. (See 35 page)
8	Heat Run mode	CURSOR Δ	-	Heat Run mode (See 31 page)

【Top panel】



【Front panel】



1. Factory Initialization Mode

Various settings are initialized. See "Initialization Items (Default setting)" for information on the settings that are initialized.

After initialization, move on to normal mode.

Caution

Version information (such as rewriting failed log) Clear.

Clear the history of protection.

"Initial value of laser current" and "The accumulated laser on time" not cleared.

Power failure flag is not cleared.

Can't erase the Recently Played list.

1.1.Operation

In "**STANDBY**" status, press and hold the "**CURSOR Δ** " and "**INPUT SOURCE**" buttons along with the power operation button to turn on the power.

Startup display

Full lighting of the display(2 seconds)



All off(2 seconds)



Lighting of all LEDs on the unit(4 second)



"**Factory Reset**" displayed for 5 seconds.



Initialization Items (Default setting)

	Default
SOURCE	Internet Radio
TUNER(band)	FM
SDB	OFF
Digital In	1
BASS	0 dB
TREBLE	0 dB
BALANCE	CENTER
DIMMER	100%
Sleep	Off
Repeat/Random/Program	Off
VOLUME	5
Favorite list	Clear all
iPod mode	Direct operation mode
Bluetooth device list	Clear all
Setup Menu/Network	All settings
Protection history	NO PROTECT
Version upgrade history	Clear all

2. User Initialization Mode

Various settings are initialized. See "Initialization Items (Default setting)" for information on the settings that are initialized.

After initialization, move on to normal mode.

Caution

The following 3 points are different from the Factory Reset.

- Does not clear the version information such as rewriting failed log.
- Does not clear the history of protection.
- Network devices are started and initialized. ⚠

2.1.Operation

- ⚠ 2. Hold down buttons "**VOLUME ▲**" and "**VOLUME ▼**" at the same time and press the power button to turn on the power.

Startup display

Flashing of the standby indicator LED(White).



"**Initialized**" displayed for 5 seconds



Wait for more than 90 seconds after "**Initialized**" is displayed and then turn the power off. ⚠
(During this time, start and initialize the network devices.)

3. Version Display Mode

Menu items appear in the Add Version. Otherwise, normal operation.

3.1. Starting up

In "**STANDBY**" status, press and hold the "**CURSOR ▲**" button along with the power operation button to turn on the power.

Startup display

"Version" displayed for 5 seconds.



3.2. Display Order

Error information → ① System u-com Version → ② System u-com(boot loader) Version
→ ③ Network u-com(boot loader) Version → ④ Network u-com(IMG) Version
→ ⑤ Bluetooth Mac Address

Select the "**Version**" in the "**Setup**".



↓ "ENTER"

① System u-com Version :



The version of the System u-com.

↓ "Cursor ▽"

② System u-com (Boot Loader) Version :



The version of the boot loader System u-com.

↓ "Cursor ▽"

③ Network u-com(Boot Loader) Version :



The version of the boot loader Network u-com.

↓ "Cursor ▽"

④ Network u-com (IMG) Version :



The version of the image Network u-com.



Network Module CY920 not start upon completion

↓ "Cursor ▽"

⑤ Bluetooth Mac Address :



Display the Bluetooth Mac Address.

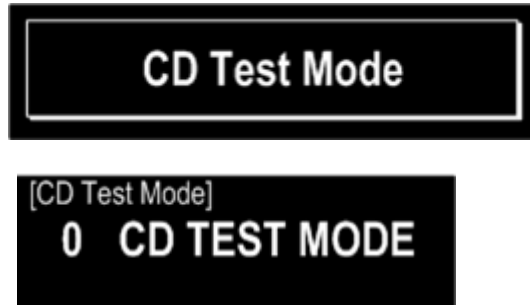
4. CD Test mode

4.1.Operation

In "STANDBY" status, press and hold the "CURSOR ◀" and "VOLUME ▲" buttons along with the power operation button to turn on the power.

Startup display

"CD Test Mode" displayed for 5 seconds.



CD TEST MODE display(Disk loading)

To exit this mode, unplug the power cord.

4.2. Before starting the test

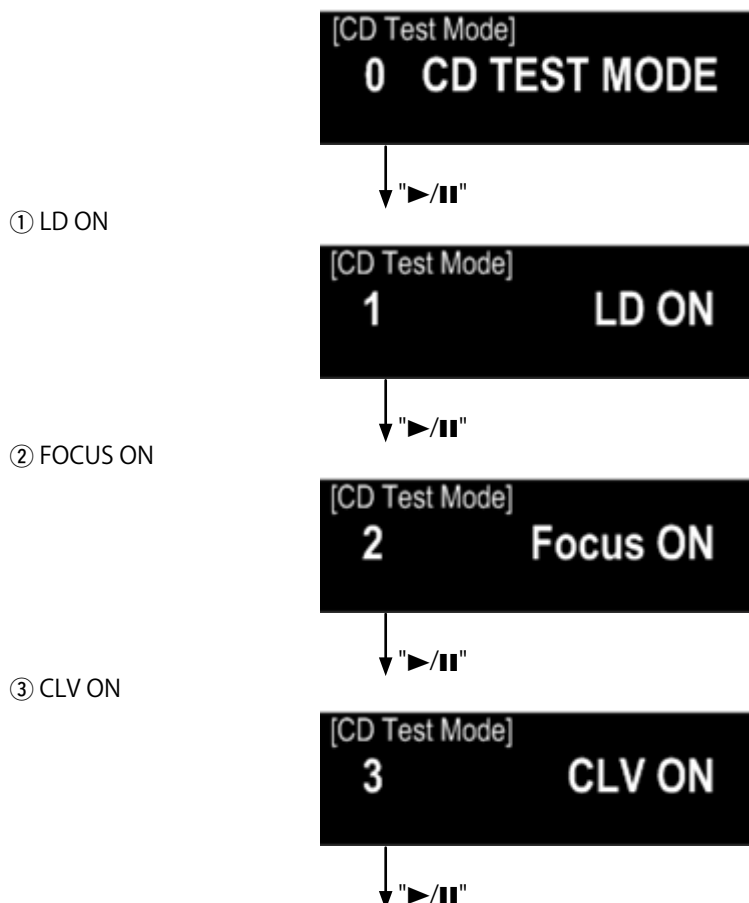
Open the tray and set the disc.

Even if the disc is, the tray must let OPEN → CLOSE.

4.3. Servo check

Press "▶/||" button. Execute the following steps.

* Press and hold the "▶/||" button for at least one second to proceed directly to the step in which the sub code from ⑤ is read. Press the "INPUT" button to return to the "0 CD TEST MODE" display.



④ TRACKING ON

[CD Test Mode]
4 Tracking ON

↓ "▶/||"

⑤ READ SUB CODE (playback sound is output)

The BER (Block Error Rate) that occurred for one second is displayed.

[CD Test Mode]
5 IN ERR: xxxxx
xTr mm:ss

↓ "Cursor <" ↑ "Cursor >"

[CD Test Mode]
5 MID ERR: xxxxx
xTr mm:ss

↓ "Cursor <" ↑ "Cursor >"

[CD Test Mode]
5 OUT ERR: xxxxx
xTr mm:ss

Inner (IN), Ataru Amare (MID), outer (OUT) to play go to three places, make the error count.

4.4. Pickup movement

In the stop mode, pickup moves in FWD (outwards) or REV (inwards) direction when "Cursor >" or "Cursor <" button pressed.

Pickup movement stops when button released. (Pickup moves while button is pressed)

When "Cursor <" button pressed, move to stop operation after detection that inner switch has turned on.

[CD Test Mode]
0 CD TEST MODE

4.4. All servo on and Auto Adjustment

When "**Cursor** Δ " button is pressed, all servos turn on, auto adjustment is performed and switch to playback operation.
(Playback sound output)

Stop (stop to the playback state after auto adjustment)

When "**SOURCE**" button is pressed, play operation and servo stop. The following will be displayed.
After stopping, conduct reading of auto adjust values.



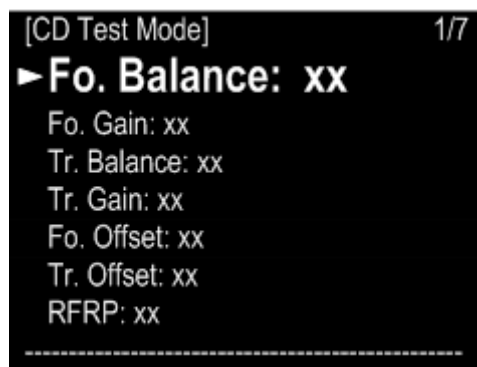
Adjustment value display (After All Servo on and Auto Adjustment)

Press the "**SOURCE**" button, after All servo on and Auto Adjustment.

When "**Cursor** Δ/∇ " button is pressed, the adjustment values are displayed in the following order.

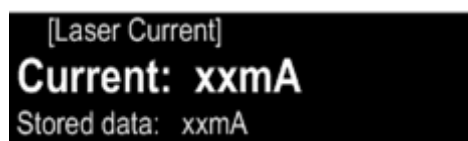
- ① FOCUS BALANCE
- ② FOCUS GAIN
- ③ TRACKING BALANCE
- ④ TRACKING GAIN
- ⑤ FOCUS OFFSET
- ⑥ TRACKING OFFSET
- ⑦ RFRP

(Caution) If you have not completed the adjustment, the value is not correct.



4.5. Laser current display

When "**VOLUME** $\blacktriangle$ " button is pressed for over 1 second while the Unit is in the CD TEST MODE, the laser turns on and the laser current is measured.



The voltage when the laser is on and off is measured (converted to A/D) and the current is calculated from this. The decimal point is omitted.

The current value is updated every 3 seconds.

Press the "**SOURCE**" button, CD TEST MODE display reappears.

Stored data is not cleared, even when the Unit is reset(Factory/User).

 The initial value of the factory, is "**50mA**" or less.

Overwriting the stored data

When the "**►/III**" button is pressed for over 5 seconds while the laser current is displayed, the current value is stored in the EEPROM (overwriting the stored data).



Once rewriting is completed, the display in "Laser current display" reappears. Rewriting is performed upon shipment from the factory and when the mechanism is replaced.

4.6. Accumulated laser on time display

When the "**Volume ▼**" button is pressed while this Unit is in the "CD TEST MODE" displayed, the accumulated laser on time is displayed.



The laser drive times are added and the result is displayed.

The time is counted in 10-minute blocks and the count values are displayed in hourly units. Values for up to 10922 hours are displayed.

Press the "**SOURCE**" button, CD TEST MODE display reappears.

The count values are not cleared, even when the set is reset (Factory/User).

Count value is reset

When the "▶/||" button is pressed for over 5 seconds while the accumulated laser on time is displayed, the count value is reset.



Count value is reset upon shipment from the factory and when the mechanism is replaced.

5. Protection History Display Mode

5.1.Operation

In "STANDBY" status, press and hold the "**CURSOR ◀**" and "**INPUT SOURCE**" buttons along with the power operation button to turn on the power.

Startup display

"Detect Protection" displayed for 5 seconds.

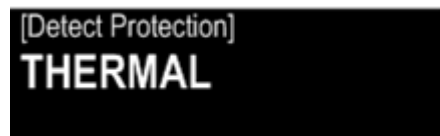


To exit this mode, unplug the power cord.

(a) No detection history



(b) Thermal protection



Abnormal increases in D-AMP temperature are detected (TAS5142).

(c) Speaker short protection



Potential difference across the terminal detects that the speaker was more than $DC \pm 3V$.

(d) Over current



Over-current detection digital amplifier(TAS5142)

(e) DC protect1



Short of fail(+29V[D-AMP power])

(e) DC protect1



Short of fail(+12V, -12V, +5V).

Protection history is reset.

When the "**Cursor**△" button is pressed for over 5 seconds while the protection history is displayed, the count value is reset.



"**No Protection**" is displayed after the history is cleared.



After the reset is complete, the display "No Protection".

6. CD heat run mode

Heat run mode Startup display

"Heatrun Mode" displayed for 5 seconds.



Press the "**Cursor**

After loading the disc, press "**▶/II**" button.

While heat run, the operation of each button is not valid. If an error occurs, display the error and stop operation at that point. Refer to Heat run error code table.

To exit this mode, unplug the power cord.

6.1. Normal heat run mode

Playing from the first track to last track on disc. After disc playback has finished, then tray open and close. And playback again.

The heat run repetition no. is incremented (increased by 1) when the tray is opened.

Repeat this operation.

[H.R. Normal] displayed.

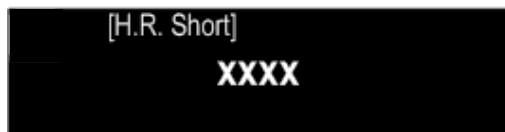


Select "**H.R.Normal**", and press "**▶/II**" button.

Press the "**Cursor**

6.2. Heat run Short mode

Playing last track on disc. After disc playback has finished, then tray open and close. And playback again. The heat run repetition no. is incremented (increased by 1) when the tray is opened. Repeat this operation.
[H.R. Short] displayed.



Select "H.R.Short", and press "▶/||" button.
Press the "Cursor Δ" button to display the count.

6.3. Heat run chacking mode

TOC read the CD, the first song disk search, open / closed later, and again read TOC. The heat run repetition no. is incremented (increased by 1) when the tray is opened. Repeat this operation.
[H.R. Chacking] displayed.



Select "H.R.Chacking", and press "▶/||" button.
Press the "Cursor Δ" button to display the count.

6.4. Error display

Press the "Cursor Δ/▽" to display the error information.



Heat run error code table

Error Code	Details of Error code
E1-00	Disc cannot be detected
E1-01	Tracking offset adjustment not possible
E1-02	Focus offset adjustment not possible
E2-00	Focus servo dropped during playback.
E2-01	Focus servo dropped during searching.
E2-03	Focus servo dropped during TOC reading.
E2-05	Focus servo dropped during manual search.
E2-10	Subcode can no longer be read during playback
E2-11	Subcode can no longer be read during searching
E2-12	Subcode can no longer be read during TOC reading
E2-14	Subcode cannot be read during pause
E2-15	Subcode cannot be read during manual search
E3-00	TOC could not be read within specified time
E3-01	PVD/SVD analysis could not be completed within specified time
E4-04	Search time out (The search was not completed within the stipulated time)
E4-05	Decoder bus error (Error in communications with CD decoder)
E5-00	Inner switch not on
E6-00	Inner switch not off
E8-00	Tray is not opened by the specified time.
E8-01	Tray is not closed by the specified time.
E9-00	CD Microprocessor error
E9-01	Other error

PROCEDURE AFTER REPLACING THE MICROPROCESSOR, ETC.

The procedure after replacing the u-COM (microprocessor), flash ROM, etc. is as follows.

PCB Name	Ref. No.	Description	Procedure after Replacement	Remark
MAIN	IC28	R5F56108VNFP	B	
EXPLODED 	C36 	CY920 MODULE ASSY	B	SOFTWARE: SYSTEM Be sure to replace the NFC module at the same time.

Procedure after Replacement

A : The software has been written. The software is not written at the time of replacement.

B : The software has been written. The software may need to be rewritten by version updates. Check the version.

C : The software has not been written. The software needs to be written after replacement.

See "**Firmware Update Procedure**" for information on writing the software.

D : The software has been written. Be sure to rewrite with the latest software for your service region.

See "**Firmware Update Procedure**" for information on writing the software.

FIRMWARE UPDATE PROCEDURE

1. Updating by USB

The latest firmware can be downloaded to a USB memory for updates.

1.1. Connecting to the USB Memory

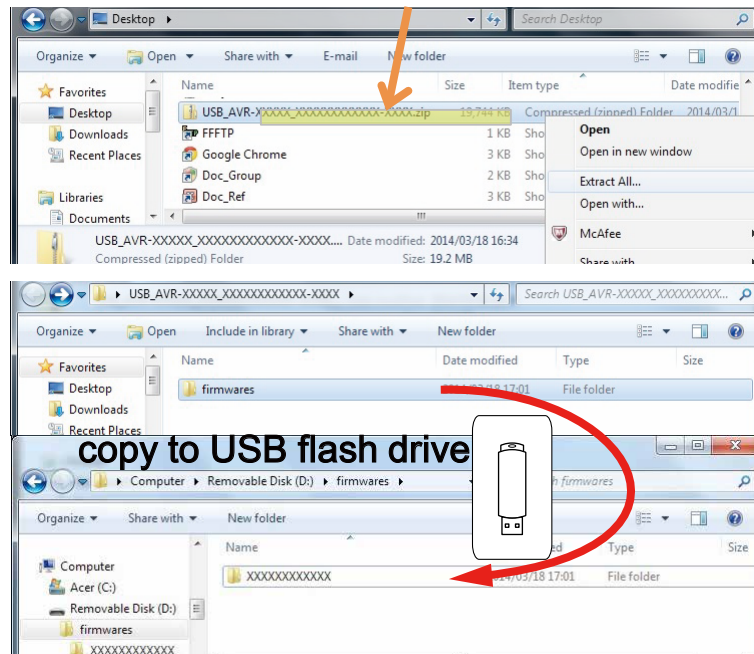
(1) Preparation

- USB format : Prepare a USB memory formatted in FAT16 or FAT32.
- Do not run the USB memory through a hub.
- Do not connect a computer to the USB port of this unit using a USB cable.
- Do not use an extension cable when connecting the USB unit.

1.2. Unzip Download File

Unzip the downloaded file on your computer.

RCD-XXXXXXX	USB_RCD-XXXXXXX_XXXXXXXXXXXX-XXXX.zip
-------------	---------------------------------------



You can find "**firmwares**" folder after unzipped.

Copy that folder to USB flash drive.

You have to put "**firmwares**" folder on root directly on USB flash drive(memory).

1.3. File structure on USB Memory

Copy the update files to the USB memory with the following structure:

USB memory root

Model Name	Model Area	Product ID
RCD-N9	Europe (E2)	000200140200
	China (E1C)	000200140500
	Japan (JP)	000200140400

+ firmwares

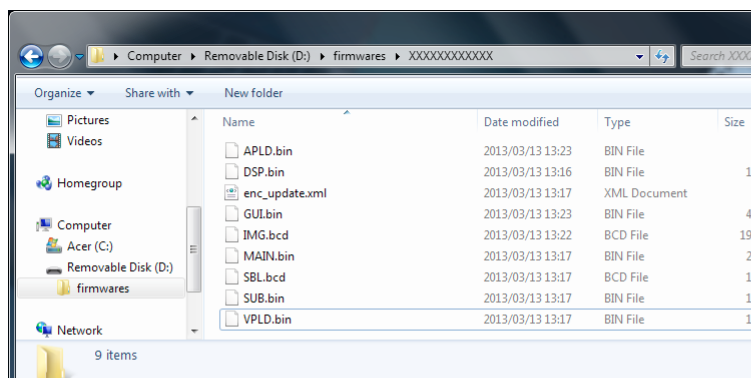
+ 000200XXXXXX

+ enc_update.xml

+ IMG.bcd

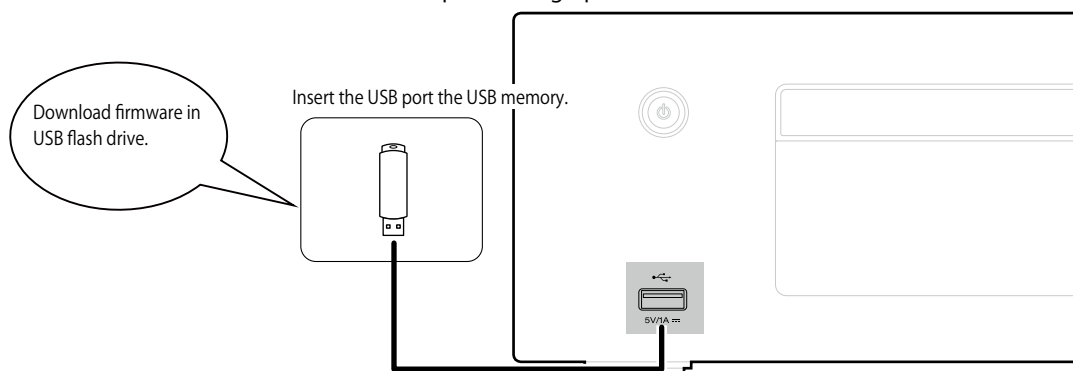
+ SBL.bcd

+ SYS.bin



1.4. Insert the USB memory in the USB port.

NOTE : Remove the LAN cable from this unit when performing updates.



1.5. Start the update.

In "STANDBY" status, press and hold the "CURSOR ▷" and "INPUT SOURCE" buttons along with the power operation button to turn on the power.

1.6. Display during USB update

The following message appears on the display:

Display



1.7. Press the "ENTER" key on the remote control unit or this unit.

Then start Firmware Update.

Display



1.4. The firmware update finishes.

Update after restart.

--- Precautions for Updates ---

- Wait for 60 seconds before turning the power back on(AC ON → OFF → ON).
 - Never remove the USB memory before the update is finished.
 - Never turn off the power before an update is completed.
 - It takes around 30 minutes to complete the update.
- Once an update is started, normal operations cannot be performed until it is completed.
Also, the settings of the unit may be initialized.
Take note of your settings beforehand and reconfigure them after the update.

2. Forced USB All Device Write Mode

2.1. Actions

Mode used when this unit cannot be recovered.
Forcibly switches this unit to USB update mode.

2.2. Operations

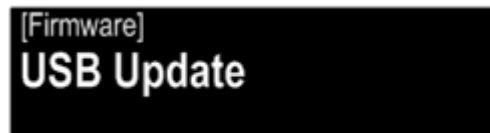
While holding down the "CURSOR △" and "▶/III/ENTER" buttons, insert the AC plug, turn on the power and wait at least three seconds.

NOTE : When you start this operation, you should waiting for until the charge of internal is completely discharged about 2 minutes.

2.3. Forced USB All Device Write Mode

The following message appears on the display:

Display



2.4. The firmware update finishes.

The update after the restart, all devices will be updated.

3. Error Code Table of FIRMWARE UPDATE

- Preparation operation rewritten, Update error code checking.

ErrCode (Hex)	The occurred event	OLED Message
01	Login failed (DPMS Access Login Incorrect notification)	Login failed 01
02	Login failed (DPMS Access Server Busy information)	Server is busy 02
03	Login failed (DPMS Access link failure information)	Connection fail 03
04	Firmware Individual information acquisition failure	Connection fail 04
05	Firmware Individual information acquisition TimeOut	Connection fail 05
06	Firmware all information acquisition failure	Connection fail 06
07	Firmware all information acquisition TimeOut	Connection fail 07
08	Error notification received at the time of Firmware Info request	Connection fail 08
09	Firmware Info response acquisition Time Out	Connection fail 09
0A	Firmware Down Load failed ((NG) information recieved)	Download fail 0A
0B	Firmware Down Load failed ((ServerBusy) information recieved)	Download fail 0B
0C	Firmware Down Load failed ((Connection failed) information recieved)	Download fail 0C
0D	Received Package Version is wrong	Connection fail 0D
20	Transition to the Boot Loader Mode (Failure to acquire the IP Address (AutoIP))	Connection fail 20
21	Transition to the Boot Loader Mode (Failure to acquire the IP Address (TimeOut))	Connection fail 21
22	Transition to the Boot Loader Mode (DDPMS Access Login Incorrect notification)	Login failed 22 / Connection fail 22
23	Transition to the Boot Loader Mode (DPMS Access Server busy infomation)	Server is busy 23
24	Transition to the Boot Loader Mode (DPMS Access Connection failed information recieved)	Connection fail 24
25	Transition fails to Boot Loader Mode	Connection fail 25
27	Write failure to the Boot Loader Mode to transition after the EEPROM	Connection fail 27

- Firm error codes at the main microprocessor rewritten.

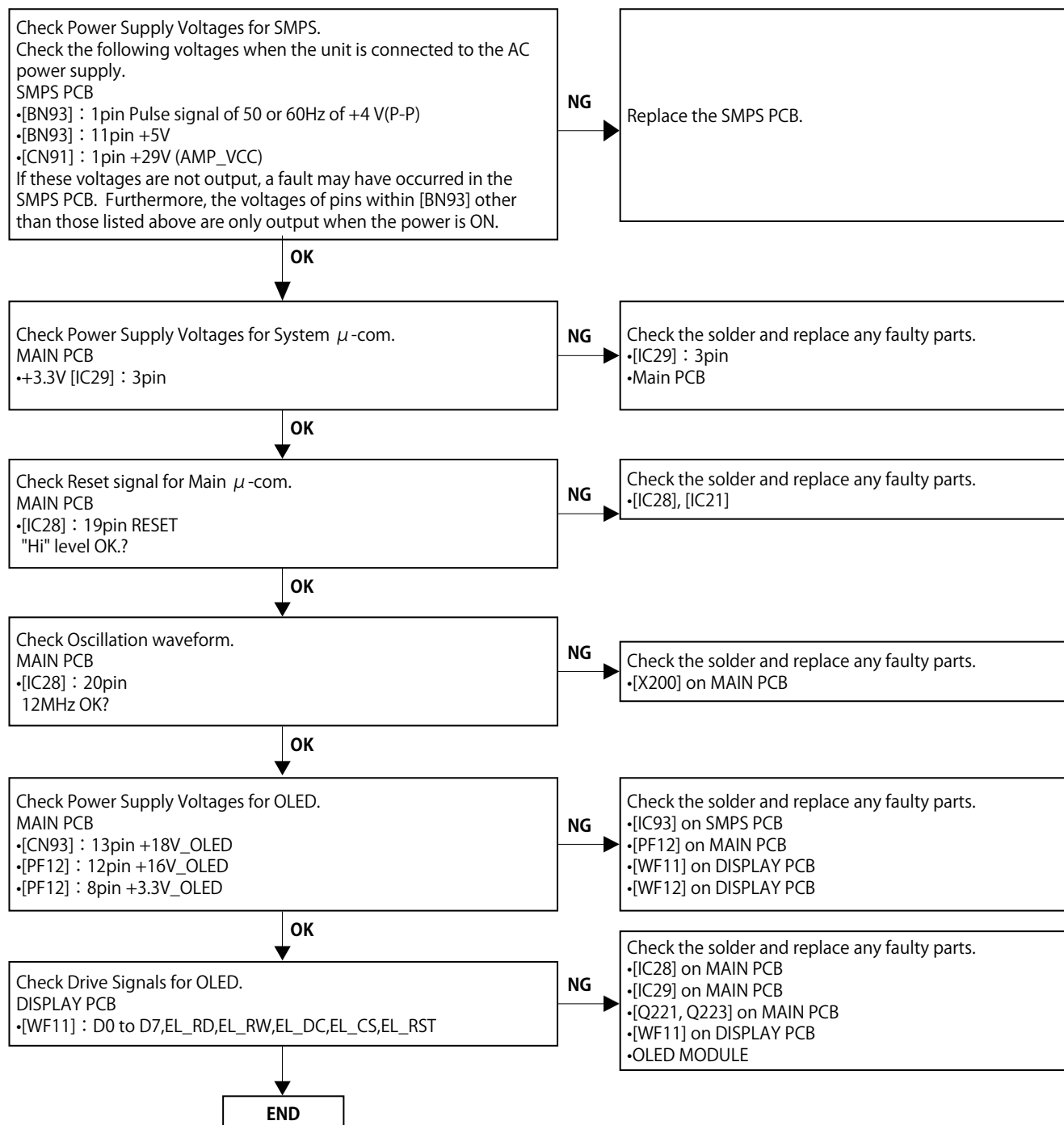
ErrCode (Hex)	The occurred event	OLED Message
10	Firm Info response acquisition Time Out (Main rewrite Firmware recived failure (Time Out))	Updating fail 10
11	Firm Info response acquisition recieved error (Main rewrite Firmware recived failure (Error))	Updating fail 11
12	Firm Info response acquisition recieved error (Main rewrite Firmware recived data incorrect (Check Sum Error))	Updating fail 12
13	Rewrite failure (Block Erase failed before Main rewriting)	Erase fail 13
14	Rewrite failure (Block Write failed before Main rewriting)	Updating fail 14
15	Rewrite failure (Verify incorrect after Main rewriting)	Updating fail 15
22	Transition to the Boot Loader Mode (DPMS Access Login Incorrect notification)	Login failed 22 / Connection fail 22
23	Transition to the Boot Loader Mode (DPMS Access Server busy infomation)	Server is busy 23
24	Transition to the Boot Loader Mode (DPMS Access Connection failed infomation)	Connection fail 24
39	Login failure (DPMS Access access Time Out)	Connection fail 39
3A	Down Load failure (Download error (NG)information recieved)	Download fail 3A
3B	Down Load failure (Download error (Server Busy) information recieved)	Server is busy 3B
3C	Down Load failure (Download error (connection failed)information recieved)	Connection fail 3C
3D	Transition to the Boot Loader Mode (Failure to acquire the IP Address (Auto IP))	Connection fail 3D
3E	Transition to the Boot Loader Mode (Failure to acquire the IP Address (Time Out))	Connection fail 3E
3F	Fail in moving into Boot Loader Mode.	Connection fail 3F

- CX920 error codes when firmware rewriting.

ErrCode (Hex)	The occurred event	OLED Message
A0	Failure to acquire the IP Address (AutoIP)	Connection fail A0
A1	Failure to acquire the IP Address (TimeOut)	Connection fail A1
A2	Login failed (DPMS Access Login Incorrect notification)	Login failed A2
A3	Login failed (DPMS Access Server busy infomation)	Server is busy A3
A4	Login failed (DPMS Access Connection failed infomation)	Connection fail A4
A6	Error notification received at the time of Firmware Info request	Updating fail A6
A7	Firmware Info response acquisition Time Out	Updating fail A7
AE	Down Load failure (Download error (NG)information recieved)	Download fail AE
AF	Down Load failure (Download error (Server Busy) information recieved)	Download fail AF
B0	Down Load failure (Download error (connection failed)information recieved)	Download fail B0
B1	Down Load failure (Error at the time of Download (TimeOut))	Download fail B1
B2	Firmware Down Load failed	Updating fail B2
B4	Transition fails to Boot Loader Mode	Updating fail B4
B5	Transition fails to Application Mode	Updating fail B5

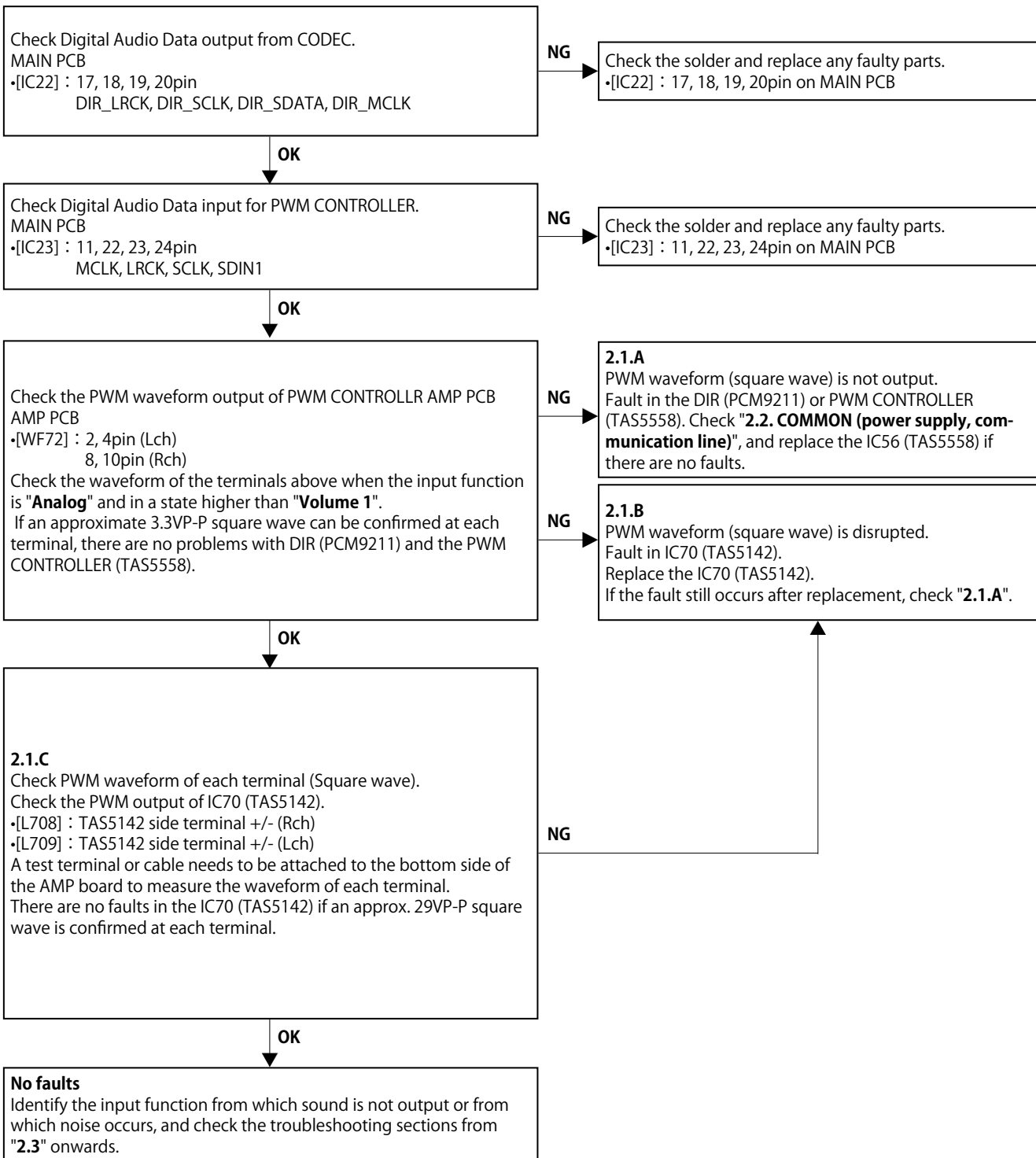
TROUBLE SHOOTING

1. OLED dosen't light

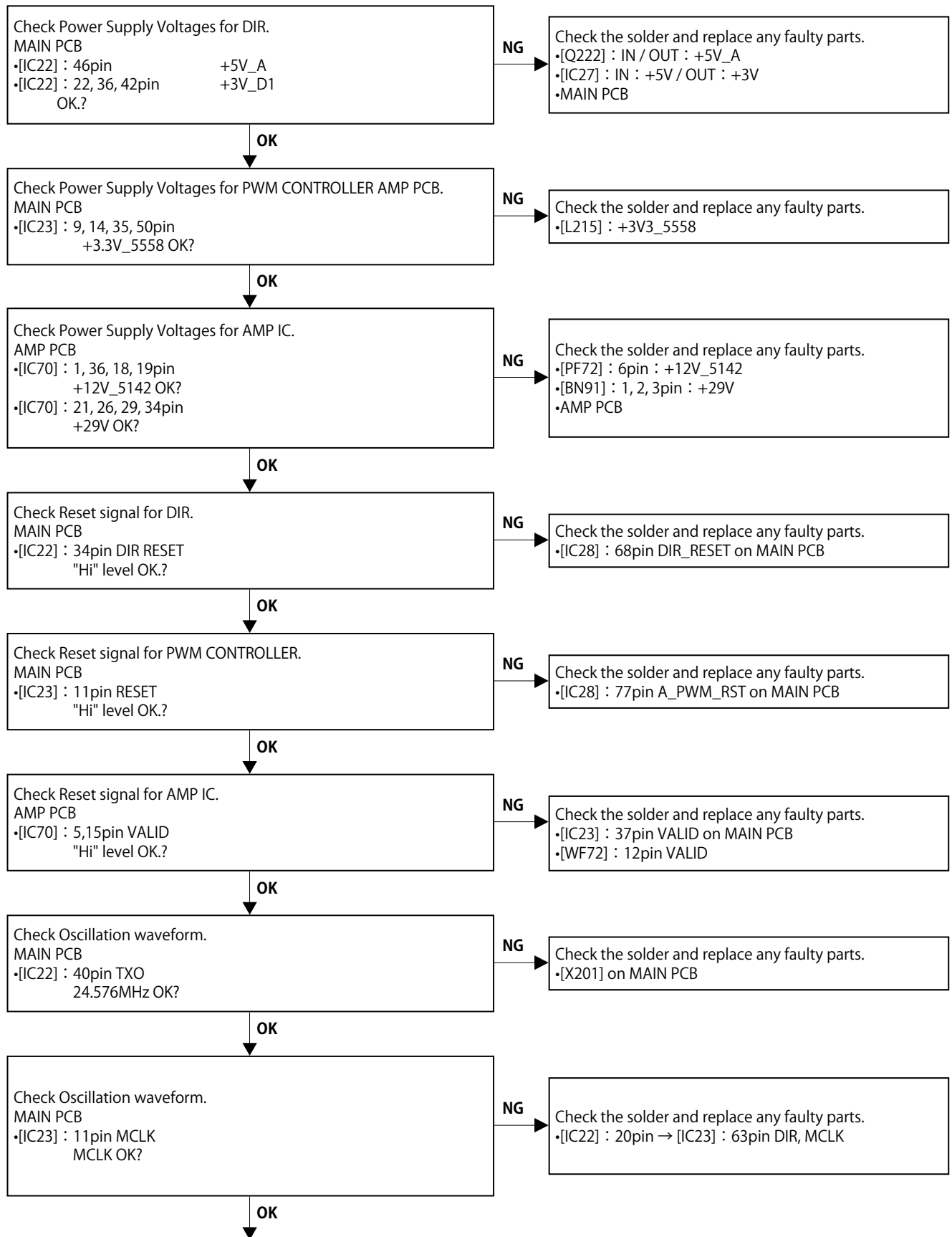


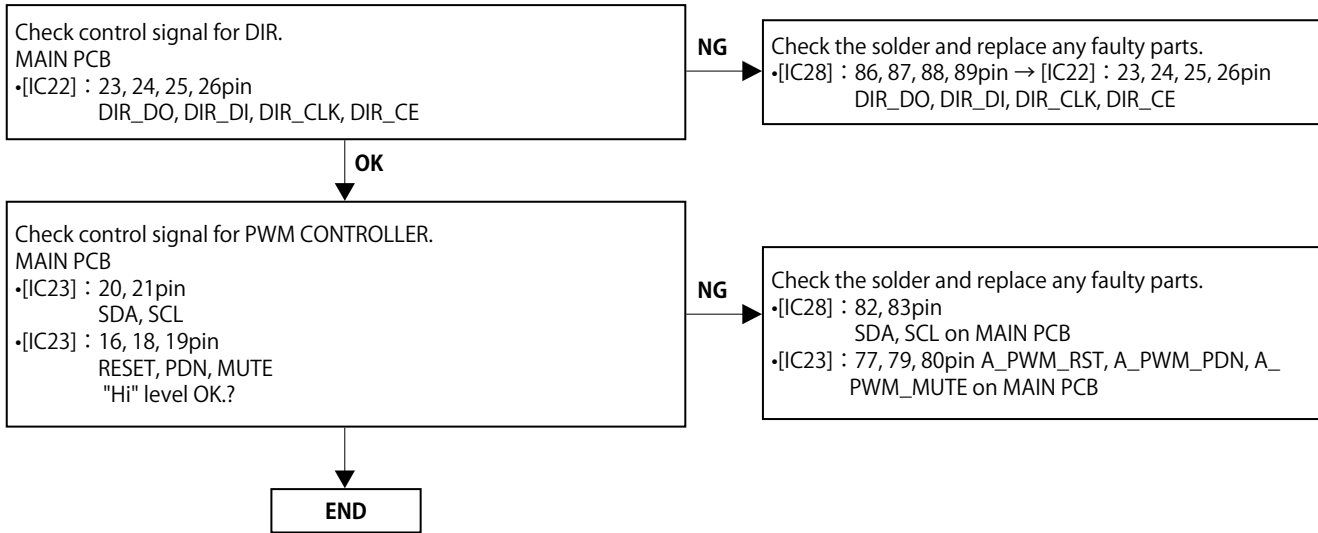
2. No Sound, Noise generated

2.1. COMMON(signal)

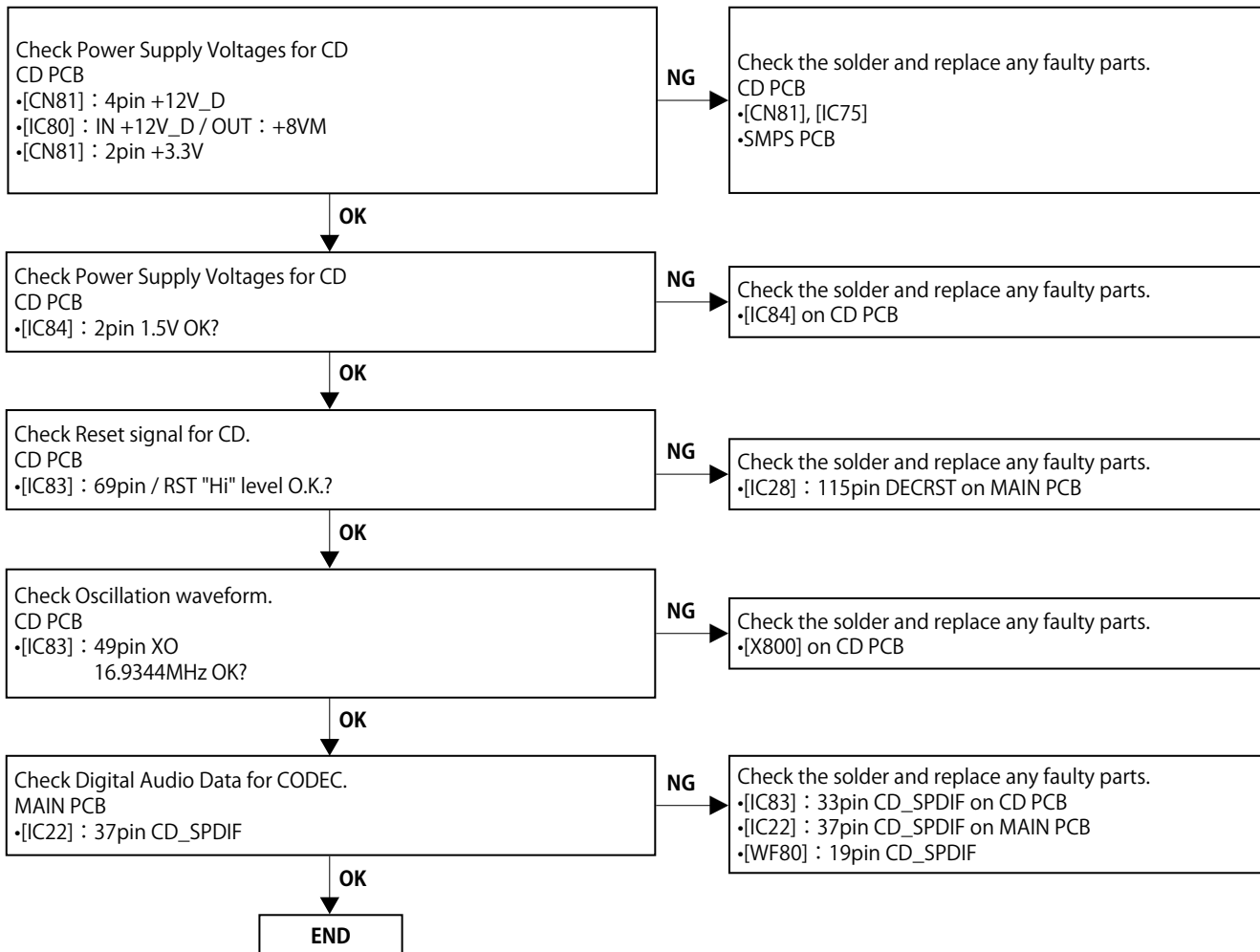


2.2. COMMON(POWER Control signal)

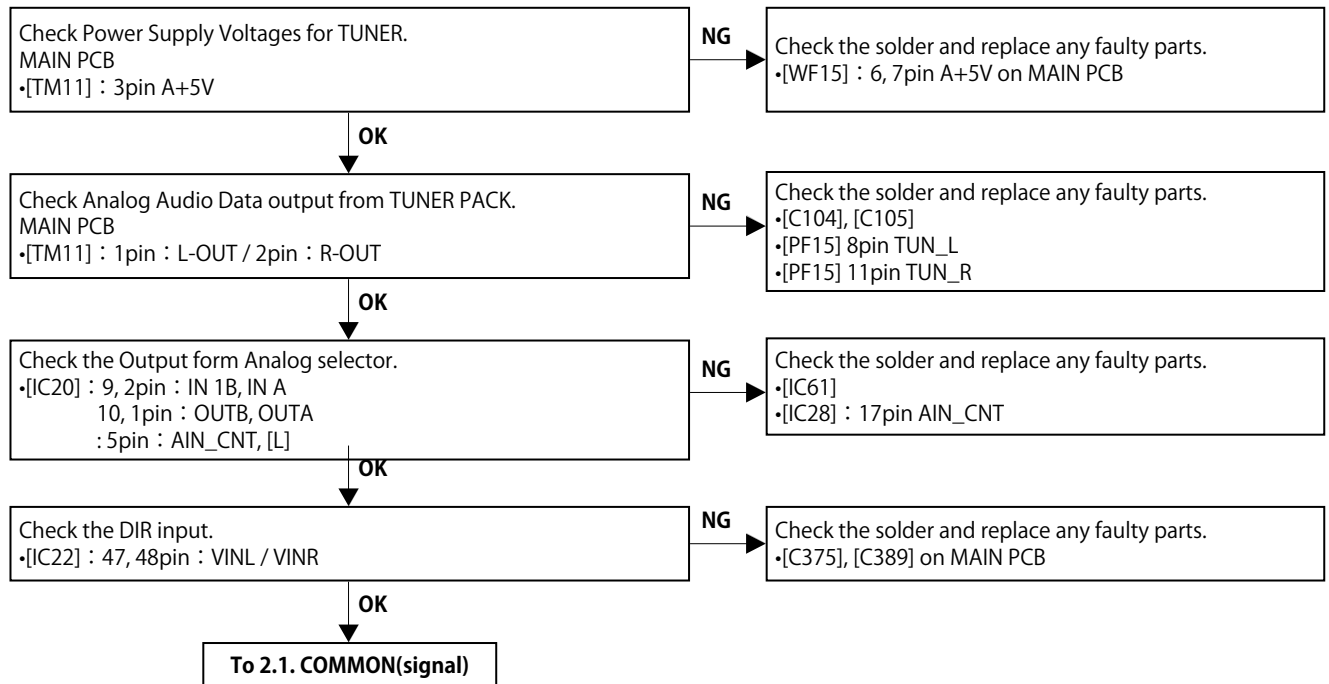




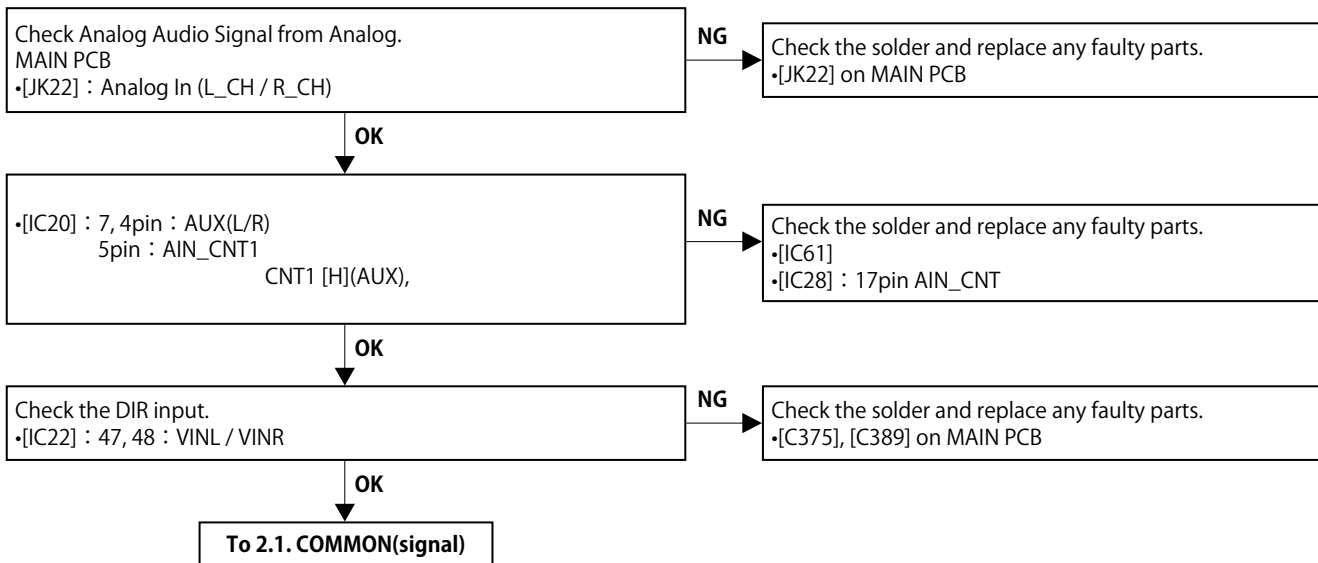
2.3. CD PLAY BACK



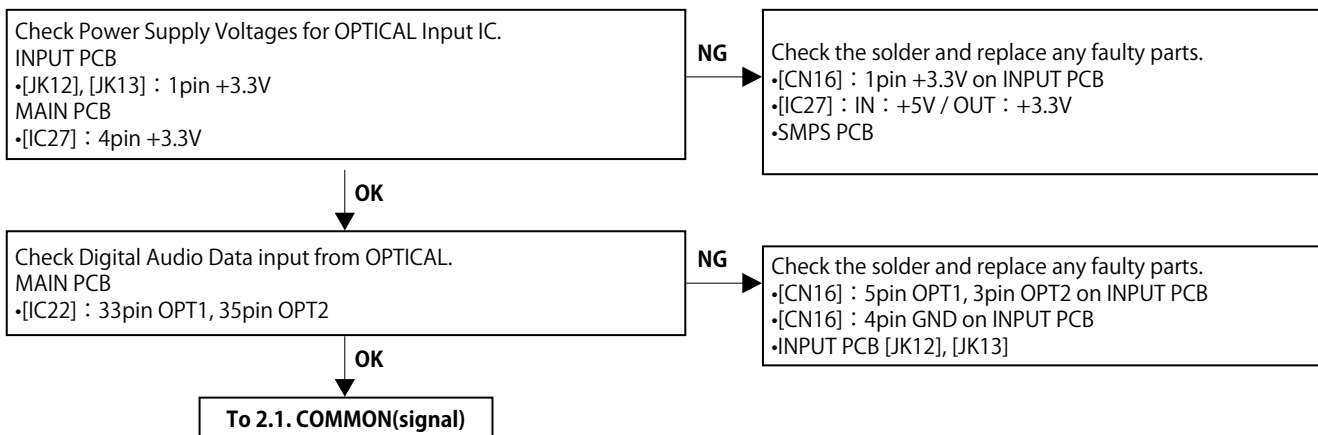
2.4 . TUNER



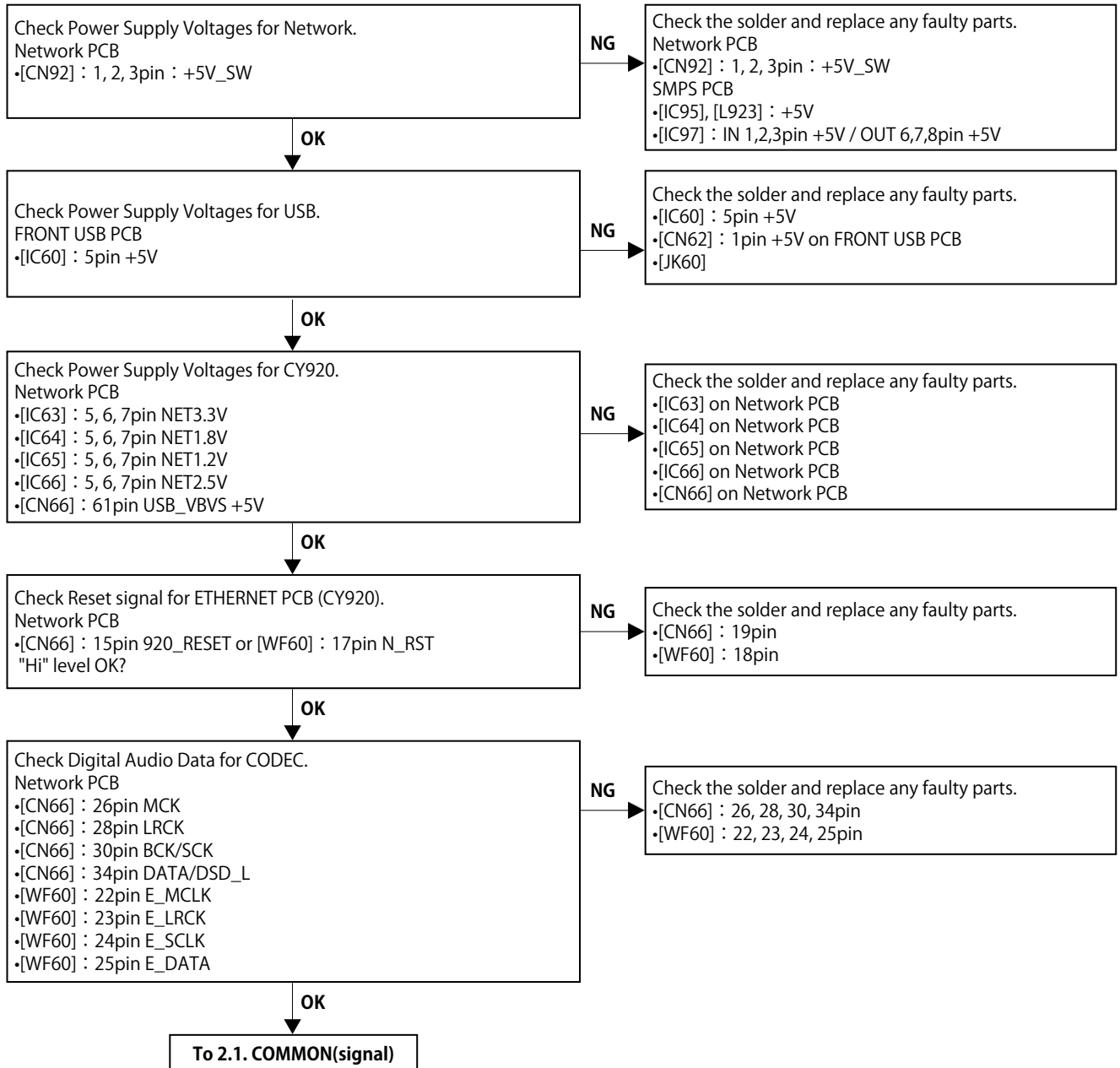
2.5 . Analog In



2.6. Digital In 1/2



2.7 . USB / ETHERNET / Wi-Fi



MEASURING METHOD AND WAVEFORMS

To check the waveforms, the GND (-) probe of the oscilloscope to specified reference voltage.
(Except for Inner SW, TRVSW)

Caution

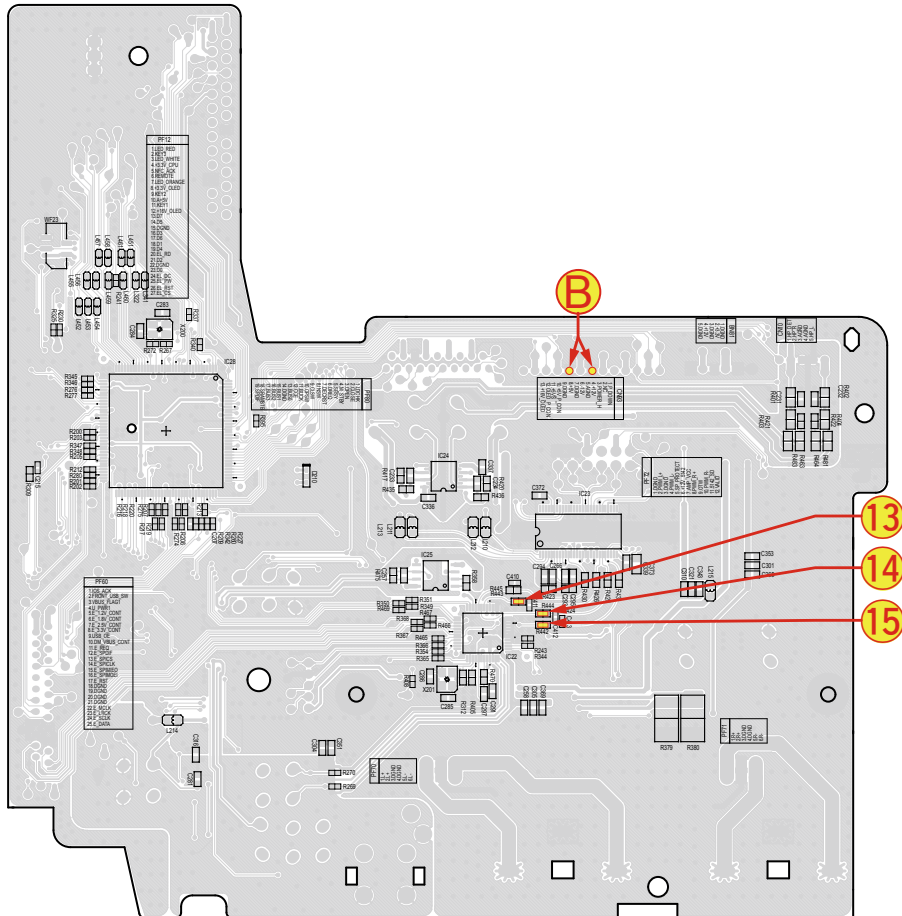
Measuring Disc : CD/TCD-784
CD-R/TCD-R082W
CD-RW/TCD-W082W

(It is the better way to use an extension wire between the test point and the probe.)

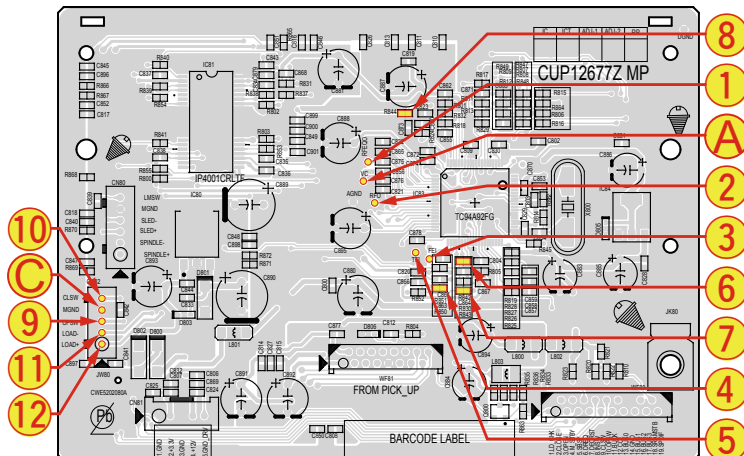
- When watching the HF waveform, use the extending wire as short as possible.
- When HF waveform is noisy or cannot discriminate the eye-pattern, replace the Traverse Unit after measuring the lop.
- Point ① - ⑮ is measured with the point shown below.

1. TEST POINT

MAIN PCB : Bside



CD PCB : Aside



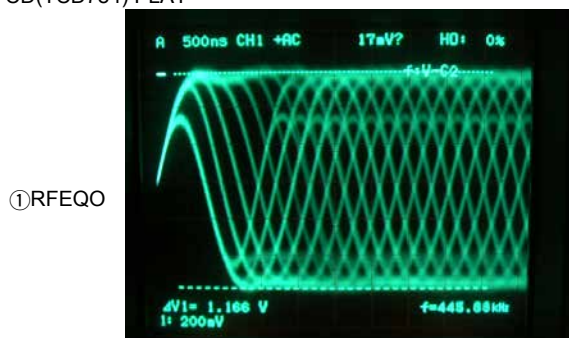
No.	Symbol	
①	TP	RFEQO
②	TP	RFO
③	TP	FEI
④	R850	FOC1
⑤	TP	TEI
⑥	R842	TRO1
⑦	R843	FMO1
⑧	R844	DMO1
⑨	CN82(3)	OPSW
⑩	CN82(5)	CLSW
⑪	CN82(2)	LOAD+
⑫	CN82(1)	LOAD-
⑬	R443	LRCK
⑭	R444	SCLK
⑮	R442	SDATA

No.	Symbol	Reference voltage
①	TP	VC : ① - ⑧
②	CN93 (7)or(9)	DGND : ⑬ - ⑮
③	CN82(4)	MGND : ⑨ - ⑫

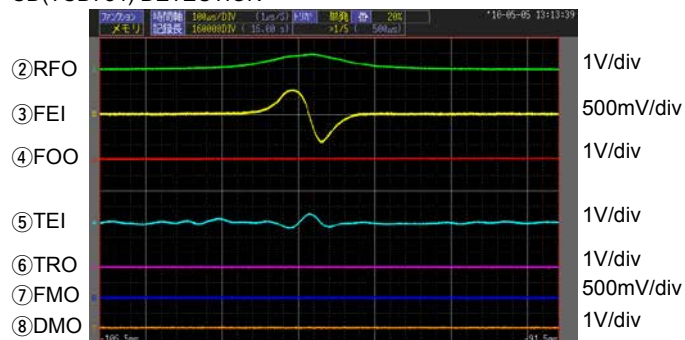
2. WAVEFORMS

1. DISC PLAY RF WAVEFORM (EYE-PATTERN) 2. DISC DETECTION

CD(TCD784) PLAY

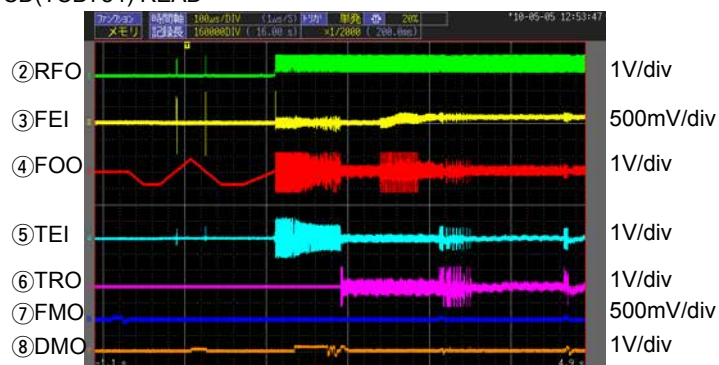


CD(TCD784) DETECTION



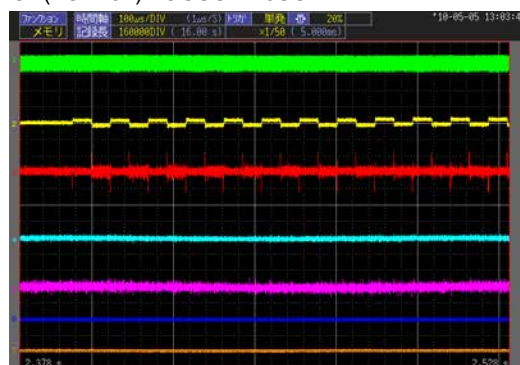
3. TOC READ

CD(TCD784) READ

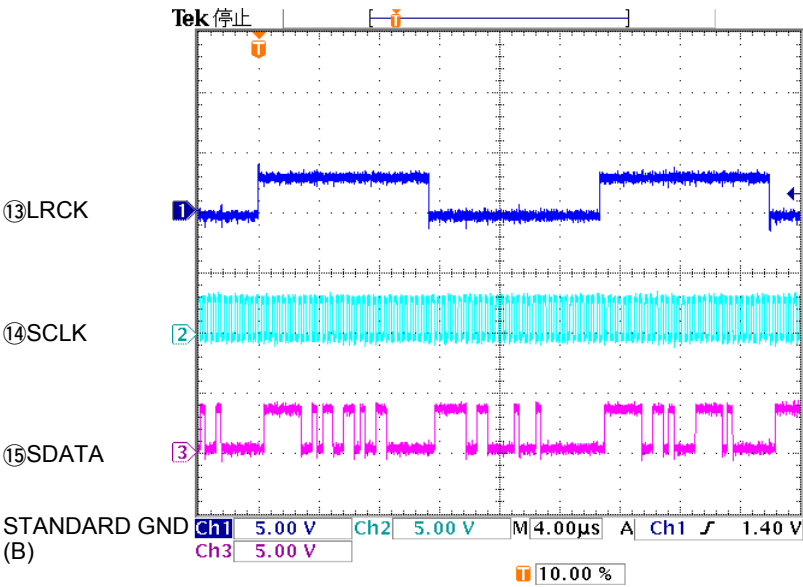


4. FOCUS ADJUSTMENT

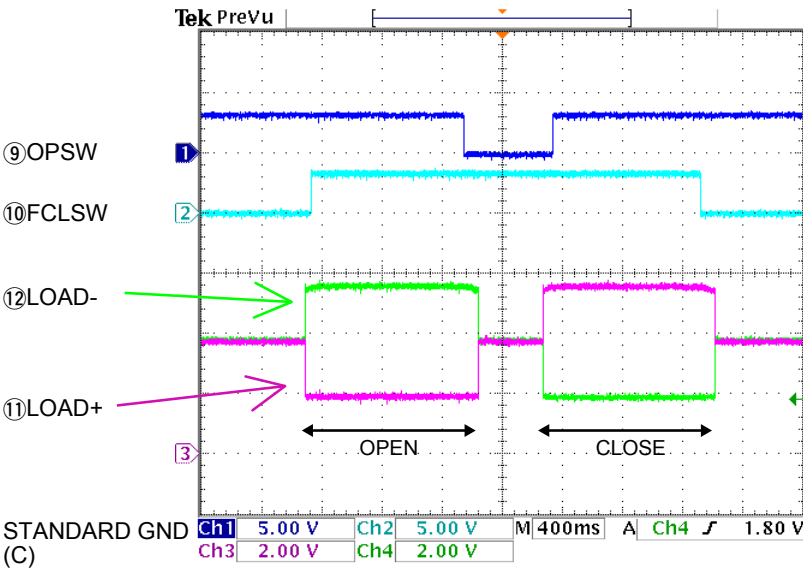
CD(TCD784) FOCUS ADJUSTMENT



4. CD Playback

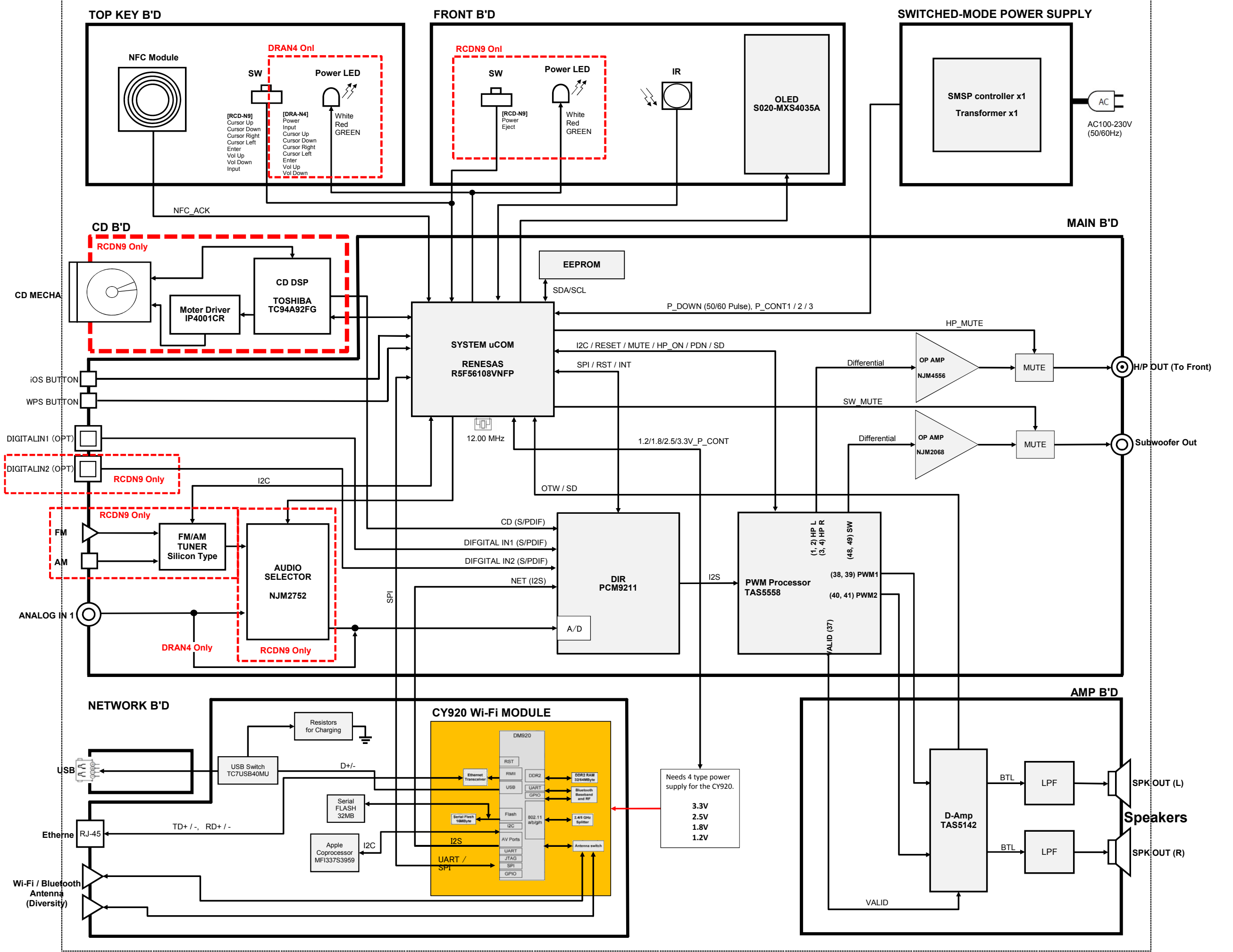


5. LOADER OPEN-CLOSE



Personal notes:

BLOCK DIAGRAM

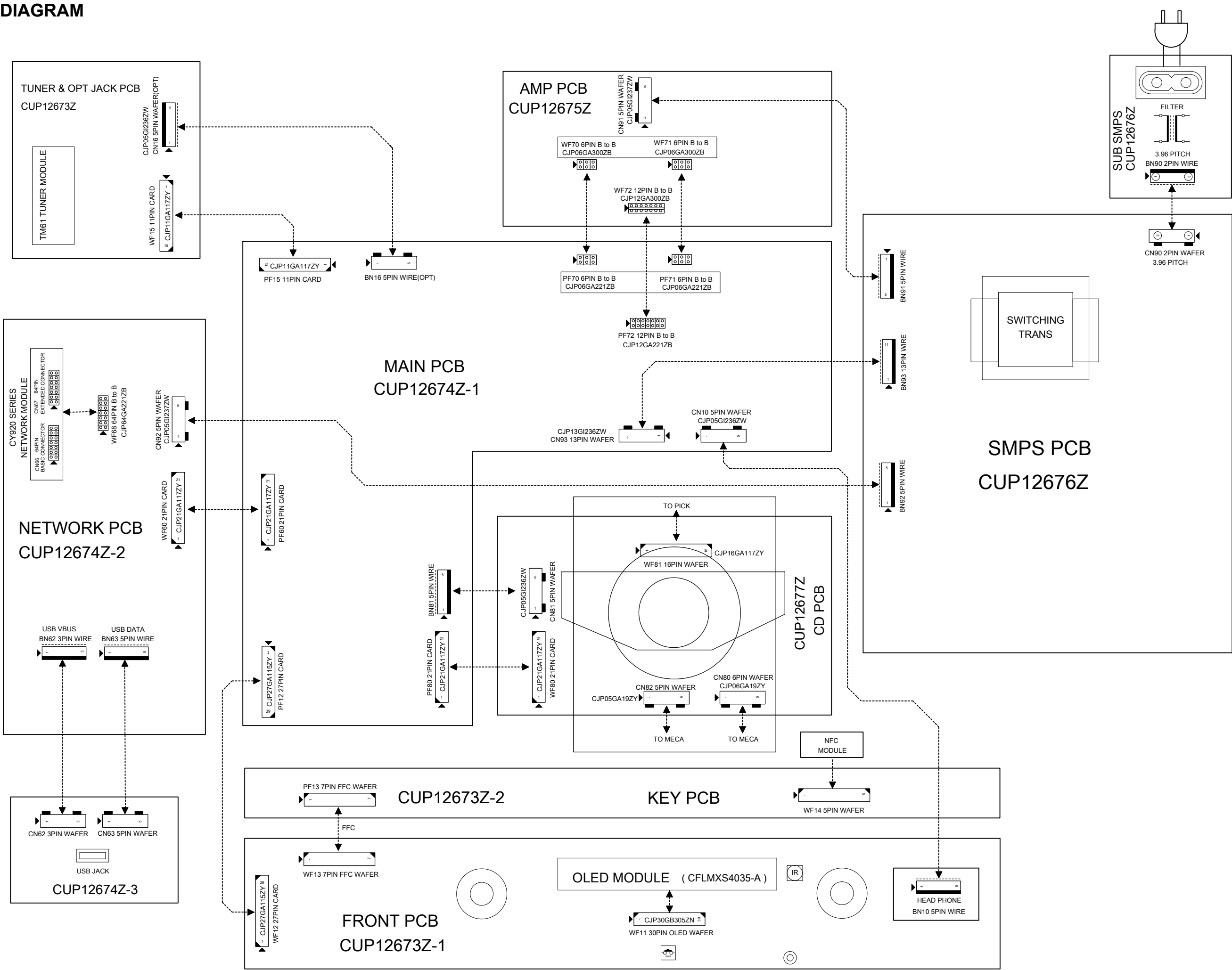


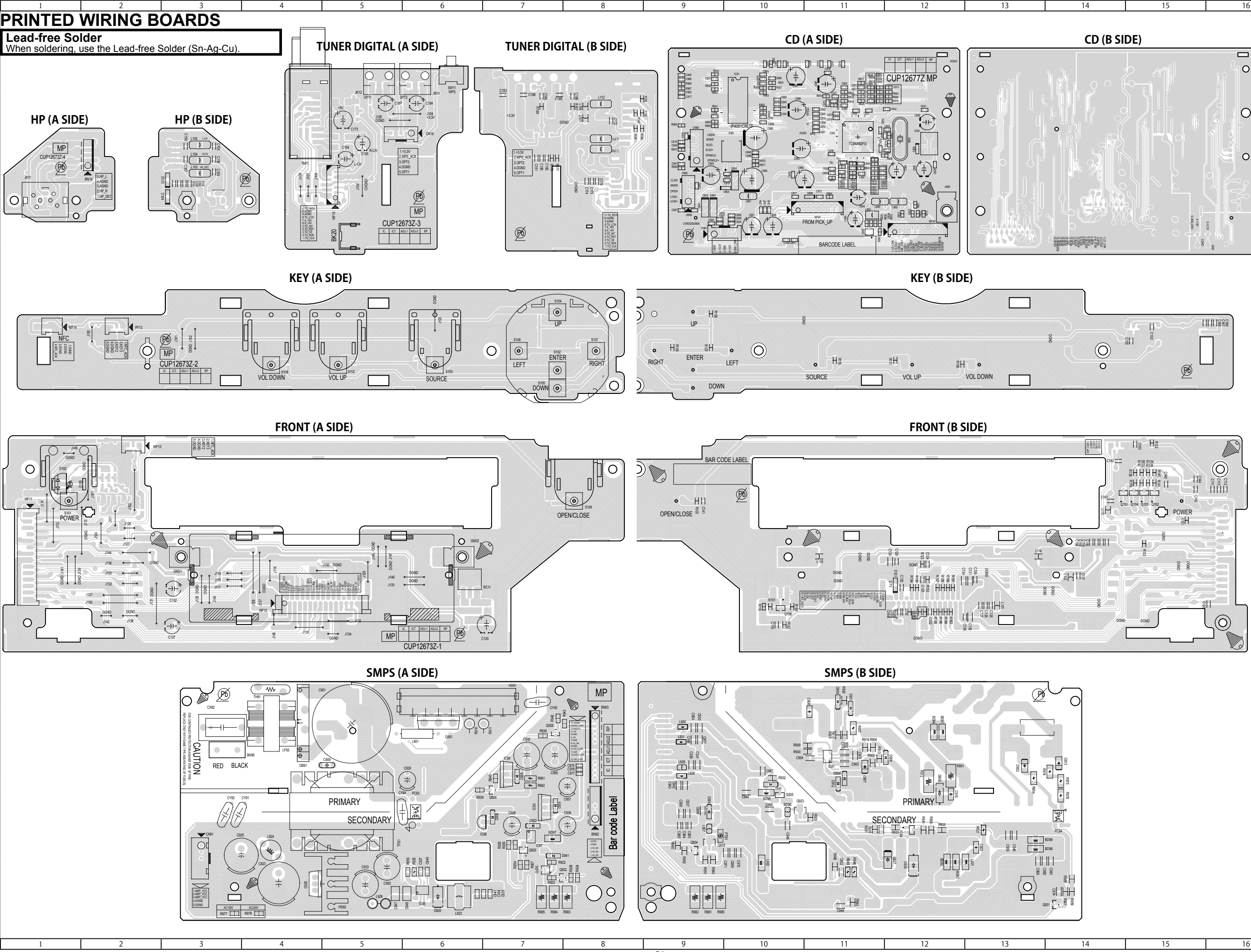
2

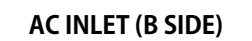
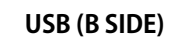
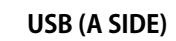
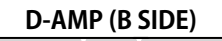
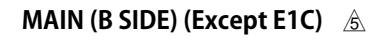
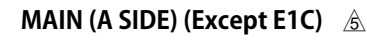
 Normal operation
 < 4W Network standby
 OLED standby
 < 0.3W Normal standby
 Audio Power Control
 Net Power Control
 OLED Power Control
 VBUS Power Control

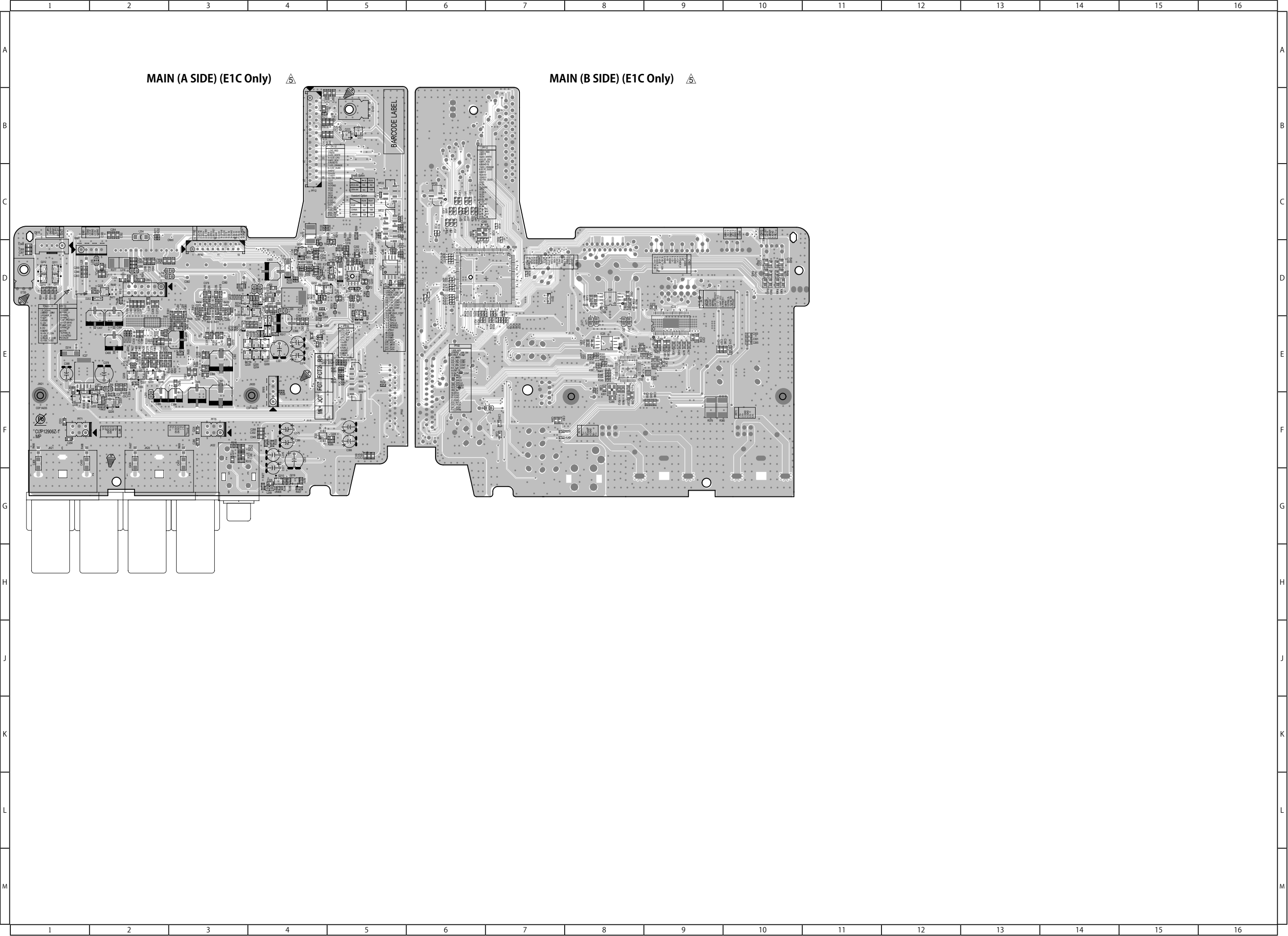


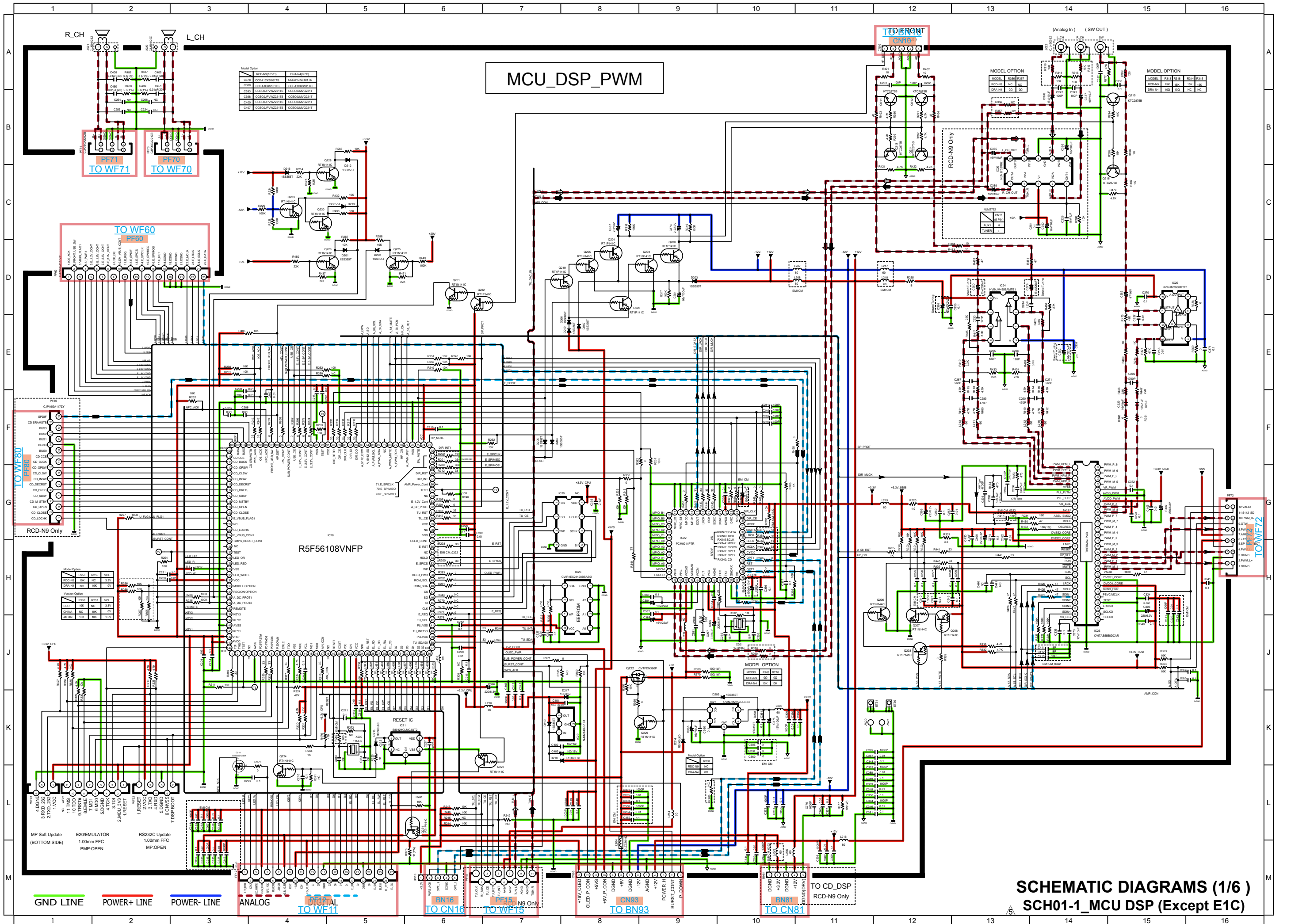
WIRING DIAGRAM





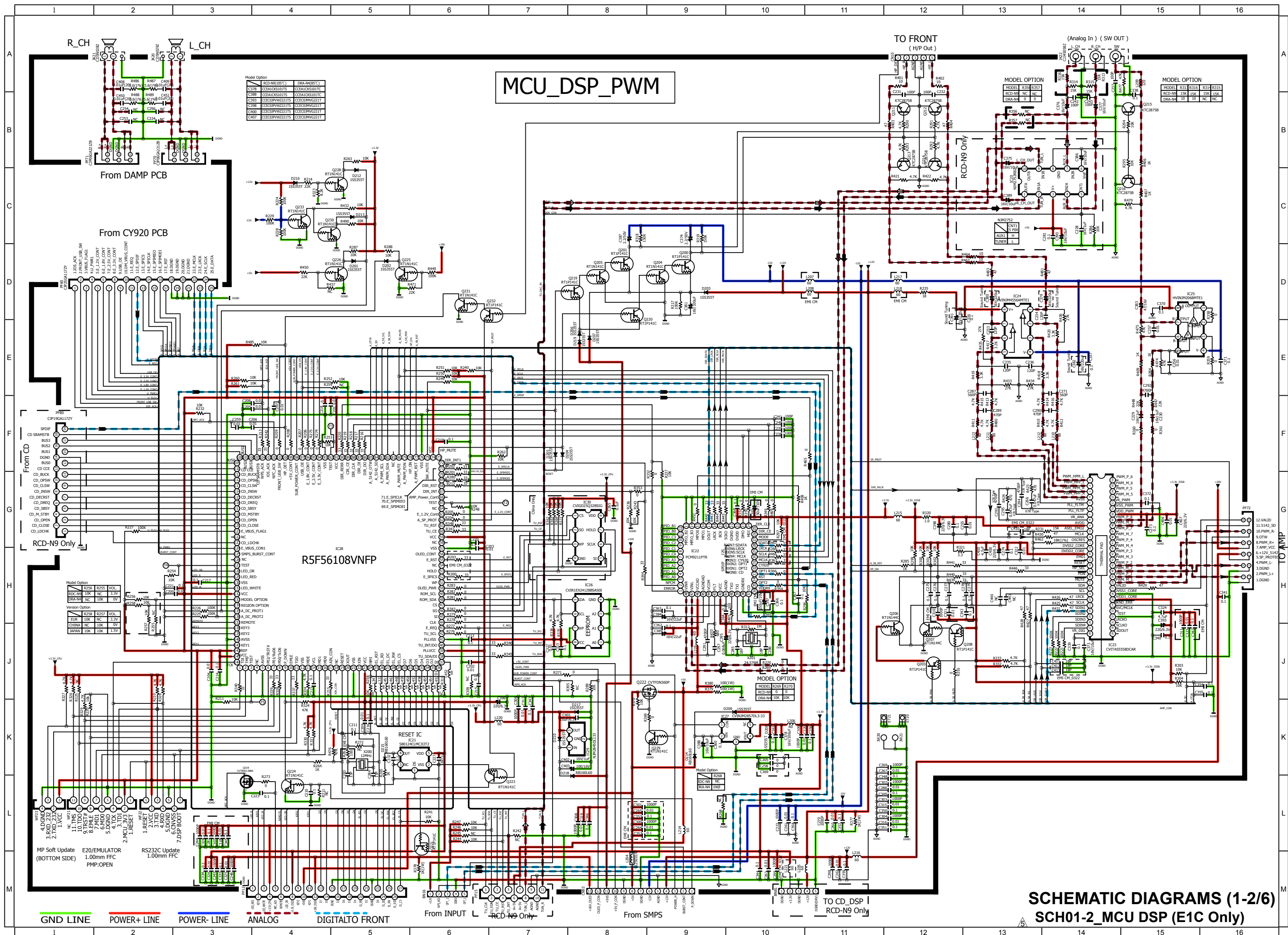




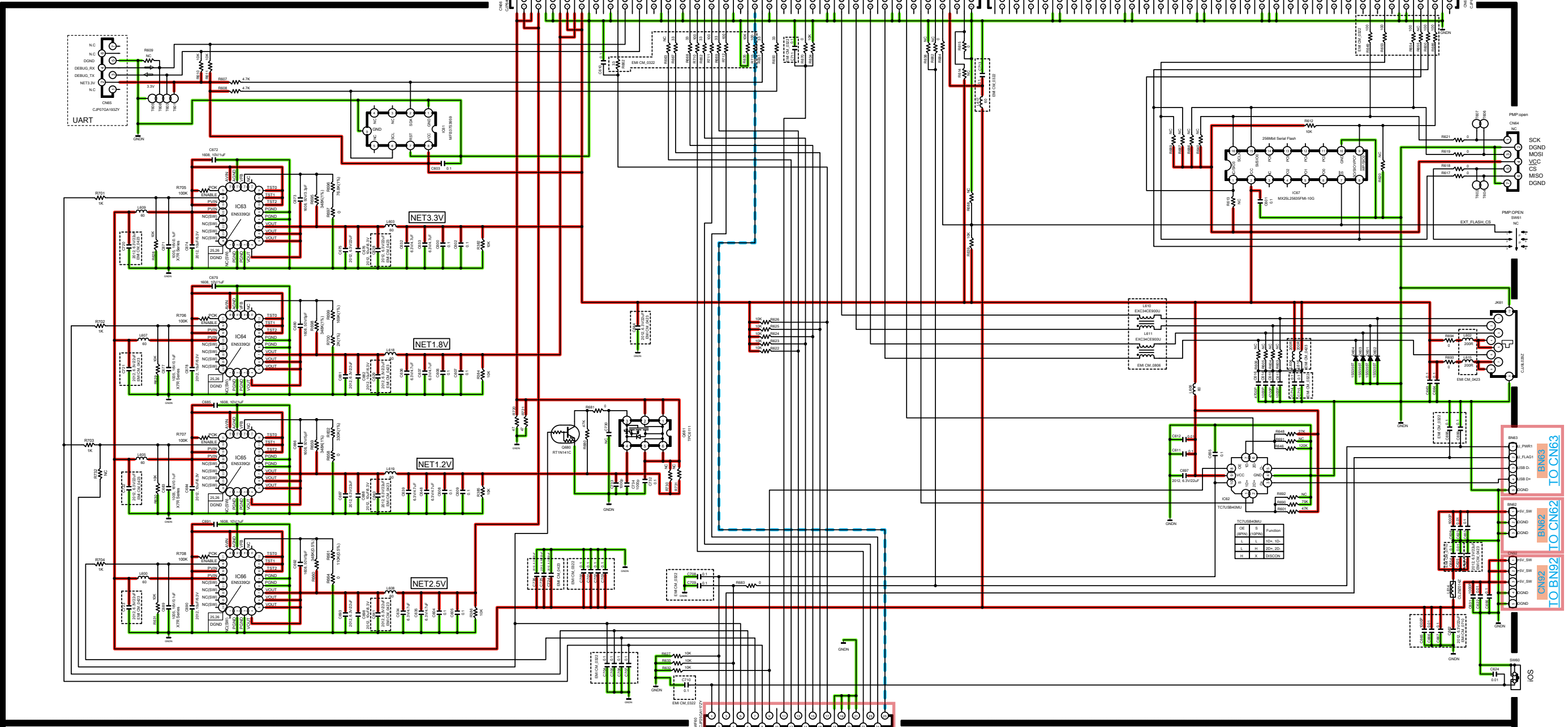


MCU_DSP_PWM

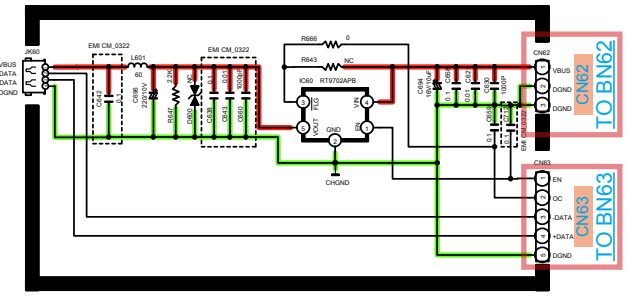
SCHEMATIC DIAGRAMS (1/6)
SCH01-1_MCU DSP (Except E1C)



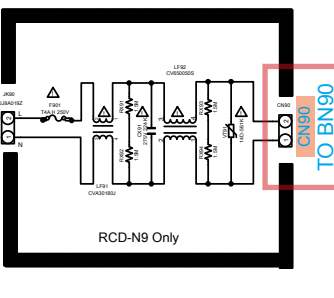
NETWORK PCB

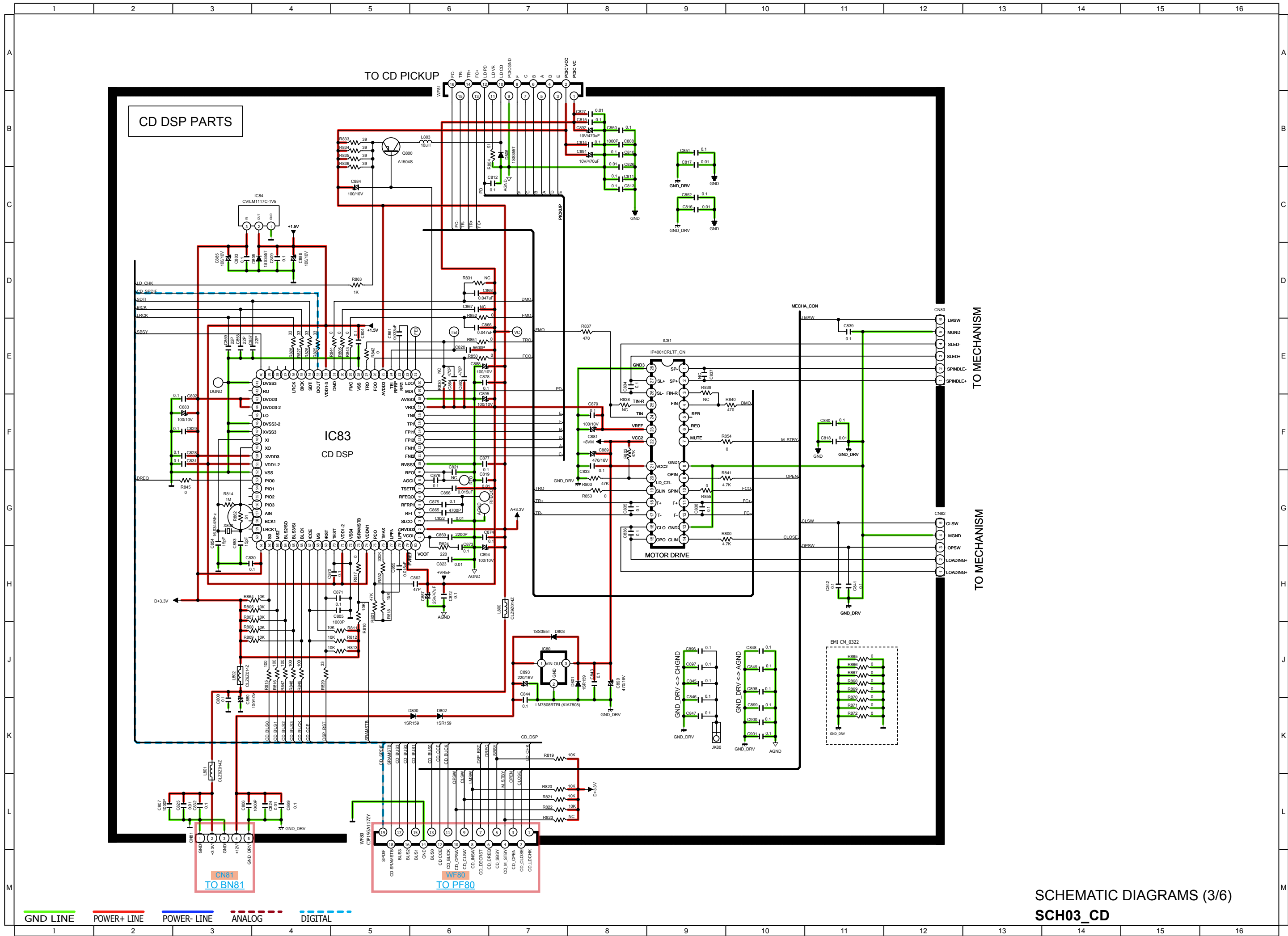


FRONT USB PCB



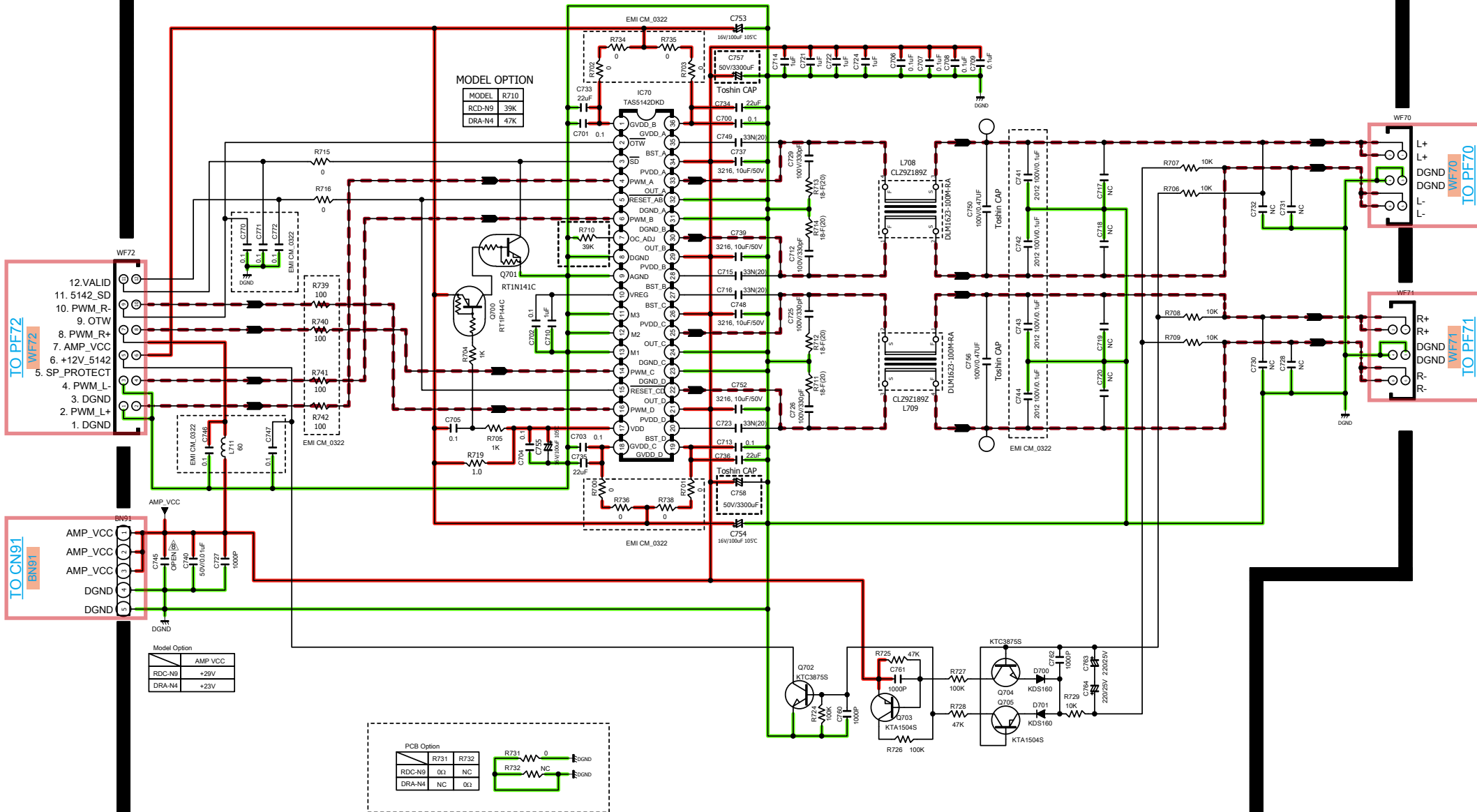
AC INLET PCB





SCHEMATIC DIAGRAMS (3/6)
SCH03_CD

D-AMP



SCHEMATIC DIAGRAMS (4/6)

SCH04_D-AMP

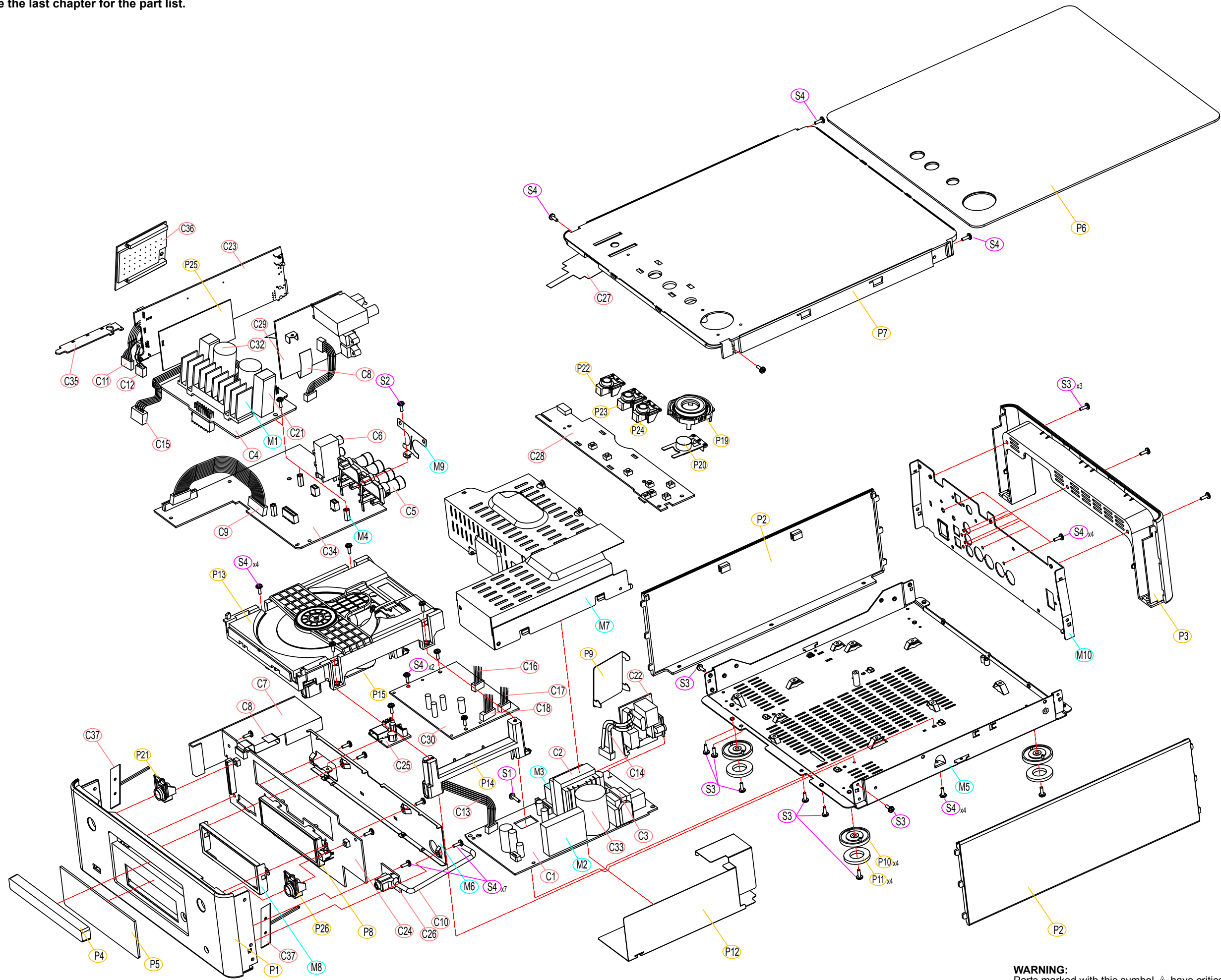
GND LINE POWER+ LINE POWER- LINE ANALOG DIGITAL





EXPLODED VIEW

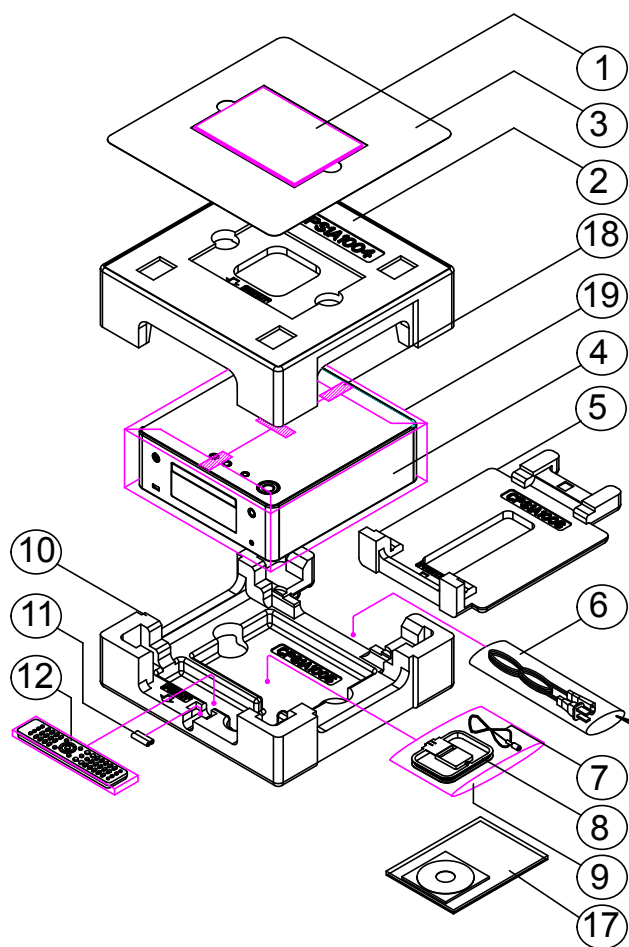
Please see the last chapter for the part list.



WARNING:
Parts marked with this symbol  have critical characteristics.
Use ONLY replacement parts recommended by the manufacturer.

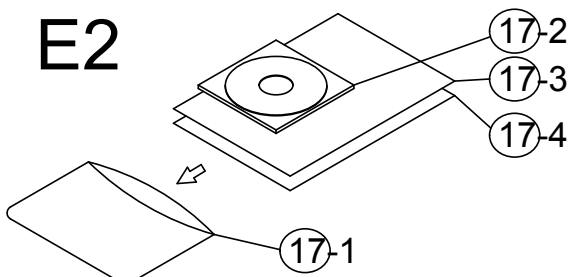
PACKING VIEW

Please see the last chapter for the part list.

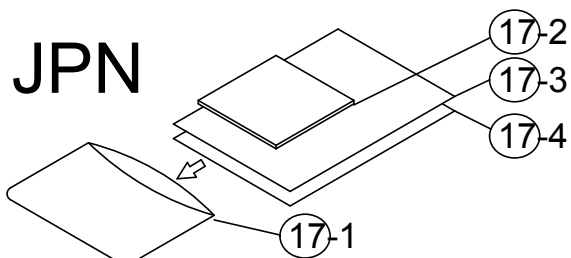


17 MANUAL ASSY

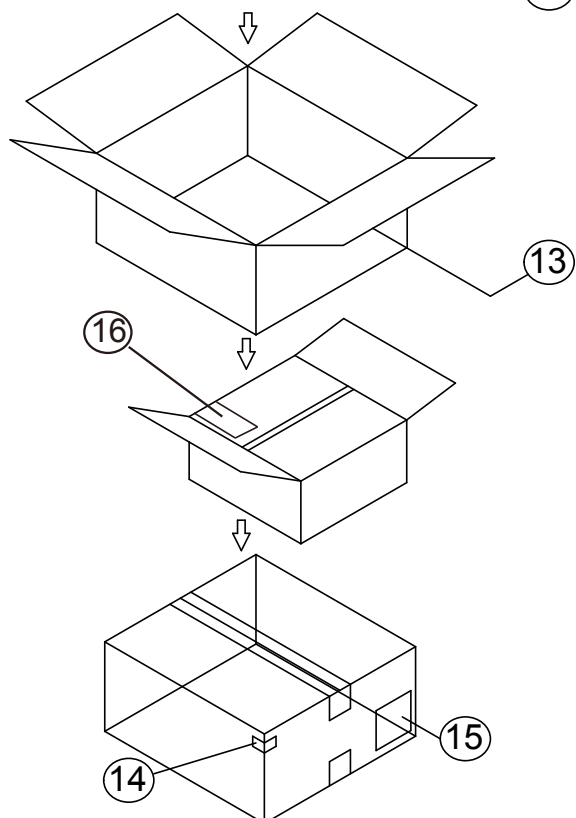
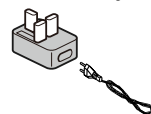
E2



JPN



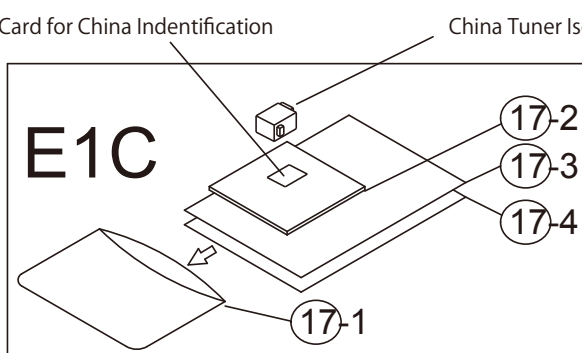
UK plug
(UK Only)



Card for China Identification

China Tuner Isolator

E1C

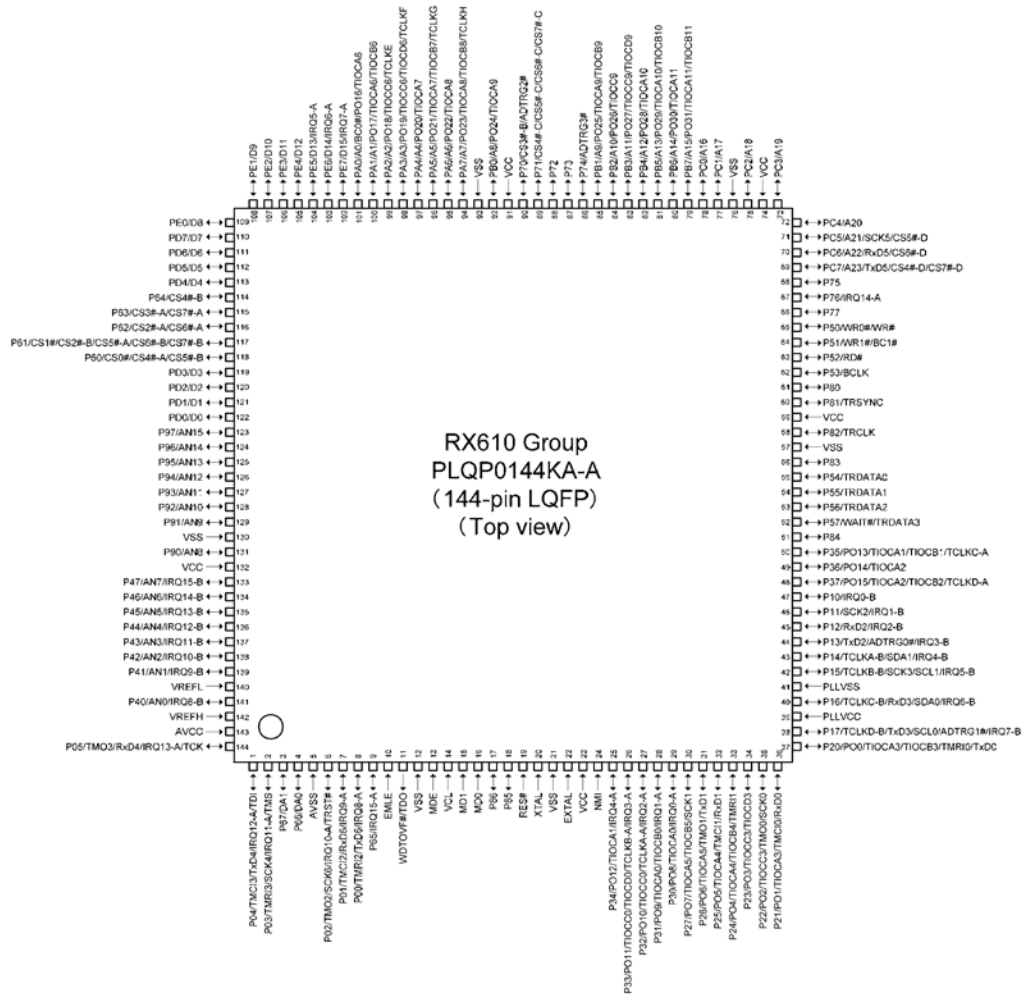


SEMICONDUCTORS

Only major semiconductors are shown, general semiconductors etc. are omitted to list.
The semiconductor which described a detailed drawing in a schematic diagram are omitted to list.

1. IC's

R5F56108VNFP (MAIN : IC28)



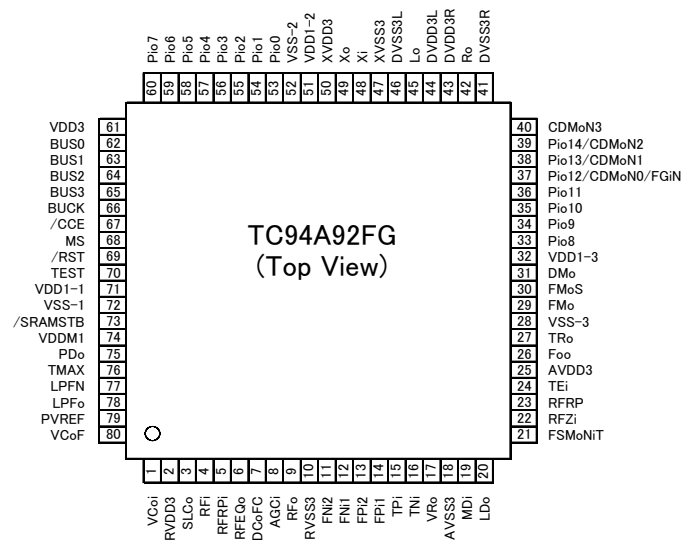
R5F56108VNFP (MAIN : IC28) Terminal Function


Pin	Port Name	PD/PU	I/O	STANDBY MODE					Note
				STBY	TIMER STBY	Network STBY	OLED STBY	OLED+NW STBY	
1	TDI	PU	I	I	I	I	I	I	Emulator Connection terminal
2	TMS	PU	I	I	I	I	I	I	Emulator Connection terminal
3	TEST1	PD	I	I	I	I	I	I	Boot for Check PCB mode
4	OPEN	-	O	O/L	O/L	O/L	O/L	O/L	OPEN
5	AVSS	-	-	-	-	-	-	-	GND
6	TRST#	PD	I	I	I	I	I	I	Emulator Connection terminal
7	RXD MI232O	PU	I	I	I	I	I	I	UPDATE
8	TXD MO232I	-	O	O/L	O/L	O/L	O/L	O/L	UPDATE
9	P.Down	PU	I	I	I	I	I	I	P.Down Detect (INT)
10	EMLE	PD	I	I	I	I	I	I	Emulator Connection terminal
11	TDO	PU_OPEN	O	O/L	O/L	O/L	O/L	O/L	Emulator Connection terminal
12	VSS	-	-	-	-	-	-	-	GND
13	MDE	PD	I	I	I	I	I	I	Operation Mode Setting
14	VCL	-	I	I	I	I	I	I	Smoothing capacitor (0.1uF) connection terminal
15	MD1	PU	I	I	I	I	I	I	Emulator Connection terminal
16	MD0	PU	I	I	I	I	I	I	Emulator Connection terminal
17	AIN_CNT1	-	O	O/L	O/L	O/L	O/L	O/L	Analog Switch IC Control 1 (AUX1=H, TUNER=L)
18	OPEN	-	O	O/L	O/L	O/L	O/L	O/L	OPEN
19	RESET	PU	I	I	I	I	I	I	Reset
20	X-OUT	-	-	-	-	-	-	-	Clock Output (12MHz)
21	VSS	-	-	-	-	-	-	-	GND
22	X-IN	-	-	-	-	-	-	-	Clock Input (12MHz)
23	VCC	-	-	-	-	-	-	-	+3.3V_CPU
24	NMI	PU	I	I	I	I	I	I	Basic Functions of Microcomputer
25	EL RESET	PD	O	O/L	O/L	O/L	O/H	O/H	Reset for OLED (L: Reset)
26	EL E,RD	-	O	O/L	O/L	O/L	O	O	EL Readout
27	EL D/C	-	O	O/L	O/L	O/L	O	O	Switching Data/Commando (H : Data, L : Command)
28	EL R/W,WR	-	O	O/L	O/L	O/L	O	O	EL Writing
29	EL CS	-	O	O/L	O/L	O/L	O/L	O/L	EL Chip Select (L : I/F communication)
30	D7	-	O	O/L	O/L	I	O	O	Data Bus for OLED
31	D6	-	O	O/L	O/L	I	O	O	Data Bus for OLED
32	D5	-	O	O/L	O/L	I	O	O	Data Bus for OLED
33	D4	-	O	O/L	O/L	I	O	O	Data Bus for OLED
34	D3	-	O	O/L	O/L	I	O	O	Data Bus for OLED
35	D2	-	O	O/L	O/L	I	O	O	Data Bus for OLED
36	D1	-	O	O/L	O/L	I	O	O	Data Bus for OLED
37	D0	-	O	O/L	O/L	I	O	O	Data Bus for OLED
38	TU_SDA	PU	O	O/L	O/L	O/L	O/L	O/L	I2C Data for TUNER
39	PLL VCC	-	-	-	-	-	-	-	+3.3V_CPU
40	TU_INT	-	I	I	I	I	I	I	TUNER Interrupt
41	PLL VSS	-	-	-	-	-	-	-	GND
42	TU_SCL	PU	O	O/L	O/L	O/L	O/L	O/L	I2C Clock for TUNER
43	E_REQ	PD	I	I	I	I	I	I	DM870 Interrupt
44	GD25Q32_CLK	-	O	O/L	O/L	O/L	O/L	O/L	GD25Q32-6P, CLK
45	GD25Q32_SI	PU	I/O	I	I	I	I	I	GD25Q32-5P, SI (IO0)
46	GD25Q32_SO	PU	I/O	I	I	I	I	I	GD25Q32-2P, SO (IO1)
47	GD25Q32_CS	-	O	O/L	O/L	O/L	O/L	O/L	GD25Q32-1P, CS
48	EEPROM SDA	PU	I/O	I	I	I	I	I	EEPROM R1EX24256A Control
49	EEPROM SCL	PU	O	I	I	I	I	I	EEPROM R1EX24256A Control
50	OLED_P_CONT	PD	O	O/L	O/L	O/L	O/H	O/H	Power Control for OLED +18V
51	GD25Q32_WP	PU	I/O	I	I	I	I	I	GD25Q32-3P, WP# (IO2)
52	/E_SPICS	PU(CX870)	O	O/L	O/L	O	O/L	O	SCI or CS Signal Output to the DM870
53	GD25Q32_HOLD	PU	I/O	I	I	I	I	I	GD25Q32-7P, HOLD# (IO3)
54	OPEN	-	O	O/L	O/L	O/L	O/L	O/L	OPEN
55	E_RESET	PU(CX870)	O	O/L	O/L	O/H	O/L	O/H	Reset for DM870
56	OLED_3V3_CONT	PD	O	O/L	O/L	O/L	O/L	O/L	OLED_3.3V_CONT
57	VSS	-	-	-	-	-	-	-	GND
58	OPEN	-	O	O/L	O/L	O/L	O/L	O/L	OPEN
59	VCC	-	-	-	-	-	-	-	+3.3V_CPU
60	TU_CE	-	O	O/L	O/L	O/L	O/L	O/L	Tuner Control (CE)
61	TU_RST	PU	O	O/L	O/L	O/L	O/L	O/L	Reset Tuner

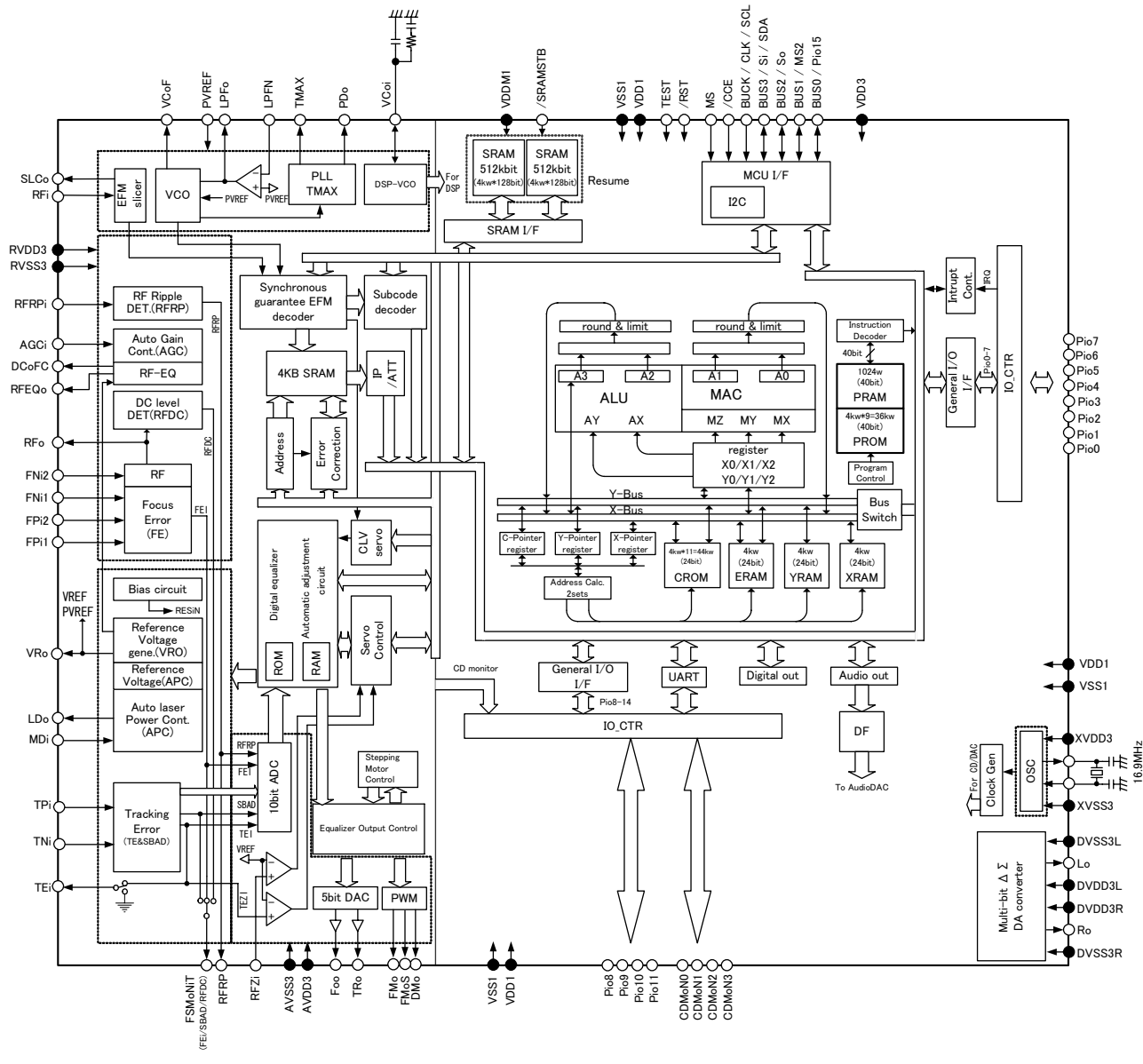
Pin	Port Name	PD/PU	I/O	STANDBY MODE					Note
				STBY	TIMER STBY	Network STBY	OLED STBY	OLED+NW STBY	
62	SP_PROTECT	PU	I	I	I	I	I	I	DC Power Detect (SPK OUT)
63	+1V2_NET_P_CONT	PD	O	O/L	O/L	O/H	O/L	O/H	Power Control for CY920_+1.2V
64	OPEN	-	O	O/L	O/L	O/L	O/L	O/L	OPEN
65	TEST2	PD	I	I	I	I	I	I	Boot for Check PCB mode
66	OPEN	-	O	O/L	O/L	O/L	O/L	O/L	OPEN
67	DIR_INT	PD(DIR_RERR) Common	I	I	I	I	I	I	PCM9211(DIR) Control
68	DIR_RST	PD	O	O/L	O/L	O/L	O/L	O/L	PCM9211(DIR) Control
69	E_SPIMOEI	-	O	O/L	O/L	O/L	O/L	O/L	CY920 SPI
70	E_SPIMIEO	-	I	I	I	I	I	I	CY920 SPI
71	E_SPICLK	-	O	O/L	O/L	O/L	O/L	O/L	CY920 SPI
72	DIR_INT1	PD	I	I	I	I	I	I	Analog Input Detection from PCM9211 (Not used)
73	/H/P_MUTE	PD	O	O/L	O/L	O/L	O/L	O/L	H/P MUTE
74	VCC	-	-	-	-	-	-	-	+3.3V_CPU
75	SW_MUTE	PD	O	O/L	O/L	O/L	O/L	O/L	SW MUTE
76	VSS	-	-	-	-	-	-	-	GND
77	/5558_RESET	PU	O	O/L	O/L	O/L	O/L	O/L	TAS 5558 System Reset input (11 pin)
78	/H/P_ON	PU	O	O/L	O/L	O/L	O/L	O/L	TAS 5558 Headphone in/out selector (12 pin)
79	/5558_PDN	PU(DTA)	O	O/L	O/L	O/L	O/L	O/L	TAS 5558 Power down (12 pin)
80	/5558_MUTE	PU(DTA)	O	O/L	O/L	O/L	O/L	O/L	TAS 5558 Soft mute of outputs (14 pin)
81	OPEN	-	O	O/L	O/L	O/L	O/L	O/L	OPEN
82	5558_SDA	PU	I/O	I	I	I	I	I	TAS 5558 I2C SDA (24 pin)
83	5558_SCL	PU	I/O	I	I	I	I	I	TAS 5558 I2C SCL (25 pin)
84	/5142_SD	PU	I	I	I	I	I	I	TAS 5142 Shutdown Signal
85	/5142_OTW	PU	I	I	I	I	I	I	TAS 5142 Overtemperature Warning Signal
86	DIR_DO	-	I	I	I	I	I	I	PCM9211(DIR) Control
87	DIR_DI	-	O	O/L	O/L	O/L	O/L	O/L	PCM9211(DIR) Control
88	DIR_CL	-	O	O/L	O/L	O/L	O/L	O/L	PCM9211(DIR) Control
89	DIR_CE	-	O	O/L	O/L	O/L	O/L	O/L	PCM9211(DIR) Control
90	DIR_RERR	PD	I	I	I	I	I	I	PCM9211(DIR) Control
91	VCC	-	-	-	-	-	-	-	+3.3V_CPU
92	TEST3	PD	I	I	I	I	I	I	Boot for Check PCB mode
93	VSS	-	-	-	-	-	-	-	GND
94	+3V3_NET_P_CONT	PD	O	O/L	O/L	O/H	O/L	O/H	Power Control for CY920_+3.3V
95	+2V5_NET_P_CONT	PD	O	O/L	O/L	O/H	O/L	O/H	Power Control for CY920_+2.5V
96	+1V8_NET_P_CONT	PD	O	O/L	O/L	O/H	O/L	O/H	Power Control for CY920_+1.8V
97	USB_OE	-	O	O/L	O/L	O/L	O/L	O/L	Mute Control When Switching USB Route (H : MUTE / L : Enable)
98	AUDIO_P_CONT	PD	O	O/L	O/L	O/L	O/L	O/L	Power Control (-/+3.3V_D1, -/+12V_A)
99	+5V_P_CONT	PD	O	O/L	O/L	O/H	O/L	O/H	Power Control for CY920_+5V
100	HP/DET	PU	I	I	I	I	I	I	H/P detect
101	FRONT_USB_SW	PD	O	O/L	O/L	O/L	O/L	O/L	Front USB Switch IC Control
102	NFC_ACK	PU	I	I	I	I	I	I	Bluetooth Pairing Mode
103	iOS_ACK	PU	I	I	I	I	I	I	WiFi Sharing Start
104	WPS_ACK	PU	I	I	I	I	I	I	WPS Start
105	SRAMSTB	PU	O	O/L	O/L	O/L	O/L	O/L	SRAMSTB Control for CD DSP
106	BUS3	PU	I/O	O/L	O/L	O/L	O/L	O/L	CD DSP (TC94A92FG) Control
107	BUS2	PU	I/O	O/L	O/L	O/L	O/L	O/L	CD DSP (TC94A92FG) Control
108	BUS1	PU	I/O	O/L	O/L	O/L	O/L	O/L	CD DSP (TC94A92FG) Control
109	BUS0	PU	I/O	O/L	O/L	O/L	O/L	O/L	CD DSP (TC94A92FG) Control
110	CCE	PU	O	O/L	O/L	O/L	O/L	O/L	CD DSP Control (Chip Enable)
111	BUCK	PU	O	O/L	O/L	O/L	O/L	O/L	CD DSP Control (BUS CLK)
112	OPSW	PU	I	I	I	I	I	I	Open SW from CD Mecha
113	CLSW	PU	I	I	I	I	I	I	Close SW from CD Mecha
114	LNSW	PU	I	I	I	I	I	I	Limit SW from CD Mecha
115	DECRST	PU	O	O/L	O/L	O/L	O/L	O/L	Reset for CD DSP (TC94A92FG)
116	DREQ	-	I	I	I	I	I	I	CD DSP (TC94A92FG) DREQ
117	SBSY	PU	I	I	I	I	I	I	CD Monitor (Default: SBSY) from CD DSP (TC94A92FG)

Pin	Port Name	PD/PU	I/O	STANDBY MODE					Note
				STBY	TIMER STBY	Network STBY	OLED STBY	OLED+NW STBY	
118	DRVMUTE	PU_OPEN	O	O/L	O/L	O/L	O/L	O/L	CD Driver Mute (H: Mute Off, L: Mute On)
119	CD_OPEN	-	O	O/L	O/L	O/L	O/L	O/L	Open CD Tray
120	CD_CLOSE	-	O	O/L	O/L	O/L	O/L	O/L	Close CD Tray
121	VBUS_FLUG1	PU	I	I	I	I	I	I	Check VBUS Voltage 1 (Front USB), L : Error
122	OPEN	-	O	O/L	O/L	O/L	O/L	O/L	OPEN
123	LD_CHK	AD	I	I	I	I	I	I	Check CD Laser Diode Current
124	VBUS_CTL1	PD	O	O/L	O/L	O/L	O/L	O/L	VBUS Control 1 (Front USB)
125	SMPS_BURST_CONT	-	O	O/L	O/L	O/L	O/L	O/L	SMPS Burst mode Control
126	DM_VBUS_CONT	-	O	O/L	O/L	O/H	O/L	O/H	DM870 VBUS Control
127	TEST4	PD	I	I	I	I	I	I	Boot for Check PCB mode
128	LED_ORANGE	PD	O	O/L	O/H	O/L	O/L	O/L	Control ORANGE (Red + Green) LED
129	LED_RED	PD	O	O/L	O/L	O/H	O/L	O/H	Control RED LED
130	VSS	-	-	-	-	-	-	-	GND
131	LED_WT	PD	O	O/L	O/L	O/L	O/L	O/L	Control WHITE LED (POWER ON: H)
132	VCC	-	-	-	-	-	-	-	+3.3V_CPU
133	MODEL	AD	I	I	I	I	I	I	Model Select (L (0V):N4, H (3.3V):N9)
134	REGION	AD	I	I	I	I	I	I	Region Select (H (3.3V):E2, E3/MID (1.64V):JP)
135	DC_PROT1	PU	I	I	I	I	I	I	Power Down Detect (+29V LINE)
136	DC_PROT2	PU	I	I	I	I	I	I	Power Down Detect
137	REMOTE IN	PU(open)	I	I	I	I	I	I	Remote Input
138	KEY3	PU	I	I	I	I	I	I	Key Input 3 (A/D Port)
139	KEY2	PU	I	I	I	I	I	I	Key Input 2 (A/D Port)
140	VREFL	-	-	-	-	-	-	-	GND
141	KEY1	PU	I	I	I	I	I	I	Key Input 1 (A/D Port)
142	VREFH	-	-	-	-	-	-	-	+3.3V_CPU
143	AVCC	-	-	-	-	-	-	-	+3.3V_CPU
144	TCK	PU	I	I	I	I	I	I	Emulator Connection terminal

TC94A92FG (CD : IC83)



TC94A92FG Block Diagram



TC94A92FG Terminal Function

Pin No.	Symbol	I/O	Description	Default	Remarks
1	VCoI	O 3A/I/F	DSP VCO - EFM and PLCK Phase difference signal output pin. (DSP VCO control voltage input pin.)	O	3 state output
2	RVDD3	-	CD-DSP-Power supply for 3.3V RF amplifier core and PLL circuit	-	
3	SLCo	O 3A/I/F	EFM slice level output pin	O	Connect capacitor according with servo frequency band.
4	RFi	I 3A/I/F	RF signal input pin	I	Selectable Zin 20/10 kΩ
5	RFRPi	I 3A/I/F	RF ripple signal input pin	I	
6	RFEQo	O 3A/I/F	RF equalizer circuit output pin.	O	Connect to RFRPi by 0.1uF, to RFi by 4700pF.
7	DCoFC	O 3A/I/F	RFEQo offset compensation LPF output	O	Connect to Vro by more than 0.015uF
8	AGCi	I 3A/I/F	RF signal AGC amplifier input pin	I	
9	RFo	O 3A/I/F	RF signal generation amplifier output pin	O	
10	RVSS3	-	Grounding pin for 3.3 RF amplifier core and PLL circuit	-	
11	FNI2	I 3A/I/F	Main beam signal input pin. To be connected to PIN diode C.	I	
12	FNI1	I 3A/I/F	Main beam signal input pin. To be connected to PIN diode A.	I	
13	FPI2	I 3A/I/F	Main beam signal input pin. To be connected to PIN diode D.	I	
14	FPI1	I 3A/I/F	Main beam signal input pin. To be connected to PIN diode B.	I	
15	TPi	I 3A/I/F	Sub beam signal input pin. To be connected to PIN diode F.	I	
16	TNi	I 3A/I/F	Sub beam signal input pin. To be connected to PIN diode E.	I	
17	VRo	O 3A/I/F	1.65 V reference voltage output pin.	O	Connected to PVREF, And connect to GNG by 0.1uF+100uF.
18	AVSS3	-	Grounding pin for 3.3V CD analog circuits.	-	
19	MDi	I 3A/I/F	Monitor photodiode amplifier input pin.	I	Reference Voltage=178mVtyp.
20	LDo	O 3A/I/F	Laser diode amplifier output pin	O	
21	FSMoNiT	O 3A/I/F	Focus Error signal / Sub beam add signal output pin(monitor pin/GND)	O	
22	RFZi	I 3A/I/F	RF ripple zero-cross signal Input pin	I	
23	RFRP	O 3A/I/F	RF ripple signal output pin.	O	
24	TEi	O 3A/I/F	Tracking error signal output pin.	O	Built-in series R=500Ω. Connect to VRo by capacitor.
25	AVDD3	-	Power supply pin for 3.3 V CD analog circuits.	-	
26	FOo	O 3A/I/F	Focus servo equalizer output pin.	O	Built-in series R=3.3 kΩ
27	TRo	O 3A/I/F	Tracking servo equalizer output pin.	O	Built-in output R=3.3 kΩ
28	VSS-3	-	Grounding pin for 1.5V Decoder-DSP CD circuit	-	
29	FMo	O 3A/I/F	Feed servo equalizer output pin.	O	Built-in output R=3.3 kΩ
30	FMoS	O 3A/I/F	Feed servo equalizer output pin. (Stepper motor application)	O	Built-in output R=3.3 kΩ
31	DMo	O 3A/I/F	Disc servo equalizer output pin	O	Built-in output R=3.3 kΩ
32	VDD1-3	I/O 3I/F	Power supply pin for 1.5V Decoder-DSP /CD circuit	-	

Pin No.	Symbol	I/O	Description	Default	Remarks
33	Pio8	I/O 3I/F	Port 8(General Input/Output Port)	I	CMOS Port Schmitt input Refer to [1.2 Pin Assinment Table]
34	Pio9	I/O 3I/F	Port 9(General Input/Output Port)	I	CMOS Port Schmitt input Refer to [1.2 Pin Assinment Table]
35	Pio10	I/O 3I/F	Port 10(General Input/Output Port)	I	CMOS Port Schmitt input Refer to [1.2 Pin Assinment Table]
36	Pio11	I/O 3I/F	Port 11(General Input/Output Port)	I	CMOS Port Schmitt input Refer to [1.2 Pin Assinment Table]
37	Pio12/ CDMoN0/ FGiN	I/O 3I/F	Port 12(General Input/Output Port) / CD Monitor 0 / FG signal input	I	CMOS Port Schmitt input Refer to [1.2 Pin Assinment Table]
38	Pio13/ CDMoN1	I/O 3I/F	Port 13(General Input/Output Port) / CD Monitor1	I	CMOS Port Schmitt input Refer to [1.2 Pin Assinment Table]
39	Pio14/ CDMoN2	I/O 3I/F	Port 14(General Input/Output Port) / CD Monitor 2	I	CMOS Port Schmitt input Refer to [1.2 Pin Assinment Table]
40	CDMoN3	I/O 3I/F	CD Monitor3 (Default output : SBSY)	O	CMOS Port Refer to [1.2 Pin Assinment Table]
41	DVSS3R	-	Grounding pin for 3.3V Muiiti-Bit DAC circuit	-	
42	Ro	O 3AI/F	R channel audio output pin of Audio DAC.	O	
43	DVDD3R	-	Power supply pin for 3.3V Audio DAC circuit.	-	
44	DVDD3L	-	Power supply pin for 3.3V Audio DAC circuit.	-	
45	Lo	O 3AI/F	L channel audio output pin of Audio DAC	O	
46	DVSS3L	-	Grounding pin for 3.3V Muiiti-Bit DAC Circuit	-	
47	XVSS3	-	Grounding pin for 3.3V clock oscillator circuit	-	
48	Xi	I 3AI/F	System clock Input pin	I	Xtal oscillation circuit. Connect feedback resistor 1 M Ω between Xo and Xi
49	Xo	O 3AI/F	System clock Output pin	O	
50	XVDD3	-	Power Supply pin for 3.3V clock oscillator circuit	-	
51	VDD1-2	-	Power Supply pin for 1.5V Digital circuit	-	
52	VSS-2	-	Grounding pin for 1.5V digital circuit	-	
53	Pio0	I/O 3I/F	Port 0(General Input/Output Port)	I	CMOS Port Schmitt input Refer to [1.2 Pin Assinment Table]
54	Pio1	I/O 3I/F	Port 1(General Input/Output Port)	I	CMOS Port Schmitt input Refer to [1.2 Pin Assinment Table]
55	Pio2	I/O 3I/F	Port 2(General Input/Output Port)	I	CMOS Port Schmitt input Refer to [1.2 Pin Assinment Table]
56	Pio3	I/O 3I/F	Port 3(General Input/Output Port)	I	CMOS Port Schmitt input Refer to [1.2 Pin Assinment Table]
57	Pio4	I/O 3I/F	Port 4(General Input/Output Port)	I	CMOS Port Schmitt input Refer to [1.2 Pin Assinment Table]
58	Pio5	I/O 3I/F	Port 5(General Input/Output Port)	I	CMOS Port Schmitt input Refer to [1.2 Pin Assinment Table]
59	Pio6	I/O 3I/F	Port 6(General Input/Output Port)	I	CMOS Port Schmitt input Refer to [1.2 Pin Assinment Table]
60	Pio7	I/O 3I/F	Port 7(General Input/Output Port)	I	CMOS Port Schmitt input Refer to [1.2 Pin Assinment Table]
61	VDD3	-	Power Supply pin for 3.3V Digital circuit	-	
62	BUS0	I/O 3I/F	Microprocessor I/F data input/output pin 0	I	CMOS Port Schmitt input Refer to [1.2 Pin Assinment Table]

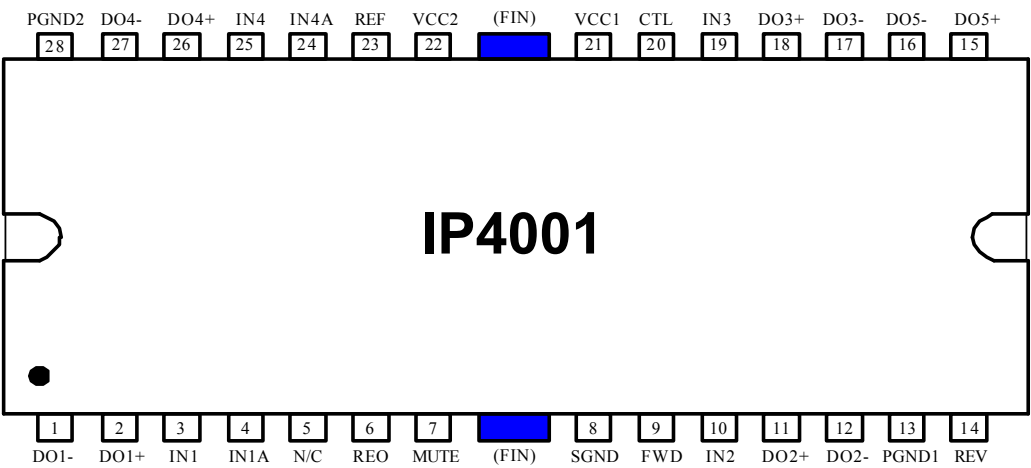
Pin No.	Symbol	I/O	Description	Default	Remarks
63	BUS1	I/O 3I/F	Microprocessor I/F data input/output pin 1	I	CMOS Port Schmitt input Refer to [1.2 Pin Assinment Table]
64	BUS2	I/O 3I/F	Microprocessor I/F data input/output pin 2	I	CMOS Port Schmitt input Refer to [1.2 Pin Assinment Table]
65	BUS3	I/O 3I/F	Microprocessor I/F data input/output pin 3	I	CMOS Port Schmitt input Refer to [1.2 Pin Assinment Table]
66	BUCK	I 3I/F	Microprocessor I/F BUS clock Input pin	I	CMOS Port Schmitt input Refer to [1.2 Pin Assinment Table]
67	/CCE	I 3I/F	Microprocessor I/F chip enable input pin	I	CMOS Port Schmitt input Refer to [1.2 Pin Assinment Table]
68	MS	I 3I/F	Microprocessor I/F mode selection pin. "H" : Parallel I/F, "L" : Serial I/F	I	Refer to [1.2 Pin Assinment Table]
69	/RST	I 3I/F	Reset Input pin	I	Schmitt input
70	Test	I 3I/F	Test pin (" L" fixed)	I	Connect to GND for normal operation
71	VDD1-1	-	Power Supply pin for 1.5V Digital circuit	-	
72	VSS-1	-	Grounding pin for 1.5V Digital circuit	-	
73	/SRAMSTB	I 3I/F	1Mbit SRAM stand by pin(/SRAMSTB="L")	I	
74	VDDM1	-	Power Supply for 1.5V 1Mbit SRAM circuit	-	
75	PDo	O 3AI/F	EFM and PLCK Phase difference signal output pin.	O	4-state output (RVDD3, RVSS3,PVREF, Hiz)
76	TMAX	O 3AI/F	TMAX detection result output pin	O	3-state output (RVDD3, RVSS3, Hiz)
77	LPFN	I 3AI/F	PLL circuit LPF amplifier inversion input pin	I	
78	LPFo	O 3AI/F	PLL circuit LPF amplifier Output pin	O	
79	PVREF	-	PLL circuit 1.65 V reference voltage pin.	-	Connected to VRO. Connect to GND by 0.1uF and 100uF.
80	VCoF	O 3AI/F	VCO filter pin	O	Connect to GND by 0.01uF

3A I/F : 3 V analog circuit input/output pin.

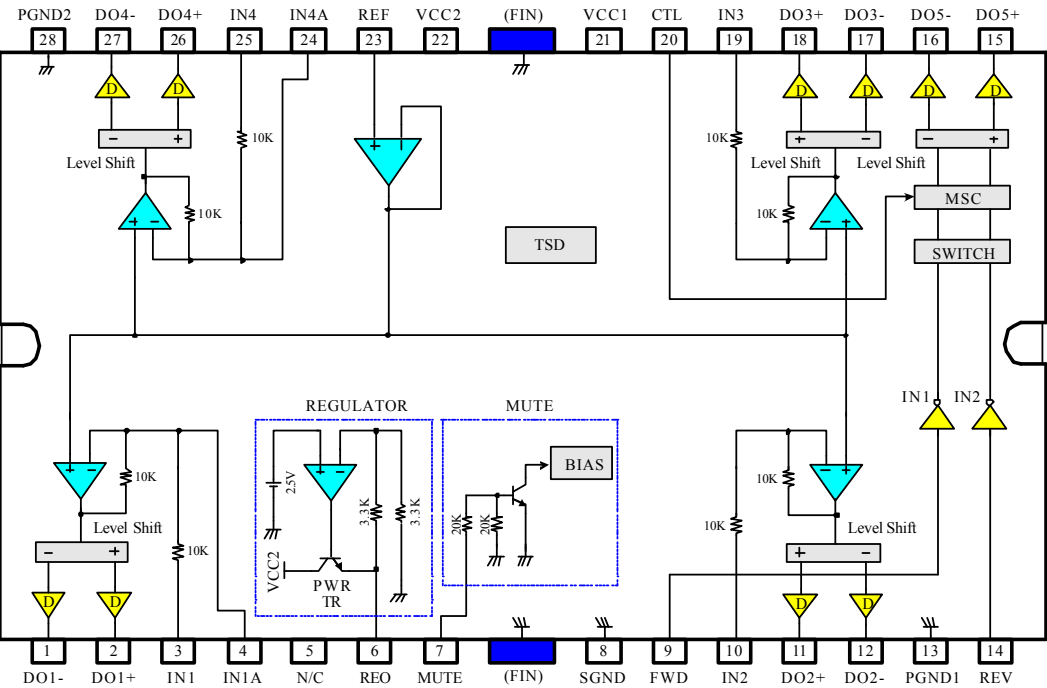
1.5 I/F : 1.5Vdigital input/output pin.

3 I/F : 3 V digital input/output pin.

IP4001CR (CD : IC81)



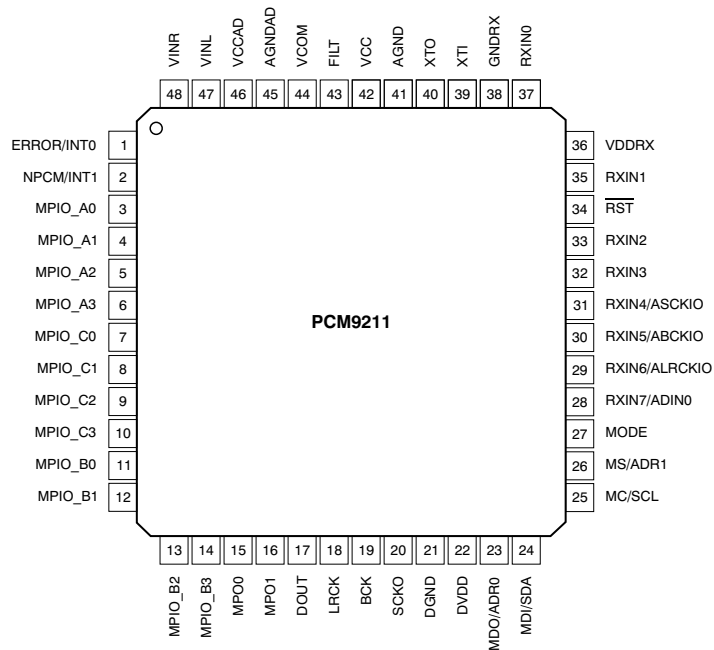
IP4001CR Block Diagram



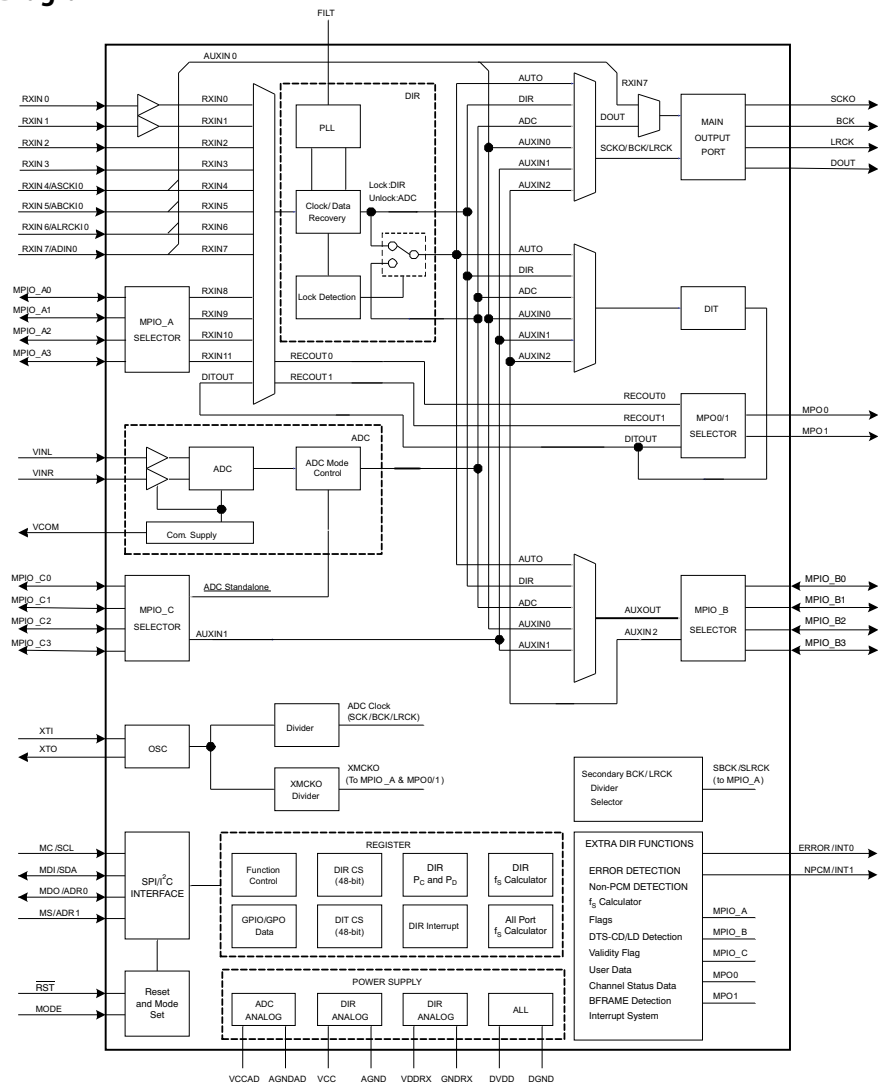
IP4001CR Pin Discriptions

NO	SYMBOL	I/O	DESCRIPTION	NO	SYMBOL	I/O	DESCRIPTION
1	DO1-	O	CH1 OUTPUT (-)	15	DO5+	O	CH5 OUTPUT (+)
2	DO1+	O	CH1 OUTPUT (+)	16	DO5-	O	CH5 OUTPUT (-)
3	IN1	I	CH1 INPUT 1	17	DO3-	O	CH3 OUTPUT (-)
4	IN1A	I	CH1 INPUT 2	18	DO3+	O	CH3 OUTPUT (+)
5	N / C	-	NO-CONNECTION	19	IN3	I	CH3 INPUT
6	REO	O	REGULATOR OUTPUT	20	CTL	I	CH5 MOTOR SPEED CONTROL
7	MUTE	I	MUTE INPUT	21	VCC1	I	SUPPLY VOLTAGE 1 (CH2,CH3,CH5)
8	SGND	-	SIGNAL GROUND	22	VCC2	I	SUPPLY VOLTAGE 2 (CH1,CH4,SIGNAL,REG)
9	FWD	I	CH5 INPUT 1	23	REF	I	CH BIAS INPUT
10	IN2	I	CH2 INPUT	24	IN4A	I	CH4 INPUT 1
11	DO2+	O	CH2 OUTPUT (+)	25	IN4	I	CH4 INPUT 2
12	DO2-	O	CH2 OUTPUT (-)	26	DO4+	O	CH4 OUTPUT (+)
13	PGND1	-	POWER GROUND 1	27	DO4-	O	CH4 OUTPUT (-)
14	REV	I	CH5 INPUT 2	28	PGND2	-	POWER GROUND 2

PCM9211 (MAIN : IC22)



PCM9211 Block Diagram



PCM9211 Pin Discriptions

PIN				DESCRIPTION
NO.	NAME	I/O	5-V TOLERANT	
1	ERROR/INT0	O	No	DIR Error detection output / Interrupt0 output
2	NPCM/INT1	O	No	DIR Non-PCM detection output / Interrupt1 output
3	MPIO_A0	I/O	Yes	Multipurpose I/O, Group A(1)
4	MPIO_A1	I/O	Yes	Multipurpose I/O, Group A(1)
5	MPIO_A2	I/O	Yes	Multipurpose I/O, Group A(1)
6	MPIO_A3	I/O	Yes	Multipurpose I/O, Group A(1)
7	MPIO_C0	I/O	Yes	Multipurpose I/O, Group C(1)
8	MPIO_C1	I/O	Yes	Multipurpose I/O, Group C(1)
9	MPIO_C2	I/O	Yes	Multipurpose I/O, Group C(1)
10	MPIO_C3	I/O	Yes	Multipurpose I/O, Group C(1)
11	MPIO_B0	I/O	Yes	Multipurpose I/O, Group B(1)
12	MPIO_B1	I/O	Yes	Multipurpose I/O, Group B(1)
13	MPIO_B2	I/O	Yes	Multipurpose I/O, Group B(1)
14	MPIO_B3	I/O	Yes	Multipurpose I/O, Group B(1)
15	MPO0	O	No	Multipurpose output 0
16	MPO1	O	No	Multipurpose output 1
17	DOUT	O	No	Main output port, serial digital audio data output
18	LRCK	O	No	Main output port, LR clock output
19	BCK	O	No	Main output port, Bit clock output
20	SCKO	O	No	Main output port, System clock output
21	DGND	-	-	Ground, for digital
22	DVDD	-	-	Power supply, 3.3 V (typ.), for digital
23	MDO/ADRO	I/O	Yes	Software control I/F, SPI data output / I2C slave address setting0(2)
24	MDI/SDA	I/O	Yes	Software control I/F, SPI data input / I2C data input/output(2) (3)
25	MC/SCL	I	Yes	Software control I/F, SPI clock input / I2C clock input(2)
26	MS/ADR1	I	Yes	Software control I/F, SPI chip select / I2C slave address setting1(2)
27	MODE	I	No	Control mode setting, (see the Serial Control Mode section, Control Mode Pin Setting)
28	RXIN7/ADIN0	I	Yes	Biphase signal, input 7 / AUXIN0, serial audio data input(2)
29	RXIN6/ALRCKI0	I	Yes	Biphase signal, input 6 / AUXIN0, LR clock input(2)
30	RXIN5/ABCKI0	I	Yes	Biphase signal, input 5 / AUXIN0, bit clock input(2)
31	RXIN4/ASCKI0	I	Yes	Biphase signal, input 4 / AUXIN0, system clock input(2)
32	RXIN3	I	Yes	Biphase signal, input 3(2)
33	RXIN2	I	Yes	Biphase signal, input 2(2)
34	RST	I	Yes	Reset Input, active low(2) (4)
35	RXIN1	I	Yes	Biphase signal, input 1, built-in coaxial amplifier
36	VDDR_X	-	-	Power supply, 3.3 V (typ.), for RXIN0 and RXIN1.
37	RXIN0	I	Yes	Biphase signal, input 0, built-in coaxial amplifier
38	GNDRX	-	-	Ground, for RXIN
39	XTI	I	No	Oscillation circuit input for crystal resonator or external XTI clock source input(5)
40	XTO	O	No	Oscillation circuit output for crystal resonator
41	AGND	-	-	Ground, for PLL analog
42	VCC	-	-	Power supply, 3.3 V (typ.), for PLL analog
43	FILT	O	No	External PLL loop filter connection terminal; must connect recommended filter
44	VCOM	O	No	ADC common voltage output; must connect external decoupling capacitor
45	AGNDAD	-	-	Ground, for ADC analog
46	VCCAD	-	-	Power supply, 5.0 V (typ.), for ADC analog
47	VINL	I	No	ADC analog voltage input, left channel
48	VINR	I	No	ADC analog voltage input, right channel

(1) Schmitt trigger input

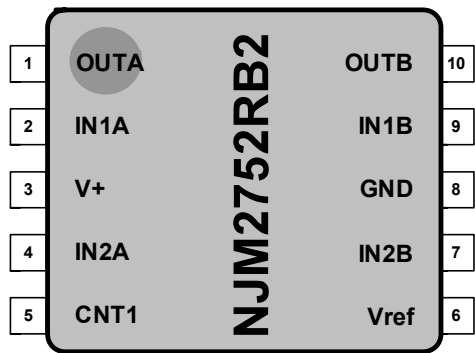
(2) Schmitt trigger input

(3) Open-drain configuration in I2C mode

(4) Onboard pull-down resistor (50 k Ω , typical)

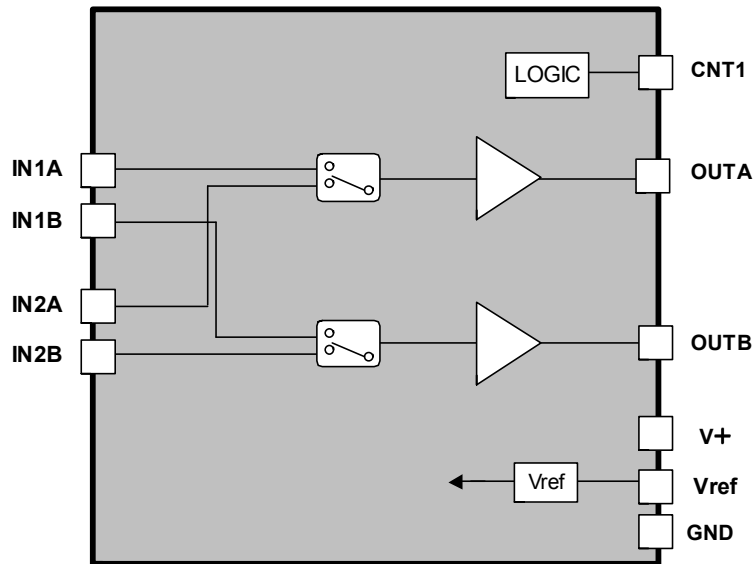
(5) CMOS Schmitt trigger input

TVSP10

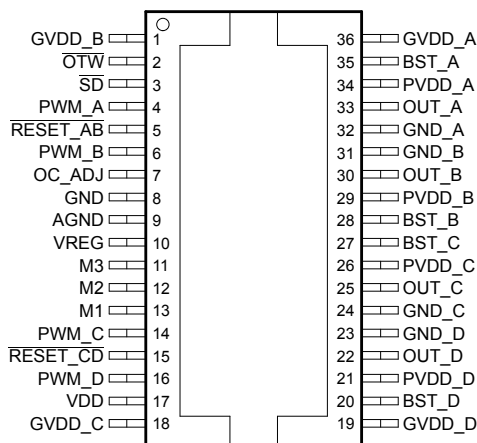


PIN.No.	SYMBOL	FUNCTION	PIN.No.	SYMBOL	FUNCTION
1	OUTA	Ach Output Terminal	6	Vref	Reference Terminal
2	IN1A	Ach Input Terminal1	7	IN2B	Bch Input Terminal2
3	V+	Power Supply Terminal	8	GND	GND Terminal
4	IN2A	Ach Input Terminal2	9	IN1B	Bch Input Terminal1
5	CNT1	Control Switch Terminal	10	OUTB	Bch Output Terminal

NJM2755 Block Diagram



TAS5142DKD (AMP : IC70)

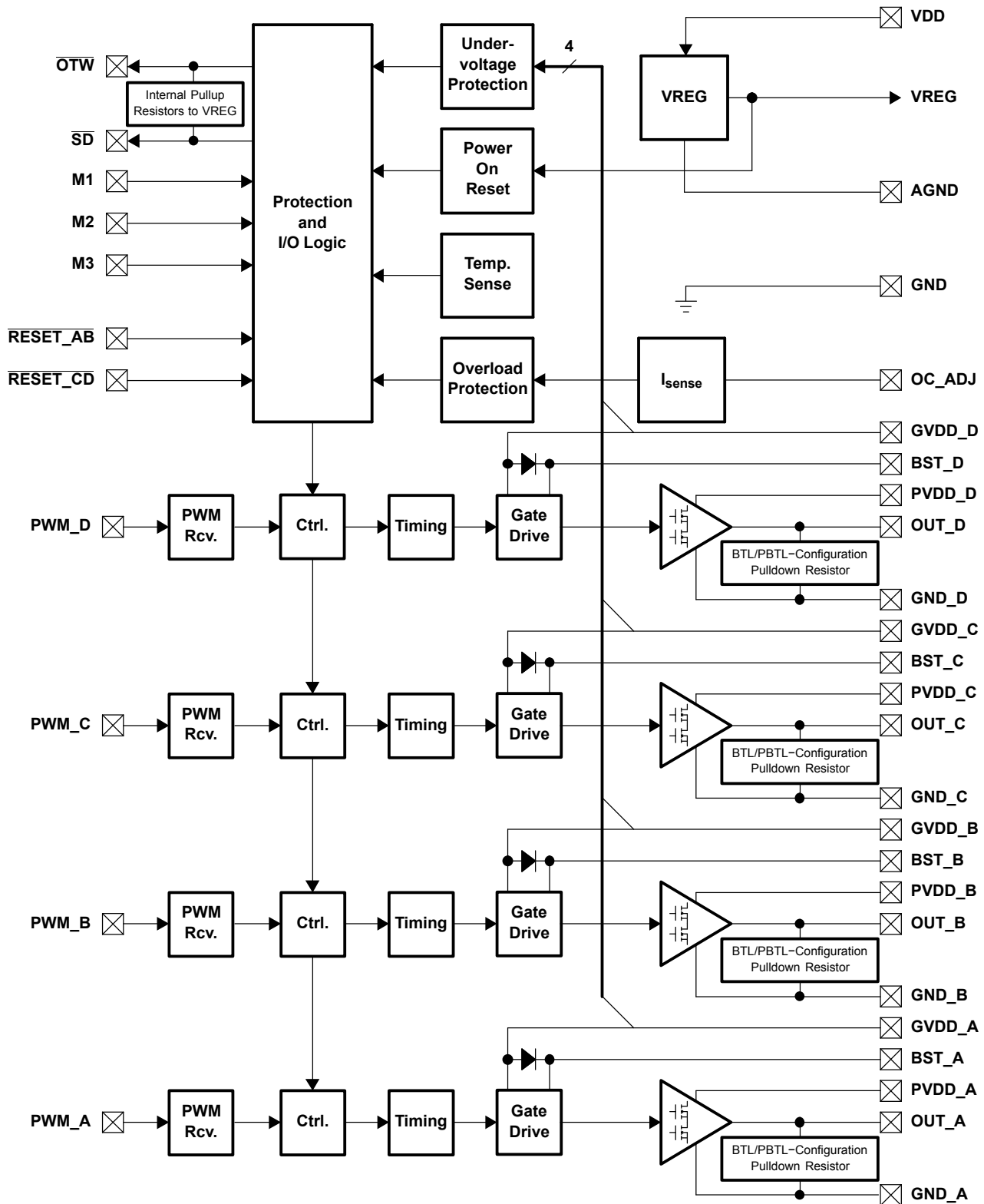


TAS5142 Pin Discriptions

TERMINAL			FUNCTION ⁽¹⁾	DESCRIPTION
NAME	DKD NO.	DDV NO.		
AGND	9	11	P	Analog ground
BST_A	35	43	P	HS bootstrap supply (BST), external capacitor to OUT_A required
BST_B	28	34	P	HS bootstrap supply (BST), external capacitor to OUT_B required
BST_C	27	33	P	HS bootstrap supply (BST), external capacitor to OUT_C required
BST_D	20	24	P	HS bootstrap supply (BST), external capacitor to OUT_D required
GND	8	10	P	Ground
GND_A	32	38	P	Power ground for half-bridge A
GND_B	31	37	P	Power ground for half-bridge B
GND_C	24	30	P	Power ground for half-bridge C
GND_D	23	29	P	Power ground for half-bridge D
GVDD_A	36	44	P	Gate-drive voltage supply requires 0.1-μF capacitor to AGND
GVDD_B	1	1	P	Gate-drive voltage supply requires 0.1-μF capacitor to AGND
GVDD_C	18	22	P	Gate-drive voltage supply requires 0.1-μF capacitor to AGND
GVDD_D	19	23	P	Gate-drive voltage supply requires 0.1-μF capacitor to AGND
M1	13	15	I	Mode selection pin
M2	12	14	I	Mode selection pin
M3	11	13	I	Mode selection pin
NC	–	3, 4, 19, 20, 25, 42	–	No connect. Pins may be grounded.
OC_ADJ	7	9	O	Analog overcurrent programming pin requires resistor to ground
OTW	2	2	O	Overtemperature warning signal, open-drain, active-low
OUT_A	33	39	O	Output, half-bridge A
OUT_B	30	36	O	Output, half-bridge B
OUT_C	25	31	O	Output, half-bridge C
OUT_D	22	28	O	Output, half-bridge D
PVDD_A	34	40, 41	P	Power supply input for half-bridge A requires close decoupling of 0.1-μF capacitor to GND_A.
PVDD_B	29	35	P	Power supply input for half-bridge B requires close decoupling of 0.1-μF capacitor to GND_B.
PVDD_C	26	32	P	Power supply input for half-bridge C requires close decoupling of 0.1-μF capacitor to GND_C.
PVDD_D	21	26, 27	P	Power supply input for half-bridge D requires close decoupling of 0.1-μF capacitor to GND_D.
PWM_A	4	6	I	Input signal for half-bridge A
PWM_B	6	8	I	Input signal for half-bridge B
PWM_C	14	16	I	Input signal for half-bridge C
PWM_D	16	18	I	Input signal for half-bridge D
RESET_AB	5	7	I	Reset signal for half-bridge A and half-bridge B, active-low
RESET_CD	15	17	I	Reset signal for half-bridge C and half-bridge D, active-low
SD	3	5	O	Shutdown signal, open-drain, active-low
VDD	17	21	P	Power supply for digital voltage regulator requires 0.1-μF capacitor to GND.
VREG	10	12	P	Digital regulator supply filter pin requires 0.1-μF capacitor to AGND.

(1) I = input, O = output, P = power

TAS5142 Block Diagram



TAS5558 (MAIN : IC23)

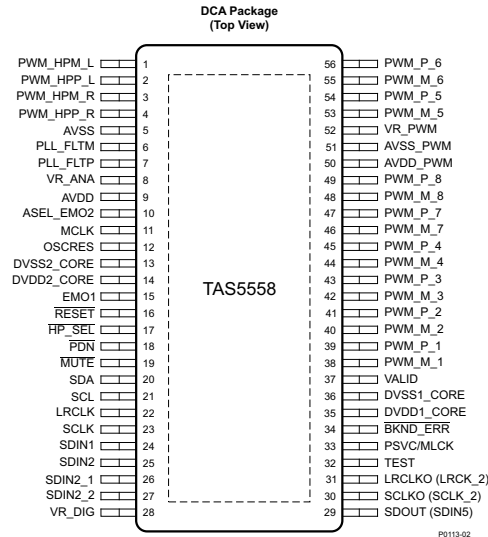


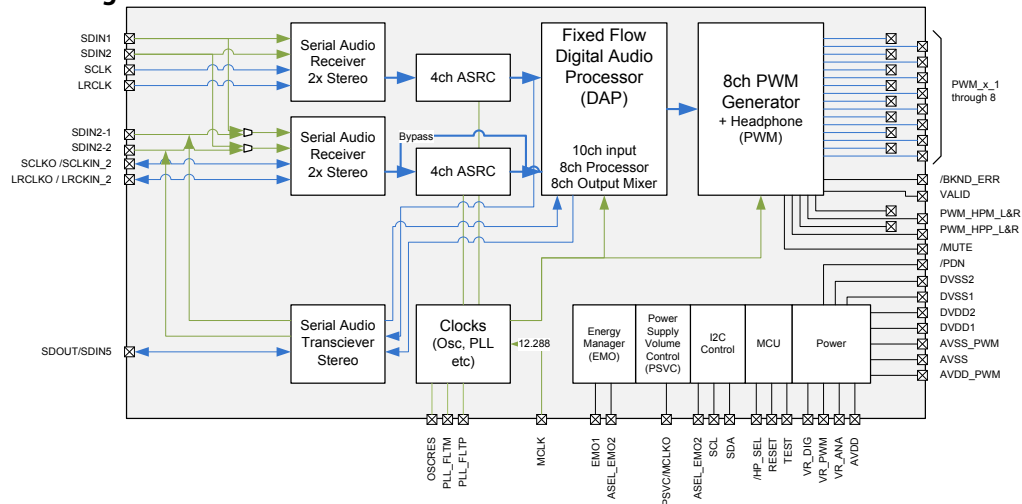
Figure 2-1. TAS5558 Pinout

TAS5558 Pin Discriptions

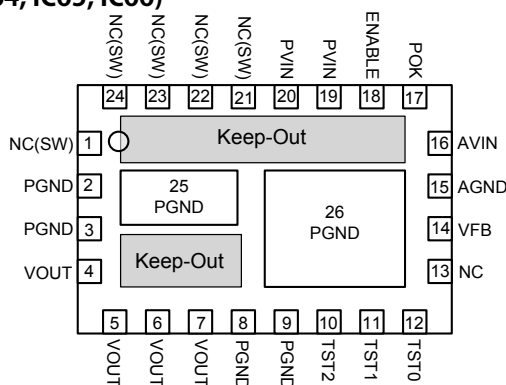
PIN		TYPE ⁽¹⁾	5-V TOLERANT	TERMINATION ⁽²⁾	DESCRIPTION
NAME	NO.				
ASEL_EMO2	10	DIO		Pullup	I2C Address Select. Address will 0X34/0X36 with the value of pin being "0" or "1" during de-assertion of reset. Can be programmed to be an output (as energy manager output for subwoofer)
AVDD	9	P			Analog supply (3.3 V) for PLL.
AVDD_PWM	50	P			3.3-V analog power supply for PWM. This terminal can be connected to the same power source used to drive power terminal DVDD; but to achieve low PLL jitter, this terminal should be bypassed to AVSS_PWM with a 0.1-μF low-ESR capacitor.
AVSS	5	P			Analog ground
AVSS_PWM	51	P			Analog ground for PWM. Must have direct return Cu path to analog 3.3V supply for optimized performance.
BKND_ERR	34	DI		Pullup	Active-low. A back-end error sequence is generated by applying logic low to this terminal. The BKND_ERR results in no change to I2C parameters, with all H-bridge drive signals going to a hard-mute state (Non PWM Switching).
DVDD1	35	P			3.3-V digital power supply. (It is recommended that decoupling capacitors of 0.1 μF and 10 μF be mounted close to this pin).
DVDD2	14	P			3.3-V digital power supply for PWM. (It is recommended that decoupling capacitors of 0.1 μF and 10 μF be mounted close to this pin).
DVSS1	36	P			Digital ground 1
DVSS2	13	P			Digital ground 2
EMO1	15	DO			Energy Manger Output interrupt - Asserted high when threshold is exceeded.
HP_SEL	17	DI	5 V	Pullup	Headphone/speaker selector. When a logic low is applied, the headphone is selected (speakers are off). When a logic high is applied, speakers are selected (headphone is off).
LRCLK	22	DI	5 V	Pulldown	Serial-audio data left/right clock (sampling-rate clock)
LRCLKO / LRCKIN_2	31	DIO	5V	Pulldown	LRCLK for I2S OUT. Can also be used as LRCKIN_2 (I2S input for SDIN2_x and SRC Bank 2)
MLCK	11	DI			3.3-V master clock input. The input frequency of this clock can range from 2 MHz to 50 MHz.
MUTE	19	DI	5 V	Pullup	Soft mute of outputs, active-low (muted signal = a logic low, normal operation = a logic high). The mute control provides a noiseless volume ramp to silence. Releasing mute provides a noiseless ramp to previous volume.
OSCRES	12	DO		1MΩ Resistor	Oscillator resistor (1% tolerance).
PDN	18	DI	5 V	Pullup	Power down, active-low. PDN powers down all logic and stops all clocks whenever a logic low is applied. The I2C parameters are preserved through a power-down cycle, as long as RESET is not active.
PLL_FLTM	6	AIO			PLL negative filter.
PLL_FLTP	7	AIO			PLL positive filter.
PSVC/MCLKO	33	DO			Power-supply volume control PWM output or MCKO for external ADC (SDIN5 Source)
PWM_HPM_L	1	DO			PWM left-channel headphone (differential -)
PWM_HPM_R	3	DO			PWM right-channel headphone (differential -)
PWM_HPP_L	2	DO			PWM left-channel headphone (differential +)
PWM_HPP_R	4	DO			PWM right-channel headphone (differential +)
PWM_M_1	38	DO			PWM 1 output (differential -)
PWM_M_2	40	DO			PWM 2 output (differential -)
PWM_M_3	42	DO			PWM 3 output (differential -)
PWM_M_4	44	DO			PWM 4 output (differential -)
PWM_M_5	53	DO			PWM 5 output (lineout L) (differential -)
PWM_M_6	55	DO			PWM 6 output (lineout R) (differential -)
PWM_M_7	46	DO			PWM 7 output (differential -)
PWM_M_8	48	DO			PWM 8 output (differential -)
PWM_P_1	39	DO			PWM 1 output (differential +)

- (1) Type: A = analog; D = 3.3-V digital; P = power/ground/decoupling; I = input; O = output
 (2) All pullups are 20-μA weak pullups and all pulldowns are 20-μA weak pulldowns. The pullups and pulldowns are included to ensure proper input logic levels if the terminals are left unconnected (pullups → logic-1 input; pulldowns → logic-0 input). Devices that drive inputs with pullups must be able to sink 20 μA while maintaining a logic-0 drive level. Devices that drive inputs with pulldowns must be able to source 20 μA while maintaining a logic-1 drive level.

TAS5558 Block Diagram



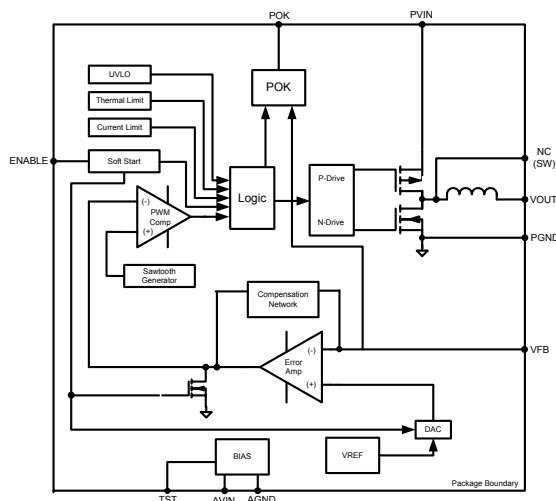
EN5339QI (NETWORK : IC63, IC64, IC65, IC66)



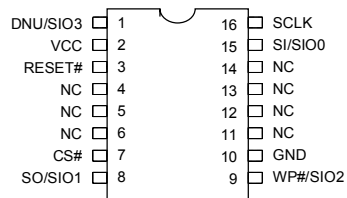
EN5339QI Pin Discriptions

PIN	NAME	FUNCTION
1, 21-24	NC(SW)	NO CONNECT: These pins are internally connected to the common switching node of the internal MOSFETs. They must be soldered to PCB but not be electrically connected to any external signal, ground, or voltage. Failure to follow this guideline may result in device damage.
2-3, 8-9	PGND	Input and output power ground. Connect these pins to the ground electrode of the input and output filter capacitors. See VOUT, PVIN descriptions and Layout Recommendation for more details.
4-7	VOUT	Regulated converter output. Connect to the load and place output filter capacitor(s) between these pins and PGND pins 8 and 9. See layout recommendation for details
10	TST2	Test Pin. For Altera internal use only. Connect to AVIN at all times.
11	TST1	Test Pin. For Altera internal use only. Connect to AVIN at all times.
12	TST0	Test Pin. For Altera internal use only. Connect to AVIN at all times.
13	NC	NO CONNECT: This pin must be soldered to PCB but not electrically connected to any other pin or to any external signal, voltage, or ground. This pin may be connected internally. Failure to follow this guideline may result in device damage.
14	VFB	This is the external feedback input pin. A resistor divider connects from the output to AGND. The mid-point of the resistor divider is connected to VFB. A feed-forward capacitor is required parallel to the upper feedback resistor (R_A). The output voltage regulation is based on the VFB node voltage equal to 0.600V.
15	AGND	The quiet ground for the control circuits. Connect to the ground plane with a via right next to the pin.
16	AVIN	Analog input voltage for the control circuits. Connect this pin to the input power supply (PVIN) at a quiet point. Decouple with a 1uF capacitor to AGND.
17	POK	POK is an open drain output. Refer to Power OK section for details. Leave POK open if unused.
18	ENABLE	Output Enable. A logic high level on this pin enables the output and initiates a soft-start. A logic low signal disables the output and discharges the output to GND. This pin must not be left floating.
19-20	PVIN	Input power supply. Connect to input power supply and place input filter capacitor(s) between these pins and PGND pins 2 to 3.
25,26	PGND	Not a perimeter pin. Device thermal pad to be connected to the system GND plane for heat-sinking purposes. See Layout Recommendation section.

EN5339QI Block Diagram



MX25L25635FMI (NETWORK : IC67)



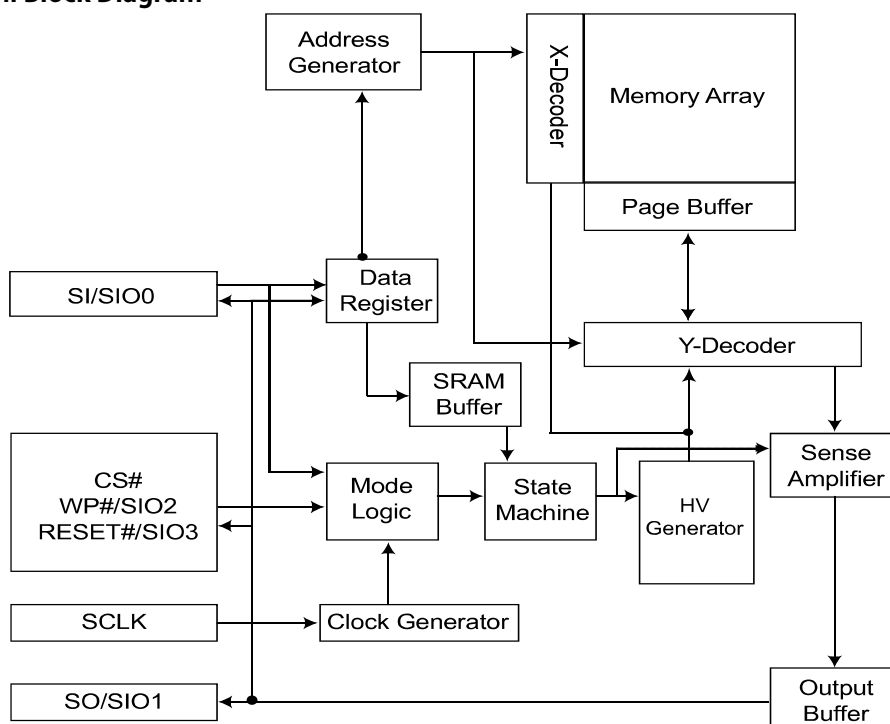
MX25L25635FMI Pin Discriptions

SYMBOL	DESCRIPTION
CS#	Chip Select
SI/SIO0	Serial Data Input (for 1 x I/O)/ Serial Data Input & Output (for 2xI/O or 4xI/O read mode)
SO/SIO1	Serial Data Output (for 1 x I/O)/ Serial Data Input & Output (for 2xI/O or 4xI/O read mode)
SCLK	Clock Input
WP#/SIO2	Write protection: connect to GND or Serial Data Input & Output (for 4xI/O read mode)
RESET#/SIO3	Hardware Reset Pin Active low or Serial Data Input & Output (for 4xI/O read mode)
DNU/SIO3	Do not use or Serial Data Input & Output (for 4xI/O read mode)
RESET#*	Hardware Reset Pin Active low
VCC	+ 3V Power Supply
GND	Ground
NC	No Connection

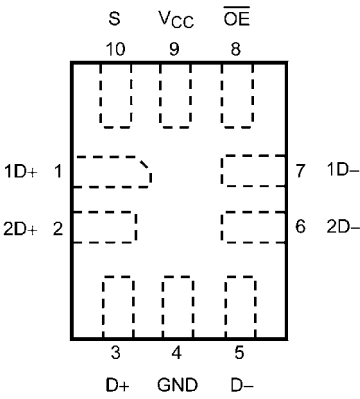
Notes:

1. RESET# pin has internal pull up.
2. When using 1I/O or 2I/O (QE bit not enable), the DNU/SIO3 pin of 16SOP can not connect to GND. Recommend to connect this pin to VCC or floating.

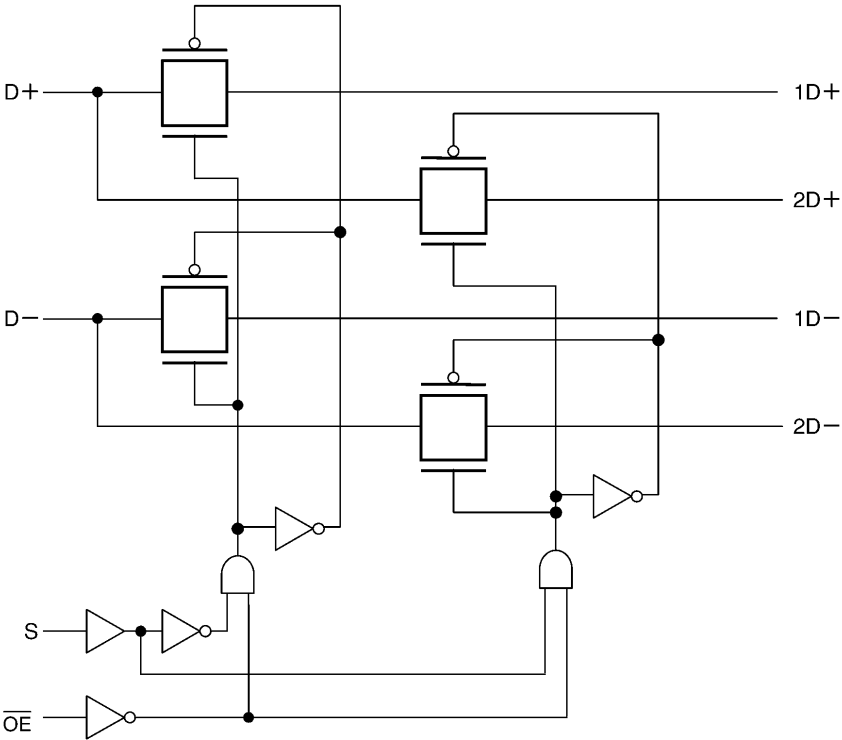
MX25L25635FMI Block Diagram



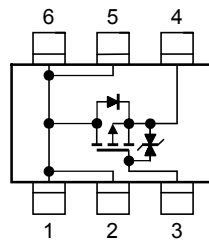
TC7USB40MU (NETWORK : IC62)



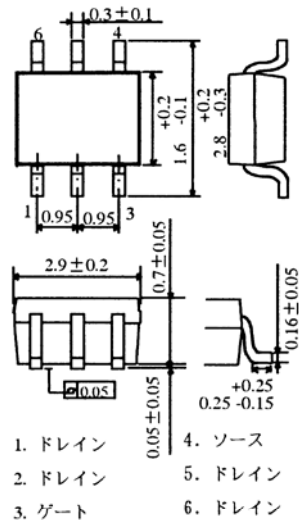
TC7USB40MU Block Diagram



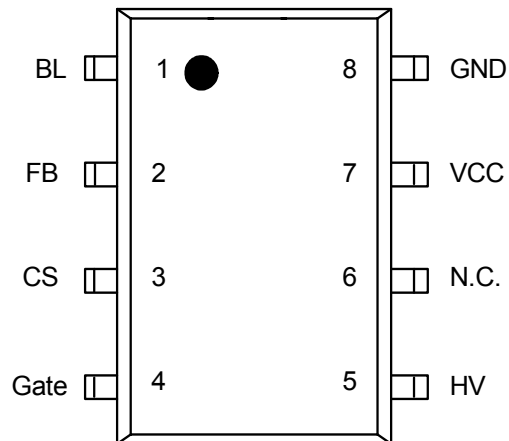
TPC6111 (NETWORK : Q681)



TPC6111 Pin Discriptions



ICE3BS03LJG (SMPS : IC91)

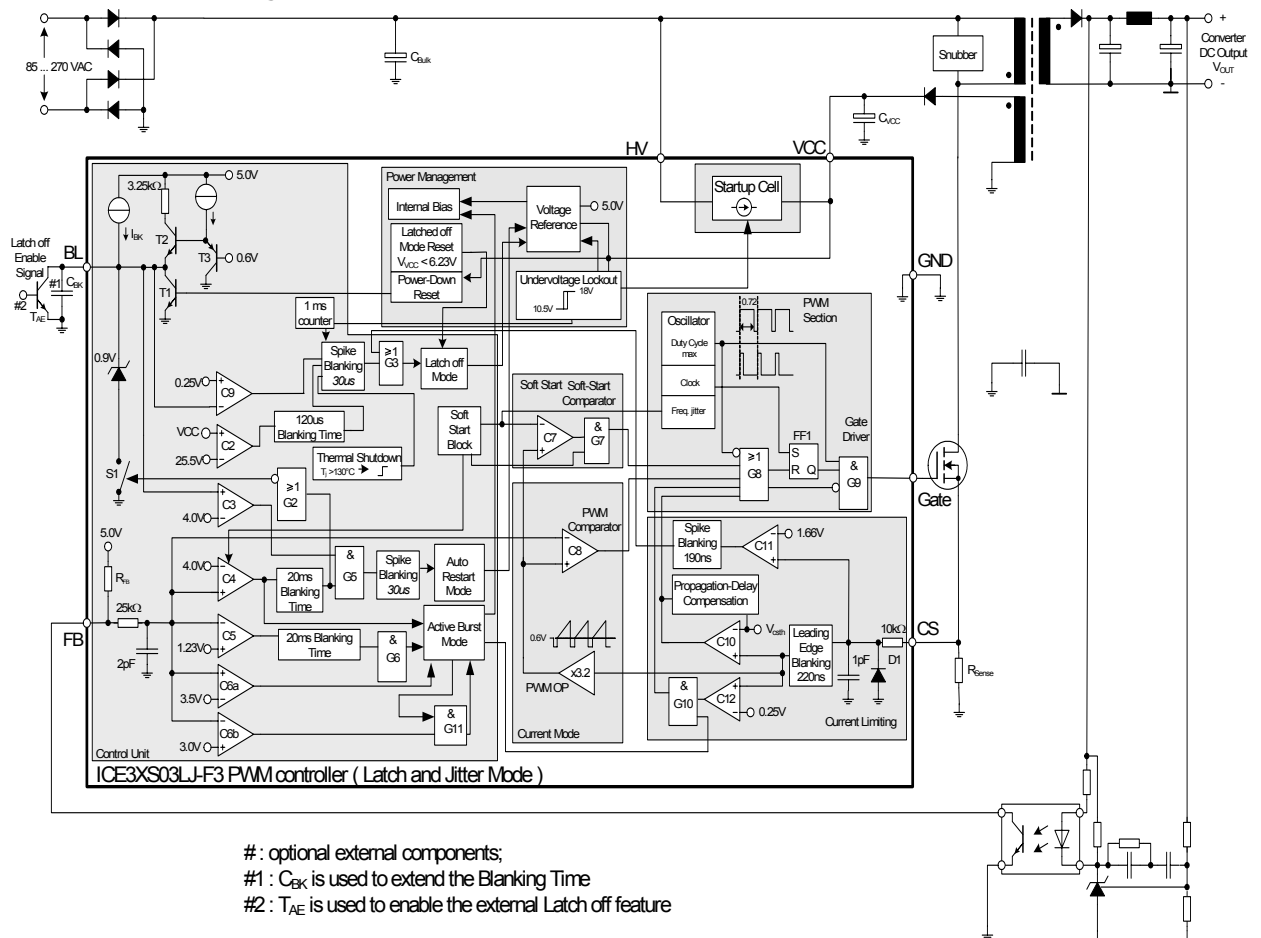


ICE3BS03LJG Pin Discriptions

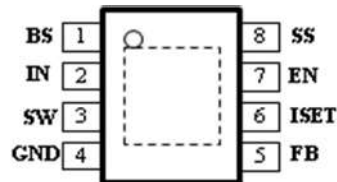
Pin	Symbol	Function
1	BL	extended Blanking and Latch off enable
2	FB	Feedback
3	CS	Current Sense
4	Gate	Gate driver output
5	HV	High Voltage input
6	NC	Not connected
7	VCC	Controller Supply Voltage
8	GND	Controller Ground

(1) at $T_J=110^{\circ}\text{C}$

ICE3BS03LJG Block Diagram



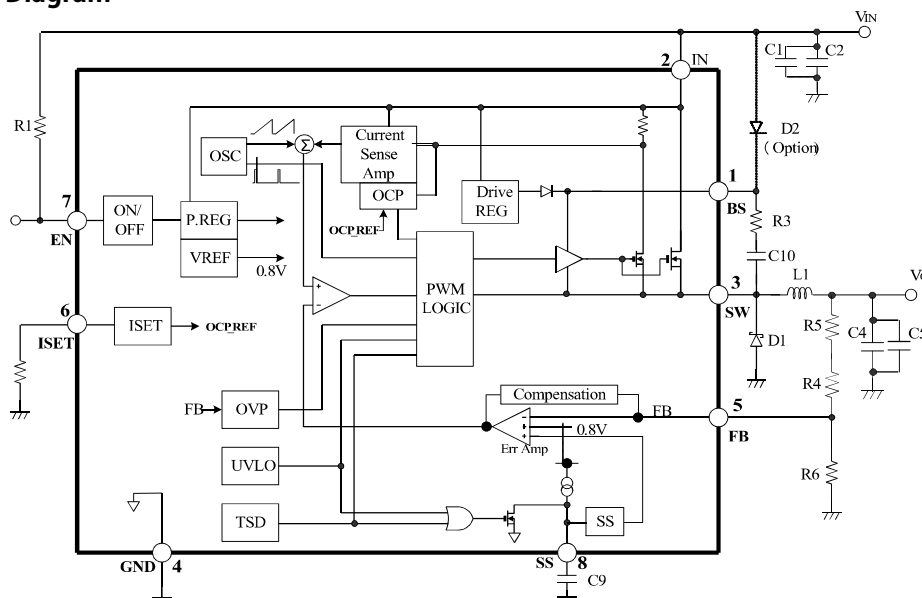
NR111E (SMPS : IC95)



NR111E Pin Discriptions

Pin No.	Symbol	Description
1	BS	High-side Boost input. BS supplies the drive for High-side Nch-MOSFET switch. Connect a capacitor and a resistor between SW to BS.
2	IN	Power input. IN supplies the power to the IC as well as the regulator switches
3	SW	Power switching output. SW supplies power to the output. Connect the LC filter from SW to the output. Note that a capacitor is required from SW to BS to supply the power the High switch
4	GND	Ground Connect the exposed pad to Pin No.4
5	FB	Feedback input Pin to compare Reference Voltage. The feedback threshold is 0.8V. To set the output voltage, FB Pin is required to connect between resistive divider R4 and R6.
6	ISET	Adjust Pin of OCP starting current OCP starting current can be adjusted by connecting a resistor to ISET Pin. In the case of using at Maximum Io, ISET Pin is required to connect to GND.
7	EN	Enable input. Drive EN Pin high to turn on the regulator, low to turn it off.
8	SS	Soft-Start control input. To set the soft-start period, connect to a capacitor between GND.

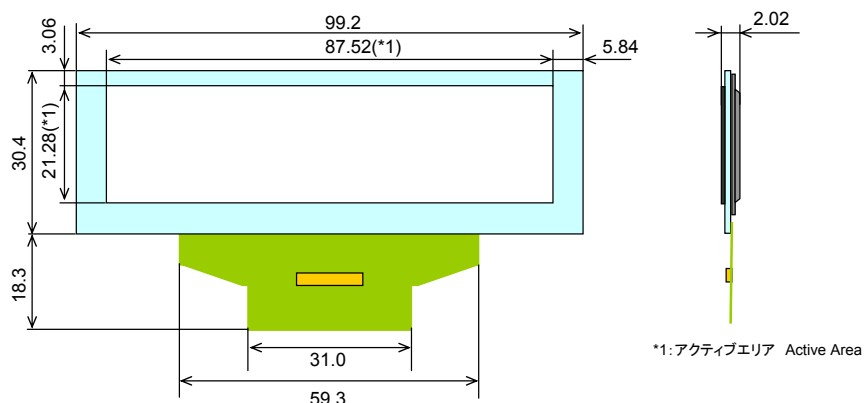
NR111E Block Diagram



2. DISPLAY

S020-MXS4035A-3 (FRONT : WF12)

端子番号 Pin No.	端子名 Pin Name	入出力 I/O	機能 Function
1	VSS	P	グラウンド GND
2	VCC	P	ドライブ系電源電圧 Drive System Power Voltage
3	VCOMH	P	陰極電源 Power Supply for Cathode Driver
4	VLSS	P	アナロググラウンド Analog System Ground
5	CLS	I	VDDIO接続 Connect to VDDIO
6	D7	I	データバス Data Bus
7	D6	I	データバス Data Bus
8	D5	I	データバス Data Bus
9	D4	I	データバス Data Bus
10	D3	I	データバス Data Bus
11	D2	I	データバス Data Bus
12	D1(SDIN)	I	データバス(シリアルデータ) Data Bus(Serial Data)
13	D0(SCLK)	I	データバス(シリアルクロック) Data Bus(Serial Clock)
14	RD#	I	読み出し Read
15	WR#	I	書き込み Write
16	BS0	I	インターフェース選択端子
17	BSI	I	Select MCU Bus Interface Setting
18	D/C#	I	データ/コマンド選択 Select Data/Command
19	CS#	I	チップセレクト Chip Select
20	RES#	I	リセット Reset
21	VSS	P	グラウンド GND
22	CL	I	VSS接続 Connect to VSS
23	IREF	O	基準電流 Reference Current Setting
24	NC	-	
25	VDDIO	P	インターフェイス系電源電圧 Interface System Power Voltage
26	VDD	O	内部ロジック電源 Internal Logic Power
27	VCI	P	ロジック系電源 Logic System Power Voltage
28	VSL	P	陽極基準電位 Anode Reference Voltage
29	VLSS	P	アナロググラウンド Analog System Ground
30	VCC	P	ドライブ系電源電圧 Drive System Power Voltage



FRONT PCB ASS'Y

※Parts indicated by "nsp" on this table cannot be supplied.

※The parts listed below are only for maintenance. Therefore they might differ from the parts used in the unit in appearances or dimensions.

NOTE: The symbols in the column Remarks indicate the following destinations.

E3 : U.S.A. & Canada model E2 : Europe model E1C : China model E1 : Asia model JP : Japan model

BK : Black model SP : Premium Silver model WT : White model

REF No.	Part No.	Part Name	Remarks	Q'ty	New	Ver
SEMICONDUCTORS GROUP						
D101	nsp	DIODE , ZENER(CHIP,2.7V)		HVDUDZS2.7BSR	1	
D102	943263100860M	L.E.D.(GREEN/RED 3P)		CVDWEJ3290W-R2H	1	
D103,104	943209001080S	DIODE , CHIP , SWITCHING		CVD1SS355T	2	
D105	943263003130S	L.E.D , WHITE		CVD1L0345W31BOC	1	
Q101-104	943213500160S	T.R.RT1N237C(2.2K-47K)		CVTRT1N237C	4	
Q108	943215500020S	T.R.RT1P141C(10K-10K)		CVTRT1P141C	1	
RESISTOR GROUP						
R105,106	nsp	RES, CHIP(1608/5%/150ohm)		CRJ10DJ151T	2	
R107	nsp	RES, CHIP(1608/5%/180ohm)		CRJ10DJ181T	1	
R108	nsp	RES, CHIP(1608/5%/270ohm)		CRJ10DJ271T	1	
R109	nsp	RES, CHIP(1608/5%/390ohm)		CRJ10DJ391T	1	
R110	nsp	RES, CHIP(1608/5%/150ohm)		CRJ10DJ151T	1	
R111	nsp	RES, CHIP(1608/5%/180ohm)		CRJ10DJ181T	1	
R115	nsp	RES, CHIP(1608/5%/0ohm)		CRJ10DJ0R0T	1	
R122	nsp	RES, CHIP(1608/5%/100ohm)		CRJ10DJ101T	1	
R123	nsp	RES, CHIP(1608/5%/10Kohm)		CRJ10DJ103T	1	
R125	nsp	RES, CHIP(1608/5%/1Mohm)		CRJ10DJ105T	1	
R126	nsp	RES, CHIP(1608/5%/0ohm)		CRJ10DJ0R0T	1	
R131-133	nsp	RES, CHIP(1608/5%/1Kohm)		CRJ10DJ102T	3	
R134	nsp	RES, CHIP(1608/5%/0ohm)		CRJ10DJ0R0T	1	
R135	nsp	RES, CHIP(1608/5%/100ohm)		CRJ10DJ101T	1	
R136	nsp	RES, CHIP(1608/5%/10ohm)		CRJ10DJ100T	1	
R137	nsp	RES, CHIP(1608/5%/150ohm)		CRJ10DJ151T	1	
R138	nsp	RES, CHIP(1608/5%/0ohm)		CRJ10DJ0R0T	1	
R139	nsp	RES, CHIP(1608/5%/100ohm)		CRJ10DJ101T	1	
R140	nsp	RES, CHIP(1608/5%/0ohm)		CRJ10DJ0R0T	1	
R141	nsp	RES, CHIP(1608/5%/560ohm)		CRJ10DJ561T	1	
R152	nsp	RES, CHIP(1608/5%/0ohm)		CRJ10DJ0R0T	1	
R154	nsp	RES, CHIP(1608/5%/0ohm)		CRJ10DJ0R0T	1	
R156	nsp	RES, CHIP(1608/5%/47Kohm)		CRJ10DJ473T	1	
R161-165	nsp	RES, CHIP(1608/5%/33ohm)		CRJ10DJ330T	5	
R166,167	nsp	RES, CHIP(1608/5%/0ohm)		CRJ10DJ0R0T	2	
R181-190	nsp	RES, CHIP(1608/5%/33ohm)		CRJ10DJ330T	10	
CAPACITORS GROUP						
C102,103	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG		CCUS1H103KCS	2	
C104,105	943134502030D	CAP, ELECT(50V/10uF)		CCEA1HH100TC	2	
C111	nsp	CAP, CHIP(1608, 50V/1000pF, X7R) SAMSUNG		CCUS1H102KCS	1	
C112	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG		CCUS1H103KCS	1	
C113	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG		CCUS1H104KCS	1	
C114	nsp	CAP, CHIP(1608, 50V/1000pF, X7R) SAMSUNG		CCUS1H102KCS	1	
C115	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG		CCUS1H103KCS	1	
C116-119	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG		CCUS1H104KCS	4	
C120	943134010670S	CAP, ELECT(16V/47uF)-S		CCEA1CK5470T	1	
C121-123	nsp	CAP, CHIP(1608, 50V/47pF, C0G) SAMSUNG		CCUS1H470JAS	3	
C124	nsp	CAP, CHIP(1608, 50V/1000pF, X7R) SAMSUNG		CCUS1H102KCS	1	
C125	nsp	CAP, CHIP(1608, 10V/1uF, X7R, X7S) SAMSUNG		CCUS1A105KCS	1	
C126	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG		CCUS1H104KCS	1	
C127	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG		CCUS1H103KCS	1	
C128	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG		CCUS1H104KCS	1	
C130,131	nsp	CAP, CHIP(2012, 25V/4.7uF)		CCUC1E475KC	2	
C132	943134503420D	CAP, ELECT(35V/10uF)-S		CCEA1VK5100T	1	*
C133	nsp	CAP, CHIP(1608, 10V/1uF, X7R, X7S) SAMSUNG		CCUS1A105KCS	1	
C134	nsp	CAP, CHIP(2012, 50V/1uF, X7R, X7S) SAMSUNG		CCUC1H105KCS	1	
C135	nsp	CAP, CHIP(2012, 25V/4.7uF)		CCUC1E475KC	1	
C136	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG		CCUS1H104KCS	1	
C137	943134503420D	CAP, ELECT(35V/10uF)-S		CCEA1VK5100T	1	*
C139	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG		CCUS1H103KCS	1	
C141	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG		CCUS1H103KCS	1	
C142-144	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG		CCUS1H104KCS	3	
C151	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG		CCUS1H103KCS	1	
C152-154	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG		CCUS1H104KCS	3	
C157,158	nsp	CAP, CHIP(1608, 50V/0.027uF, X7R) SAMSUNG		CCUS1H273KCS	2	
C159	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG		CCUS1H103KCS	1	
C161-166	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG		CCUS1H104KCS	6	
C167	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG		CCUS1H103KCS	1	
C168	nsp	CAP, CHIP(1608, 50V/1000pF, X7R) SAMSUNG		CCUS1H102KCS	1	
C172	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG		CCUS1H104KCS	1	
C173	943134503350D	CAP, ELECT(10V/470uF)		CCEA1AH471TC	1	*
C174	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG		CCUS1H104KCS	1	
C175	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG		CCUS1H103KCS	1	
C176	nsp	CAP, CHIP(1608, 50V/1000pF, X7R) SAMSUNG		CCUS1H102KCS	1	
C180	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG		CCUS1H104KCS	1	
C181	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG		CCUS1H103KCS	1	
C182	nsp	CAP, CHIP(1608, 50V/1000pF, X7R) SAMSUNG		CCUS1H102KCS	1	
C183	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG		CCUS1H103KCS	1	
C184	943134502030D	CAP, ELECT(50V/10uF)		CCEA1HH100TC	1	
C185	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG		CCUS1H104KCS	1	
C186	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG		CCUS1H103KCS	1	
C187	943134502030D	CAP, ELECT(50V/10uF)		CCEA1HH100TC	1	
C188	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG		CCUS1H104KCS	1	
C189	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG		CCUS1H103KCS	1	
OTHER PARTS GROUP						
BK20	nsp	BRACKET , PCB		CMD1A569-V1	1	
CN16	nsp	LOCKING TYPE , STRAIGHT WAFER , 2mm		CJP05GI236ZW	1	
GND1,2	nsp	PLATE , EARTH(TRONIC ELECTRONICS)		CJT1A026	2	
JK11	943643102870S	JACK , HEADPHONE (SILVER)		CJ2D003Z	1	
JK12,13	943643102630M	MODULE , OPTICAL(RX 25MHz)		CJSJSR2124-00-BB	2	
L101,102	nsp	FERRITE CHIP BEAD(2012/120R)		CLZBLM21AG121SN	2	
L103-105	nsp	FERRITE CHIP BEAD(4516/60R)		CLZ9Z014Z	3	
L106,107	nsp	COIL , CHIP(10uH, 2012)		CLQ08E100KRZ	2	
L110-112	nsp	FERRITE CHIP BEAD(4516/60R)		CLZ9Z014Z	3	
L113-115	nsp	FERRITE , CHIP BEAD(60ohm, 2012)		CLZ9R001Z	3	
PF13	nsp	WAFER, FFC(5P-1mm, ANGLE)		CJP05GB113ZY	1	
RC11	943262010290S	SENSOR , REMOTE/U		CRVKSM603TH5B	1	
S101-109	943662101030D	SW, TACT (DIP, DARK GRAY, H=5mm, 1.57N)		CST1A0382T	9	*
S112	943662101030D	SW, TACT (DIP, DARK GRAY, H=5mm, 1.57N)		CST1A0382T	1	*
SW11	943662100180M	SW, TACT, VERTICAL (3.3mm)		CST1A0322T	1	
TM11	943183100530D	TUNER(EUR) , FM, AM, RDS (S/LAB)	E2, E1C	CNVMW104MV1S63	1	*
TM11	943183100540D	TUNER(USA/JAPAN) , FM(SCREW : F TYPE), AM (S/LAB)	JP	CNVMW004MV1S63	1	*
WF11	nsp	WAFER, FFC(27P-1.25mm, ANGLE)		CJP27GB116ZY	1	
WF12	nsp	WAFER, FFC/FFC(30P, 1mm PITCH, ANGLE)		CJP30GB305ZN	1	
WF13	nsp	WAFER, FFC(5P-1mm, ANGLE)		CJP05GB113ZY	1	
WF14	nsp	WAFER, FFC(4P-1mm, ANGLE)		CJP04GB113ZY	1	
WF15	nsp	WAFER, FFC(11P-1mm, STRAIGHT)		CJP11GA117ZY	1	
★	963179100040S	OLED MODULE (MXS4035-A)		CFLMXS4035-A	1	

MAIN For E2,JP PCB ASS'Y

※Parts indicated by "nsp"on this table cannot be supplied.

※The parts listed below are only for maintenance. Therefore they might differ from the parts used in the unit in appearances or dimensions

NOTE:The symbols in the column Remarks indicate the following destinations.

E3 : U.S.A. & Canada model E2 : Europe model E1C : China model E1 : Asia model JP : Japan model

BK : Black model SP : Premium Silver model WT : White model

REF No.	Part No.	Part Name	Remarks	Q'ty	New	Ver
SEMICONDUCTORS GROUP						
D201-210	943209001080S	DIODE , CHIP , SWITCHING	E2, JP	CVD1SS355T	10	
D212,213	943209001080S	DIODE , CHIP , SWITCHING	E2, JP	CVD1SS355T	2	
D214,215	90M-HD201820R	DIODE, SCHOTTKY BARRIER	E2, JP	HVDRB160L60TE25	2	
D216,217	943209001080S	DIODE , CHIP , SWITCHING	E2, JP	CVD1SS355T	2	
D218	90M-HD201820R	DIODE, SCHOTTKY BARRIER	E2, JP	HVDRB160L60TE25	1	
D219	943209001080S	DIODE , CHIP , SWITCHING	E2, JP	CVD1SS355T	1	
D601-604	943209001080S	DIODE , CHIP , SWITCHING	E2, JP	CVD1SS355T	4	
IC20	943239101590D	I.C , Audio Switch Stereo(TVSP10)	E2, JP	CVINJM2752RB2	1	*
IC21	943234009290S	I.C , RESET 2.4V (200ms,C-MOS,SOT23-5P)	E2, JP	CVIS80124CLMCJJI	1	
IC22	943236101350D	I.C , DIR/DIT(WITH ADC,LQFP-48P)	E2, JP	CVIPC9211PTR	1	
IC23	943239101600D	I.C , PWM PROCESSOR(HTSSOP-56P)	E2, JP	CVITAS5558DCAR	1	*
IC24	943235100670M	I.C , OP AMP	E2, JP	HVINJM4556AMTE1	1	
IC25	00MHC10102090	I.C , OP AMP (JRC)	E2, JP	HVINJM2068MDTE1	1	
IC26	943239101500S	I.C , EEPROM(128KBIT,SOP-8P)	E2, JP	CVIR1EX24128BSA	1	
IC27	943239101610D	I.C, REGULATOR(3.3V, TO-252-5, Io=1.5A, LDO)	E2, JP	CVINJM2857DL3-33	1	*
IC28	-	I.C, CPU(2M/PLQP0144KA-A)	E2, JP	CVIR5F56108VNF	1	
IC28	943243102690S	I.C,MAIN MCU(DRA-N4,RCD-N9),2M/PLQP0144KA-A See Procedure after Replacing the Microprocessor, etc.	E2, JP	CVIANAM2033CR	1	*
IC29	943239010400S	I.C, REGULATOR(3.3V/TO-252)	E2, JP	CVINJM2845DL133	1	
IC60	943239001120S	IC , CURRENT LIMITER	E2, JP	CVIRT9702APB	1	
IC61	23671011050AS	I.C , IPOD AUTHENTICATION FROM D&M	E2, JP	CVI23671011050AS	1	
IC62	943606502150M	I.C , USB SWITCH(DUAL SPDT,UQFN10)	E2, JP	CVITC7USB40MU	1	
IC63-66	943239101070S	I.C , DC-DC CONVERTER (3A, QFN T&R-24P)	E2, JP	CVIEN5339QI	4	
IC67	24681009260AS	I.C , SERIAL FLASH(256M,SOP-16)	E2, JP	CVIMX25L25635FMI	1	*
Q200,201	943215500020S	T.R,RT1P141C(10K-10K)	E2, JP	CVTRT1P141C	2	
Q203	943215500020S	T.R,RT1P141C(10K-10K)	E2, JP	CVTRT1P141C	1	
Q204,205	943216500020S	T.R,RT1N141C(10K-10K)	E2, JP	CVTRT1N141C	2	
Q206,207	963216500060S	T.R,RT1N144C(10K-47K)	E2, JP	CVTRT1N144C	2	
Q208	943215500020S	T.R,RT1P141C(10K-10K)	E2, JP	CVTRT1P141C	1	
Q211-216	00D9430072502	T.R , CHIP , SOT-23	E2, JP	HVTKT2875B	6	
Q218	943222500300S	FET, BSS138BK, N-CH, TO-236AB, NXP	E2, JP	CVTBSS138BK	1	
Q219-221	943215500020S	T.R,RT1P141C(10K-10K)	E2, JP	CVTRT1P141C	3	
Q222	943229500160D	FET, FDN360P, P-CH, SOT-23, FAIRCHILD	E2, JP	CVTFDN360P	1	*
Q223-226	943216500020S	T.R,RT1N141C(10K-10K)	E2, JP	CVTRT1N141C	4	
Q228-231	943216500020S	T.R,RT1N141C(10K-10K)	E2, JP	CVTRT1N141C	4	
Q232	943215500020S	T.R,RT1P141C(10K-10K)	E2, JP	CVTRT1P141C	1	
Q233	943216500020S	T.R,RT1N141C(10K-10K)	E2, JP	CVTRT1N141C	1	
Q680	943216500020S	T.R,RT1N141C(10K-10K)	E2, JP	CVTRT1N141C	1	
Q681	943229500020S	MOSFET,TPC6111(P-CH,U-MOSV)	E2, JP	CVTTPC6111	1	
RESISTOR GROUP						
R200-203	nsp	RES, CHIP(1005/5%/33ohm)	E2, JP	CRJ06I330T	4	
R204-209	nsp	RES, CHIP(1005/5%/0ohm)	E2, JP	CRJ06I30R0T	6	
R210	nsp	RES, CHIP(1005/5%/4.7Kohm)	E2, JP	CRJ06I472T	1	
R211	nsp	RES, CHIP(1005/5%/10Kohm)	E2, JP	CRJ06I103T	1	
R212,213	nsp	RES, CHIP(1005/5%/33ohm)	E2, JP	CRJ06I330T	2	
R214	nsp	RES, CHIP(1005/5%/22Kohm)	E2, JP	CRJ06I223T	1	
R215-220	nsp	RES, CHIP(1005/5%/33ohm)	E2, JP	CRJ06I330T	6	
R221-229	nsp	RES, CHIP(1005/5%/100Kohm)	E2, JP	CRJ06I104T	9	
R230	nsp	RES, CHIP(1005/5%/10Kohm)	E2, JP	CRJ06I103T	1	
R231	nsp	RES, CHIP(1005/5%/15Kohm)	E2, JP	CRJ06I153T	1	
R232	nsp	RES, CHIP(1005/5%/10Kohm)	E2, JP	CRJ06I103T	1	
R235	nsp	RES, CHIP(2012/5%/18ohm)	E2, JP	CRJ18AJ180T	1	
R236-238	nsp	RES, CHIP(1005/5%/10Kohm)	E2, JP	CRJ06I103T	3	
R240,241	nsp	RES, CHIP(1005/5%/10Kohm)	E2, JP	CRJ06I103T	2	
R243,244	nsp	RES, CHIP(1005/5%/10Kohm)	E2, JP	CRJ06I103T	2	
R246-254	nsp	RES, CHIP(1005/5%/10Kohm)	E2, JP	CRJ06I103T	9	
R256	nsp	RES, CHIP(1005/5%/10Kohm)	E2, JP	CRJ06I103T	1	
R257	nsp	RES, CHIP(1005/5%/10Kohm)	JP	CRJ06I103T	1	
R258	nsp	RES, CHIP(1005/5%/10Kohm)	E2, JP	CRJ06I103T	1	
R260-262	nsp	RES, CHIP(1005/5%/10Kohm)	E2, JP	CRJ06I103T	3	
R263	nsp	RES, CHIP(1608/5%/10Kohm)	E2, JP	CRJ10DJ103T	1	
R264,265	nsp	RES, CHIP(1005/5%/1Kohm)	E2, JP	CRJ06I102T	2	
R267	nsp	RES, CHIP(1005/5%/100ohm)	E2, JP	CRJ06I101T	1	
R269-271	nsp	RES, CHIP(1005/5%/0ohm)	E2, JP	CRJ06I30R0T	3	
R273-277	nsp	RES, CHIP(1005/5%/0ohm)	E2, JP	CRJ06I30R0T	5	
R280	nsp	RES, CHIP(1005/5%/33ohm)	E2, JP	CRJ06I330T	1	
R281-283	nsp	RES, CHIP(1005/5%/0ohm)	E2, JP	CRJ06I30R0T	3	
R284,285	nsp	RES, CHIP(1608/5%/1Kohm)	E2, JP	CRJ10DJ102T	2	
R286-289	nsp	RES, CHIP(1608/5%/10Kohm)	E2, JP	CRJ10DJ103T	4	
R290-293	nsp	RES, CHIP(1608/5%/4.7Kohm)	E2, JP	CRJ10DJ472T	4	
R294-297	nsp	RES, CHIP(1608/5%/10Kohm)	E2, JP	CRJ10DJ103T	4	
R299-304	nsp	RES, CHIP(1608/5%/10Kohm)	E2, JP	CRJ10DJ103T	6	
R312	nsp	RES, CHIP(1608/5%/1Mohm)	E2, JP	CRJ10DJ105T	1	
R313-316	nsp	RES, CHIP(1608/5%/15Kohm)	E2, JP	CRJ10DJ153T	4	
R317	nsp	RES, CHIP(1608/5%/100Kohm)	E2, JP	CRJ10DJ104T	1	
R318,319	nsp	RES, CHIP(1608/5%/150Kohm)	E2, JP	CRJ10DJ154T	2	
R320	nsp	RES, CHIP(1608/5%/1ohm)	E2, JP	CRJ10DJ1R0T	1	
R321	nsp	RES, CHIP(1608/5%/3.3ohm)	E2, JP	CRJ10DJ3R3T	1	
R323	nsp	RES, CHIP(1005/5%/8.2Kohm)	E2, JP	CRJ06I822T	1	
R324	nsp	RES, CHIP(1005/5%/47Kohm)	E2, JP	CRJ06I473T	1	
R326-336	nsp	RES, CHIP(1005/5%/4.7Kohm)	E2, JP	CRJ06I472T	11	
R337-340	nsp	RES, CHIP(1005/5%/33ohm)	E2, JP	CRJ06I330T	4	
R342	nsp	RES, CHIP(1005/5%/33ohm)	E2, JP	CRJ06I330T	1	
R344-348	nsp	RES, CHIP(1005/5%/33ohm)	E2, JP	CRJ06I330T	5	
R349-354	nsp	RES, CHIP(1005/5%/0ohm)	E2, JP	CRJ06I30R0T	6	
R355	nsp	RES, CHIP(1608/5%/0ohm)	E2, JP	CRJ10DJ30R0T	1	
R358-361	nsp	RES, CHIP(1608/5%/0ohm)	E2, JP	CRJ10DJ30R0T	4	
R365,366	nsp	RES, CHIP(1005/5%/0ohm)	E2, JP	CRJ06I30R0T	2	
R367,368	nsp	RES, CHIP(1005/5%/33ohm)	E2, JP	CRJ06I330T	2	
R369	nsp	RES, CHIP(1608/5%/0ohm)	E2, JP	CRJ10DJ30R0T	1	
R370	nsp	RES, CHIP(1608/5%/10Kohm)	E2, JP	CRJ10DJ103T	1	
R377,378	nsp	RES, CHIP(6432/5%/1Kohm)	E2, JP	CRJ01HJ102T	2	
R379,380	nsp	RES, CHIP(6432/5%/100ohm)	E2, JP	CRJ01HJ101T	2	
R382	nsp	RES, CHIP(1608/5%/10Kohm)	E2, JP	CRJ10DJ103T	1	
R384-386	nsp	RES, CHIP(1608/5%/10Kohm)	E2, JP	CRJ10DJ103T	3	
R401,402	nsp	RES, CHIP(2012/5%/10ohm)	E2, JP	CRJ18AJ100T	2	
R403,404	nsp	RES, CHIP(2012/5%/47ohm)	E2, JP	CRJ18AJ470T	2	
R405	nsp	RES, CHIP(1608/5%/100ohm)	E2, JP	CRJ10DJ101T	1	
R406,407	nsp	RES, CHIP(1608/5%/1Kohm)	E2, JP	CRJ10DJ102T	2	
R408	nsp	RES, CHIP(1005/5%/1Kohm)	E2, JP	CRJ06I102T	1	
R409	nsp	RES, CHIP(1608/5%/1Kohm)	E2, JP	CRJ10DJ102T	1	
R410-416	nsp	RES, CHIP(1608/5%/4.7Kohm)	E2, JP	CRJ10DJ472T	7	
R417-420	nsp	RES, CHIP(1608/5%/3.3Kohm)	E2, JP	CRJ10DJ332T	4	
R421,422	nsp	RES, CHIP(1608/5%/4.7Kohm)	E2, JP	CRJ10DJ472T	2	
R423,424	nsp	RES, CHIP(1608/5%/470ohm)	E2, JP	CRJ10DJ471T	2	

REF No.	Part No.	Part Name	Remarks	Q'ty	New	Ver
R425-431	nsp	RES, CHIP(1608/5%/47ohm)	E2, JP	CRJ10DJ470T	7	
R432	nsp	RES, CHIP(1608/5%/10Kohm)	E2, JP	CRJ10DJ103T	1	
R433-436	nsp	RES, CHIP(1608/5%/27Kohm)	E2, JP	CRJ10DJ273T	4	
R439-446	nsp	RES, CHIP(1608/5%/33ohm)	E2, JP	CRJ10DJ330T	8	
R447, 448	nsp	RES, CHIP(1608/5%/22Kohm)	E2, JP	CRJ10DJ223T	2	
R449	nsp	RES, CHIP(1608/5%/100Kohm)	E2, JP	CRJ10DJ104T	1	
R450	nsp	RES, CHIP(1608/5%/22Kohm)	E2, JP	CRJ10DJ223T	1	
R451	nsp	RES, CHIP(1005/5%/0ohm)	E2, JP	CRJ06J0R0T	1	
R462	nsp	RES, CHIP(1608/1%/18Kohm)	E2, JP	CRJ10DF1802T	1	
R463, 464	nsp	RES, CHIP(2012/5%/10ohm)	E2, JP	CRJ18AJ100T	2	
R465	nsp	RES, CHIP(1005/5%/0ohm)	E2, JP	CRJ06J0R0T	1	
R466, 467	nsp	RES, CHIP(1005/5%/33ohm)	E2, JP	CRJ06J330T	2	
R469	nsp	RES, CHIP(1005/5%/0ohm)	E2, JP	CRJ06J0R0T	1	
R470	nsp	RES, CHIP(1608/5%/680ohm)	E2, JP	CRJ10DJ681T	1	
R471	nsp	RES, CHIP(1608/5%/22Kohm)	E2, JP	CRJ10DJ223T	1	
R474-477	nsp	RES, CHIP(1608/5%/47Kohm)	E2, JP	CRJ10DJ473T	4	
R479, 480	nsp	RES, CHIP(1608/5%/4.7Kohm)	E2, JP	CRJ10DJ472T	2	
R481	nsp	RES, CHIP(2012/5%/47ohm)	E2, JP	CRJ18AJ470T	1	
R483	nsp	RES, CHIP(2012/5%/47ohm)	E2, JP	CRJ18AJ470T	1	
R485	nsp	RES, CHIP(1005/5%/10Kohm)	E2, JP	CRJ06J103T	1	
R486-489	nsp	RES, CHIP(2012/1%/5.6ohm)	E2, JP	CRJ18AF5R60T	4	
R490	nsp	RES, CHIP(1608/5%/10Kohm)	E2, JP	CRJ10DJ103T	1	
R600	nsp	RES, CHIP(1608/5%/100ohm)	E2, JP	CRJ10DJ101T	1	
R601	nsp	RES, CHIP(1608/5%/47Kohm)	E2, JP	CRJ10DJ473T	1	
R602	nsp	RES, CHIP(1608/1%/330Kohm)	E2, JP	CRJ10DF3303T	1	
R607, 608	nsp	RES, CHIP(1005/5%/4.7Kohm)	E2, JP	CRJ06J472T	2	
R610-612	nsp	RES, CHIP(1005/5%/10Kohm)	E2, JP	CRJ06J103T	3	
R615	nsp	RES, CHIP(1005/5%/0ohm)	E2, JP	CRJ06J0R0T	1	
R617-619	nsp	RES, CHIP(1005/5%/0ohm)	E2, JP	CRJ06J0R0T	3	
R621	nsp	RES, CHIP(1005/5%/0ohm)	E2, JP	CRJ06J0R0T	1	
R622-635	nsp	RES, CHIP(1608/5%/10Kohm)	E2, JP	CRJ10DJ103T	14	
R639	nsp	RES, CHIP(1608/5%/10Kohm)	E2, JP	CRJ10DJ103T	1	
R646	nsp	RES, CHIP(1608/5%/120Kohm)	E2, JP	CRJ10DJ124T	1	
R647	nsp	RES, CHIP(1608/5%/2.2Kohm)	E2, JP	CRJ10DJ222T	1	
R648	nsp	RES, CHIP(1608/5%/27Kohm)	E2, JP	CRJ10DJ273T	1	
R649	nsp	RES, CHIP(1608/5%/100ohm)	E2, JP	CRJ10DJ101T	1	
R650-652	nsp	RES, CHIP(1608/5%/33ohm)	E2, JP	CRJ10DJ330T	3	
R653, 654	nsp	RES, CHIP(1608/5%/100ohm)	E2, JP	CRJ10DJ101T	2	
R658	nsp	RES, CHIP(1608/5%/0ohm)	E2, JP	CRJ10DJ0R0T	1	
R659	nsp	RES, CHIP(1608/1%/348Kohm)	E2, JP	CRJ10DF3483T	1	
R660	nsp	RES, CHIP(1608/0.5%/348Kohm)	E2, JP	CRJ10DD3483T	1	
R661	nsp	RES, CHIP(1608/0.5%/110Kohm)	E2, JP	CRJ10DD1103T	1	
R662	nsp	RES, CHIP(1608/5%/33ohm)	E2, JP	CRJ10DJ330T	1	
R664	nsp	RES, CHIP(1608/5%/0ohm)	E2, JP	CRJ10DJ0R0T	1	
R666	nsp	RES, CHIP(1608/5%/0ohm)	E2, JP	CRJ10DJ0R0T	1	
R667-669	nsp	RES, CHIP(1608/5%/33ohm)	E2, JP	CRJ10DJ330T	3	
R670	nsp	RES, CHIP(1608/5%/0ohm)	E2, JP	CRJ10DJ0R0T	1	
R680	nsp	RES, CHIP(1608/5%/47Kohm)	E2, JP	CRJ10DJ473T	1	
R681	nsp	RES, CHIP(1608/5%/0ohm)	E2, JP	CRJ10DJ0R0T	1	
R683, 684	nsp	RES, CHIP(1608/5%/0ohm)	E2, JP	CRJ10DJ0R0T	2	
R685	nsp	RES, CHIP(1608/5%/100ohm)	E2, JP	CRJ10DJ101T	1	
R690	nsp	RES, CHIP(1608/5%/75Kohm)	E2, JP	CRJ10DJ753T	1	
R693, 694	nsp	RES, CHIP(1608/5%/0ohm)	E2, JP	CRJ10DJ0R0T	2	
R695	nsp	RES, CHIP(1608/1%/348Kohm)	E2, JP	CRJ10DF3483T	1	
R696	nsp	RES, CHIP(1608/1%/76.8Kohm)	E2, JP	CRJ10DF7682T	1	
R697	nsp	RES, CHIP(1608/5%/0ohm)	E2, JP	CRJ10DJ0R0T	1	
R698	nsp	RES, CHIP(1608/1%/348Kohm)	E2, JP	CRJ10DF3483T	1	
R699	nsp	RES, CHIP(1608/1%/169Kohm)	E2, JP	CRJ10DF1693T	1	
R700	nsp	RES, CHIP(1608/1%/2Kohm)	E2, JP	CRJ10DF2001T	1	
R701-704	nsp	RES, CHIP(1608/5%/1Kohm)	E2, JP	CRJ10DJ102T	4	
R705-708	nsp	RES, CHIP(1608/5%/100Kohm)	E2, JP	CRJ10DJ104T	4	
R710-713	nsp	RES, CHIP(1005/5%/100ohm)	E2, JP	CRJ06J101T	4	
R720, 721	nsp	RES, CHIP(2012/5%/47ohm)	E2, JP	CRJ18AJ470T	2	
RX91-94	nsp	RES, CHIP(3216/5%/1.5Mohm)	E2, JP	CRJ14CJ155T	4	
CAPACITORS GROUP						
C200-209	nsp	CAP, CHIP(1005, 25V/0.01uF, X7R) SAMSUNG	E2, JP	CCUI1E103KCS	10	
C210-221	nsp	CAP, CHIP(1005, 16V/0.1uF, X7R) SAMSUNG	E2, JP	CCUI1C104KCS	12	
C222	nsp	CAP, CHIP(1608, 50V/1000pF, X7R) SAMSUNG	E2, JP	CCUS1H102KCS	1	
C223	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	E2, JP	CCUS1H104KCS	1	
C227-230	nsp	CAP, CHIP(1608, 16V/1uF, X7R) SAMSUNG	E2, JP	CCUS1C105KCS	4	
C231, 232	nsp	CAP, CHIP(1608, 50V/100pF, C0G) SAMSUNG	E2, JP	CCUS1H101JAS	2	
C233-236	nsp	CAP, CHIP(1608, 50V/120pF, C0G) SAMSUNG	E2, JP	CCUS1H121JAS	4	
C237	nsp	CAP, CHIP(1608, 50V/100pF, C0G) SAMSUNG	E2, JP	CCUS1H101JAS	1	
C238-241	nsp	CAP, CHIP(1005, 50V/100pF, C0G) SAMSUNG	E2, JP	CCUI1H101JAS	4	
C242, 243	nsp	CAP, CHIP(1608, 50V/100pF, C0G) SAMSUNG	E2, JP	CCUS1H101JAS	2	
C244-246	nsp	CAP, CHIP(1608, 50V/1000pF, X7R) SAMSUNG	E2, JP	CCUS1H102KCS	3	
C255-257	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG	E2, JP	CCUS1H103KCS	3	
C258	nsp	RES, CHIP(1608/5%/0ohm)	E2, JP	CRJ10DJ0R0T	1	
C259	nsp	CAP, CHIP(1005, 25V/0.01uF, X7R) SAMSUNG	E2, JP	CCUI1E103KCS	1	
C260-265	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG	E2, JP	CCUS1H103KCS	6	
C266	nsp	CAP, CHIP(1608, 50V/0.047uF, X7R) SAMSUNG	E2, JP	CCUS1H473KCS	1	
C267	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG	E2, JP	CCUS1H103KCS	1	
C269, 270	nsp	CAP, CHIP(1608, 50V/1000pF, X7R) SAMSUNG	E2, JP	CCUS1H102KCS	2	
C271	nsp	CAP, CHIP(1608, 50V/560pF, C0G) SAMSUNG	E2, JP	CCUS1H561JAS	1	
C273-282	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	E2, JP	CCUS1H104KCS	10	
C283, 284	nsp	CAP, CHIP(1608, 50V/15pF, C0G) SAMSUNG	E2, JP	CCUS1H150JAS	2	
C285, 286	nsp	CAP, CHIP(1608, 50V/18pF, C0G) SAMSUNG	E2, JP	CCUS1H180JAS	2	
C287	nsp	CAP, CHIP(1608, 50V/560pF, C0G) SAMSUNG	E2, JP	CCUS1H561JAS	1	
C288	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG	E2, JP	CCUS1H103KCS	1	
C289, 290	nsp	CAP, CHIP(1608, 50V/470pF, C0G) SAMSUNG	E2, JP	CCUS1H471JAS	2	
C291-294	nsp	CAP, CHIP(1608, 50V/4700pF, X7R) SAMSUNG	E2, JP	CCUS1H472KCS	4	
C295	nsp	CAP, CHIP(1608, 50V/0.047uF, X7R) SAMSUNG	E2, JP	CCUS1H473KCS	1	
C297	nsp	CAP, CHIP(1608, 50V/0.068uF, X7R) SAMSUNG	E2, JP	CCUS1H683KCS	1	
C298-304	nsp	CAP, CHIP(1608, 50V/1000pF, X7R) SAMSUNG	E2, JP	CCUS1H102KCS	7	
C305	nsp	RES, CHIP(1608/5%/0ohm)	E2, JP	CRJ10DJ0R0T	1	
C306-311	nsp	CAP, CHIP(1608, 50V/1000pF, X7R) SAMSUNG	E2, JP	CCUS1H102KCS	6	
C315-323	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG	E2, JP	CCUS1H103KCS	9	
C324	nsp	CAP, CHIP(1608, 6.3V/4.7uF, X5R) SAMSUNG	E2, JP	CCUS0J475KCS	1	
C325-328	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG	E2, JP	CCUS1H103KCS	4	
C332-364	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	E2, JP	CCUS1H104KCS	33	
C365	nsp	CAP, CHIP(1005, 16V/0.1uF, X7R) SAMSUNG	E2, JP	CCUI1C104KCS	1	
C366-368	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	E2, JP	CCUS1H104KCS	3	
C369	nsp	RES, CHIP(1608/5%/0ohm)	E2, JP	CRJ10DJ0R0T	1	
C370-372	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	E2, JP	CCUS1H104KCS	3	
C373	nsp	CAP, CHIP(2012, 16V/10uF, X5R) SAMSUNG	E2, JP	CCUC1C106KCS	1	
C374	943134503400D	CAP, ELECT(50V/2.2uF)-S	E2, JP	CCEA1HKS2R2T	1	*
C375-377	943134503370D	CAP, ELECT(16V/10uF)-S	E2, JP	CCEA1CKS100TC	3	*
C378	943134503390D	CAP, ELECT(16V/100uF)-S, 105°C	E2, JP	CCEA1CKS101TS	1	*
C379, 380	00D2544577958	CAP, ELECT(16V/220uF), ELNA/RA3	E2, JP	CCEA1CRA3221T	2	
C381	943134502040D	CAP, ELECT(16V/100uF)-S	E2, JP	CCEA1CKS101TC	1	
C382	00D2544577958	CAP, ELECT(16V/220uF), ELNA/RA3	E2, JP	CCEA1CRA3221T	1	
C383	943134010670S	CAP, ELECT(16V/47uF)-S	E2, JP	CCEA1CKS470T	1	
C384, 385	943134503060S	CAP, SMD ELECT(16V/22uF)	E2, JP	CCEC1CMVG220T	2	

REF No.	Part No.	Part Name	Remarks	Q'ty	New	Ver
C386	943134503370D	CAP, ELECT(16V/10uF)-S	E2, JP	CCEA1CK5100TC	1	*
C387	943134503400D	CAP, ELECT(50V/2.2uF)-S	E2, JP	CCEA1HK52R2T	1	*
C388	943134503380D	CAP, ELECT(16V/10uF)-S,105°C	E2, JP	CCEA1CK5100TS	1	*
C389,390	943134503370D	CAP, ELECT(16V/10uF)-S	E2, JP	CCEA1CK5100TC	2	*
C391	00D2544577958	CAP, ELECT(16V/220uF),ELNA/RA3	E2, JP	CCEA1CRA3221T	1	
C392	943134502580M	CAP, ELEC SMD(LOW ESR, 150UF/10V, ENESOL)	E2, JP	CCEC1AVS151TL	1	
C393	943134502570M	CAP, ELEC SMD(6.3V/220uF, PVVZ Series, ESR,105°C)	E2, JP	CCEC0JPVWZ221T	1	
C395,396	943134502560M	CAP,ALUMINUM ELECTROLYTIC (6.3V/220uF)	E2, JP	CCEC0JMMVG221T	2	
C397	943134502580M	CAP, ELEC SMD(LOW ESR, 150UF/10V, ENESOL)	E2, JP	CCEC1AVS151TL	1	
C398	943134502570M	CAP, ELEC SMD(6.3V/220uF, PVVZ Series, ESR,105°C)	E2, JP	CCEC0JPVWZ221T	1	
C400	943134502570M	CAP, ELEC SMD(6.3V/220uF, PVVZ Series, ESR,105°C)	E2, JP	CCEC0JPVWZ221T	1	
C401	nsp	CAP, CHIP(2012, 6.3V/10uF, X5R) SAMSUNG	E2, JP	CCUC0J106KCS	1	
C402	nsp	CAP, CHIP(1608, 16V/1uF, X7R) SAMSUNG	E2, JP	CCUS1C105KCS	1	
C403	943134502590M	CAP,ALUMINUM ELECTROLYTIC CAPACITORS(16V/100uF)	E2, JP	CCEC1CMVG101T	1	
C406	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG	E2, JP	CCUS1H103KCS	1	
C407	943134502570M	CAP, ELEC SMD(6.3V/220uF, PVVZ Series, ESR,105°C)	E2, JP	CCEC0JPVWZ221T	1	
C408,409	943132500640M	CAP, CHIP(3216, 100V/0.01uF, MURATA GRM31)	E2, JP	CCUMUP2A103JAM	2	
C410-413	nsp	CAP,CHIP(1005, 50V/18pF, C0G) SAMSUNG	E2, JP	CCU11H180JAS	4	
C430	nsp	CAP, CHIP(1608, 6.3V/4.7uF, X5R) SAMSUNG	E2, JP	CCUS0J475KCS	1	
C450,451	943132500640M	CAP, CHIP(3216, 100V/0.01uF, MURATA GRM31)	E2, JP	CCUMUP2A103JAM	2	
C600-611	nsp	CAP, CHIP(1005, 16V/0.1uF, X7R) SAMSUNG	E2, JP	CCU11C104KCS	12	
C612	nsp	CAP, CHIP(1005, 25V/0.01uF, X7R) SAMSUNG	E2, JP	CCU11E103KCS	1	
C613,614	nsp	CAP, CHIP(1005, 50V/1000pF, X7R) SAMSUNG	E2, JP	CCU11H102KCS	2	
C615,616	nsp	CAP, CHIP(1005, 50V/4700pF, X7R) SAMSUNG	E2, JP	CCU11H472KCS	2	
C621-625	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG	E2, JP	CCUS1H103KCS	5	
C626	nsp	CAP, CHIP(1608, 50V/1000pF, X7R) SAMSUNG	E2, JP	CCUS1H102KCS	1	
C627-629	nsp	CAP, CHIP(2012, 6.3V/22uF, X5R) SAMSUNG	E2, JP	CCUC0J226KCS	3	
C630,631	nsp	CAP, CHIP(1608, 50V/1000pF, X7R) SAMSUNG	E2, JP	CCUS1H102KCS	2	
C632-637	nsp	CAP, CHIP(1608, 6.3V/4.7uF, X5R) SAMSUNG	E2, JP	CCUS0J475KCS	6	
C638	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	E2, JP	CCUS1H104KCS	1	
C639	nsp	CAP, CHIP(1608, 6.3V/4.7uF, X5R) SAMSUNG	E2, JP	CCUS0J475KCS	1	
C640,641	nsp	CAP, CHIP(2012, 6.3V/22uF, X5R) SAMSUNG	E2, JP	CCUC0J226KCS	2	
C642	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	E2, JP	CCUS1H104KCS	1	
C643	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG	E2, JP	CCUS1H103KCS	1	
C644	nsp	CAP,CHIP(2012, 6.3V/22uF, X5R) SAMSUNG	E2, JP	CCUC0J226KCS	1	
C648	nsp	CAP, CHIP(1608, 6.3V/4.7uF, X5R) SAMSUNG	E2, JP	CCUS0J475KCS	1	
C653,654	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	E2, JP	CCUS1H104KCS	2	
C655	nsp	CAP, CHIP(1005, 16V/0.1uF, X7R) SAMSUNG	E2, JP	CCU11C104KCS	1	
C656	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	E2, JP	CCUS1H104KCS	1	
C658,659	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	E2, JP	CCUS1H104KCS	2	
C660	nsp	CAP, CHIP(1608, 50V/1000pF, X7R) SAMSUNG	E2, JP	CCUS1H102KCS	1	
C662	nsp	CAP, CHIP(2012, 6.3V/22uF, X5R) SAMSUNG	E2, JP	CCUC0J226KCS	1	
C663,664	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	E2, JP	CCUS1H104KCS	2	
C665	nsp	CAP, CHIP(1608, 50V/1000pF, X7R) SAMSUNG	E2, JP	CCUS1H102KCS	1	
C666	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG	E2, JP	CCUS1H103KCS	1	
C667	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	E2, JP	CCUS1H104KCS	1	
C671	nsp	CAP, CHIP(1005, 16V/0.1uF, X7R) SAMSUNG	E2, JP	CCU11C104KCS	1	
C672	nsp	CAP, CHIP(1608, 10V/1uF, X7R, X7S) SAMSUNG	E2, JP	CCUS1A105KCS	1	
C673	nsp	CAP, CHIP(1608, 50V/3.3pF, C0G) SAMSUNG	E2, JP	CCUS1H3R3JAS	1	
C674	nsp	CAP, CHIP(2012, 6.3V/10uF, X5R) SAMSUNG	E2, JP	CCUC0J106KCS	1	
C675	nsp	CAP, CHIP(2012, 6.3V/22uF, X5R) SAMSUNG	E2, JP	CCUC0J226KCS	1	
C676	nsp	CAP,CHIP(2012, 6.3V/10uF, X5R) SAMSUNG	E2, JP	CCUC0J106KCS	1	
C677	nsp	CAP, CHIP(1005, 16V/0.1uF, X7R) SAMSUNG	E2, JP	CCU11C104KCS	1	
C678	nsp	CAP, CHIP(2012, 6.3V/10uF, X5R) SAMSUNG	E2, JP	CCUC0J106KCS	1	
C679	nsp	CAP, CHIP(1608, 10V/1uF, X7R, X7S) SAMSUNG	E2, JP	CCUS1A105KCS	1	
C680	nsp	CAP, CHIP(1608, 50V/5pF, C0G) SAMSUNG	E2, JP	CCUS1H050CAS	1	
C681	nsp	CAP, CHIP(2012, 6.3V/22uF, X5R) SAMSUNG	E2, JP	CCUC0J226KCS	1	
C682	nsp	CAP, CHIP(2012, 6.3V/10uF, X5R) SAMSUNG	E2, JP	CCUC0J106KCS	1	
C683	nsp	CAP, CHIP(1005, 16V/0.1uF, X7R) SAMSUNG	E2, JP	CCU11C104KCS	1	
C684	nsp	CAP, CHIP(2012, 6.3V/10uF, X5R) SAMSUNG	E2, JP	CCUC0J106KCS	1	
C685	nsp	CAP, CHIP(1608, 10V/1uF, X7R, X7S) SAMSUNG	E2, JP	CCUS1A105KCS	1	
C686	nsp	CAP, CHIP(1608, 50V/5pF, C0G) SAMSUNG	E2, JP	CCUS1H050CAS	1	
C687	nsp	CAP, CHIP(2012, 6.3V/22uF, X5R) SAMSUNG	E2, JP	CCUC0J226KCS	1	
C688	nsp	CAP, CHIP(2012, 6.3V/10uF, X5R) SAMSUNG	E2, JP	CCUC0J106KCS	1	
C689	nsp	CAP, CHIP(1005, 16V/0.1uF, X7R) SAMSUNG	E2, JP	CCU11C104KCS	1	
C690	nsp	CAP, CHIP(2012, 6.3V/10uF, X5R) SAMSUNG	E2, JP	CCUC0J106KCS	1	
C691	nsp	CAP, CHIP(1608, 10V/1uF, X7R, X7S) SAMSUNG	E2, JP	CCUS1A105KCS	1	
C692	nsp	CAP, CHIP(1608, 50V/5pF, C0G) SAMSUNG	E2, JP	CCUS1H050CAS	1	
C693	nsp	CAP,CHIP(2012, 6.3V/22uF, X5R) SAMSUNG	E2, JP	CCUC0J226KCS	1	
C694	943134503370D	CAP, ELECT(16V/10uF)-S	E2, JP	CCEA1CK5100TC	1	*
C695	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	E2, JP	CCUS1H104KCS	1	
C696	00D9430173003	CAP, ELECT(10V/220uF)-S	E2, JP	CCEA1AKS221T	1	
C697	nsp	CAP, CHIP(2012, 6.3V/22uF, X5R) SAMSUNG	E2, JP	CCUC0J226KCS	1	
C698	nsp	CAP, CHIP(2012, 6.3V/10uF, X5R) SAMSUNG	E2, JP	CCUC0J106KCS	1	
C699-707	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	E2, JP	CCUS1H104KCS	9	
C708-711	nsp	CAP, CHIP(1005, 16V/0.1uF, X7R) SAMSUNG	E2, JP	CCU11C104KCS	4	
C712	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	E2, JP	CCUS1H104KCS	1	
C713	nsp	CAP, CHIP(1005, 16V/0.1uF, X7R) SAMSUNG	E2, JP	CCU11C104KCS	1	
C714,715	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	E2, JP	CCUS1H104KCS	2	
C720-726	nsp	CAP,CHIP(2012, 6.3V/22uF, X5R) SAMSUNG	E2, JP	CCUC0J226KCS	7	
C732	nsp	CAP, CHIP(1005, 16V/0.1uF, X7R) SAMSUNG	E2, JP	CCU11C104KCS	1	
C733,734	nsp	CAP, CHIP(1005, 50V/1000pF)	E2, JP	CCU11H102KC	2	
OTHER PARTS GROUP						
BK61	nsp	BRACKET , PCB	E2, JP	CMD1A629	1	
BK62	nsp	BRACKET , PCB M3	E2, JP	CMD1A834	1	
BK63	nsp	BRACKET , NETWORK A	E2, JP	CMD1A900	1	
BN16	nsp	Wire ass'y (5P,80mm,2.0mm)	E2, JP	CWB1B00508047	1	
CN10	nsp	LOCKING TYPE , STRAIGHT WAFER , 2mm	E2, JP	CJP05GI236ZW	1	
CN62	nsp	LOCKING TYPE , STRAIGHT WAFER , 2.5MM	E2, JP	CJP03GI237ZW	1	
CN63	nsp	LOCKING TYPE , STRAIGHT WAFER , 2mm	E2, JP	CJP05GI236ZW	1	
CN65	nsp	WAFER, FFC, SMD(07P-1mm, STRAIGHT)	E2, JP	CJP07GA193ZY	1	
CN66,67	nsp	WAFER, 64pin (2 x 32 x 1.27mm) SMD TYPE	E2, JP	CJP64GA312ZP	2	
CN90	nsp	WAFER, 2P, 3.96mm	E2, JP	CJP02KA060ZY	1	
CN92	nsp	LOCK-WAFER/ANGLE/2.5MM PITCH/5PIN	E2, JP	CJP05GJ289ZY	1	
CN93	nsp	LOCKING TYPE , STRAIGHT WAFER , 2MM	E2, JP	CJP13GI236ZW	1	
! CX91	943134503220D	CAP , X2(275VAC, 0.22uF, 12mm, SEORYONG)	E2, JP	CCQF2E224KZFS	1	
! ET20,21	nsp	PLATE , EARTH(TRONIC ELECTRONICS)	E2, JP	CJT1A026	2	
! F901	943652500300M	FUSE, 215 SERIES, 4A, 250V	E2, JP	CBA2C4000TLHEY	1	
FH91,92	nsp	HOLDER , FUSE	E2, JP	KJCFCS5	2	
JK20	943643102900D	Terminal 2P Speaker(PUSH BK,RD)	E2, JP	CJJ5N029Z	1	
EXPLODED C5	943643102910D	Terminal 2P Speaker(PUSH RD,BK)	E2, JP	CJJ5N028Z	1	
JK21	943643103110D	JACK, RCA (3PIN, WH/RD/BK, Ni PLATE, VERTICAL)	E2, JP	CJJ4S058Z	1	*
EXPLODED C6	943643102460D	JACK , USB ANGLE TYPE (BLACK 1.5A)	E2, JP	CJJ9X014Z	1	
JK60	943643102430S	JACK , RJ-45 W/TRANSFORMER	E2, JP	CJJ9L029Z	1	
! JK90	943641500240D	INLET , AC , NON-POL (250V/2.5A PCB MOUNT TYPE)	E2, JP	CJJ8A019Z	1	
JW20,21	nsp	SUPPORT , PCB	E2, JP	CDF1A035	2	
EXPLODED M4	nsp	FERRITE CHIP BEAD(4516/60R)	E2, JP	CLZ9Z014Z	1	
L204	nsp	FERRITE , CHIP BEAD(60ohm, 2012)	E2, JP	CLZ9R001Z	4	
L205-208	nsp	BEAD , FERRITE (FCM2012KF-121T08 , 120 OHM)	E2, JP	CLZ9R010Z	1	
L209	nsp		E2, JP			

REF No.	Part No.	Part Name	Remarks		Q'ty	New	Ver
L210-221	nsp	FERRITE , CHIP BEAD(60ohm, 2012)	E2, JP	CLZ9R001Z	12		
L322	nsp	FERRITE CHIP BEAD(1608/60R, CB03YTYH600)	E2, JP	CLZ9R005V	1		
L341	nsp	FERRITE CHIP BEAD(1608/60R, CB03YTYH600)	E2, JP	CLZ9R005V	1		
L451-461	nsp	FERRITE CHIP BEAD(1608/60R, CB03YTYH600)	E2, JP	CLZ9R005V	11		
L600,601	nsp	FERRITE , CHIP BEAD(60ohm, 2012)	E2, JP	CLZ9R001Z	2		
L602	nsp	FERRITE CHIP BEAD(2012/220R, CB05YTYH221)	E2, JP	CLZ9R018V	1		
L603	nsp	FERRITE , CHIP BEAD(60ohm, 2012)	E2, JP	CLZ9R001Z	1		
L604	nsp	FERRITE CHIP BEAD(2012/220R, CB05YTYH221)	E2, JP	CLZ9R018V	1		
L605-609	nsp	FERRITE , CHIP BEAD(60ohm, 2012)	E2, JP	CLZ9R001Z	5		
L610,611	nsp	COMMON MODE FILTER (2012, 90ohm)	E2, JP	CLZ9Z174Z	2		
L614	nsp	FERRITE CHIP BEAD(4516/60R)	E2, JP	CLZ9Z014Z	1		
L615,616	nsp	FERRITE CHIP BEAD(2012/220R, CB05YTYH221)	E2, JP	CLZ9R018V	2		
L617-619	nsp	FERRITE , CHIP BEAD(60ohm, 2012)	E2, JP	CLZ9R001Z	3		
LF91	943111100490M	FILTER , LINE(DMC250)	E2, JP	CLZ9Z087Z	1		
LF92	nsp	LINE, FILTER(5.0A/5.0mH)	E2, JP	CLZ9Z158Z	1		
PF12	nsp	WAFER, FFC(27P-1.25mm, STRAIGHT)	E2, JP	CJP27GA115ZY	1		
PF15	nsp	WAFER, FFC, SMD(11P-1mm, STRAIGHT)	E2, JP	CJP11GA193ZY	1		
PF60	nsp	WAFER, FFC(25P-1mm, STRAIGHT)	E2, JP	CJP25GA117ZY	1		
PF70,71	nsp	FEMALE HEADER (6P,2.54mm) , STRAIGHT TYPE	E2, JP	CJP06GA221ZB	2		
PF72	nsp	FEMALE HEADER (12P,2.54mm) , STRAIGHT TYPE	E2, JP	CJP12GA221ZB	1		
PF80	nsp	WAFER, FFC(19P-1mm, STRAIGHT)	E2, JP	CJP19GA117ZY	1		
SW60	943662100180M	SW, TACT, VERTICAL (3.3mm)	E2, JP	CST1A032ZT	1		
VT91	943251100070M	VARISTOR(560V, 14mm)	E2, JP	CRV5VC561D14A	1		
WF22	nsp	WAFER, FFC, SMD(07P-1mm, STRAIGHT)	E2, JP	CJP07GA193ZY	1		
WF23	nsp	WAFER, FFC, SMD(4pin, 1mm, STRAIGHT)	E2, JP	CJP04GA193ZY	1		
WF60	nsp	WAFER, FFC(25P-1mm, STRAIGHT)	E2, JP	CJP25GA117ZY	1		
X200	943141100610S	X-TAL, SMD 3.2X2.5, 12.000MHz, 10PF	E2, JP	COX120001100ST	1		
X201	943141100620S	X-TAL, SMD 3.2X2.5, 24.576MHz, 12PF	E2, JP	COX245761120ST	1		

MAIN For E1C PCB ASS'Y

※Parts indicated by "nsp" on this table cannot be supplied.

※The parts listed below are only for maintenance. Therefore they might differ from the parts used in the unit in appearances or dimensions

NOTE: The symbols in the column Remarks indicate the following destinations.

E3 : U.S.A. & Canada model E2 : Europe model E1C : China model E1 : Asia model JP : Japan model

BK : Black model SP : Premium Silver model WT : White model

REF No.	Part No.	Part Name	Remarks	Q'ty	New	Ver
SEMICONDUCTORS GROUP						
D201-210	943209001080S	DIODE , CHIP , SWITCHING	E1C	CVD1SS355T	10	
D212,213	943209001080S	DIODE , CHIP , SWITCHING	E1C	CVD1SS355T	2	
D214,215	90M-HD201820R	DIODE, SCHOTTKY BARRIER	E1C	HVDRB160L60TE25	2	
D216,217	943209001080S	DIODE , CHIP , SWITCHING	E1C	CVD1SS355T	2	
D218	90M-HD201820R	DIODE, SCHOTTKY BARRIER	E1C	HVDRB160L60TE25	1	
D219	943209001080S	DIODE , CHIP , SWITCHING	E1C	CVD1SS355T	1	
D601-604	943209001080S	DIODE , CHIP , SWITCHING	E1C	CVD1SS355T	4	
IC20	943239101590D	I.C , Audio Switch Stereo(TVSP10)	E1C	CVINJM2752RB2	1	
IC21	943234009290S	I.C , RESET 2.4V (200ms, C-MOS, SOT23-5P)	E1C	CVIS80124CLMCJJIJ	1	
IC22	23681014050AS	I.C , DIR/DIT(WITH ADC, LQFP-48P)	E1C	CVIPCM9211PTR	1	
IC23	943239101600D	I.C , PWM PROCESSOR(HTSSOP-56P)	E1C	CVITAS5558DCAR	1	
IC24	943235100670M	I.C , OP AMP	E1C	HVINJM4556AMTE1	1	
IC25	00MHC10102090	I.C , OP AMP (JRC)	E1C	HVINJM2068MDTE1	1	
IC26	943239101500S	I.C , EEPROM(128KBIT, SOP-8P)	E1C	CVIR1EX24128BSA	1	
IC27	943239101610D	I.C, REGULATOR(3.3V, TO-252-5, Io=1.5A, LDO)	E1C	CVINJM2857DL3-33	1	
IC28	-	I.C, CPU(2M/PLQP0144KA-A)	E1C	CVIR5F56108VNF	1	
IC28	943243102690S	I.C, MAIN MCU(DRA-N4, RCD-N9), 2M/PLQP0144KA-A See Procedure after Replacing the Microprocessor, etc.	E1C	CVIANAM2033CR	1	
IC29	943239010400S	I.C, REGULATOR(3.3V/TO-252)	E1C	CVINJM2845DL133	1	
IC30	963248103120S	GD25Q32B 32Mbit SOP8 SERIAL FLASH	E1C	8952600500100	1	
IC60	943239001120S	IC , CURRENT LIMITER	E1C	CVIRT9702APB	1	
IC61	23671011050AS	I.C , IPOD AUTHENTICATION FROM D&M	E1C	CVI23671011050AS	1	
IC62	943606502150M	I.C , USB SWITCH(DUAL SPDT, UQFN10)	E1C	CVITC7USB40MU	1	
IC63-66	943239101070S	I.C , DC-DC CONVERTER (3A, QFN T&R-24P)	E1C	CVIEN5339QI	4	
IC67	24681009260AS	I.C , SERIAL FLASH(256M, SOP-16)	E1C	CVIMX25L25635FMI	1	
Q200,201	943215500020S	T.R, RT1P141C(10K-10K)	E1C	CVTRT1P141C	2	
Q203	943215500020S	T.R, RT1P141C(10K-10K)	E1C	CVTRT1P141C	1	
Q204,205	943216500020S	T.R, RT1N141C(10K-10K)	E1C	CVTRT1N141C	2	
Q206,207	963216500060S	T.R, RT1N144C(10K-47K)	E1C	CVTRT1N144C	2	
Q208	943215500020S	T.R, RT1P141C(10K-10K)	E1C	CVTRT1P141C	1	
Q211-216	00D9430072502	T.R , CHIP , SOT-23	E1C	HVTKTC2875B	6	
Q218	943222500300S	FET, BSS138BK, N-CH, TO-236AB, NXP	E1C	CVTBSS138BK	1	
Q219-221	943215500020S	T.R, RT1P141C(10K-10K)	E1C	CVTRT1P141C	3	
Q222	943229500160D	FET, FDN360P, P-CH, SOT-23, FAIRCHILD	E1C	CVTFDN360P	1	
Q223-226	943216500020S	T.R, RT1N141C(10K-10K)	E1C	CVTRT1N141C	4	
Q228-231	943216500020S	T.R, RT1N141C(10K-10K)	E1C	CVTRT1N141C	4	
Q232	943215500020S	T.R, RT1P141C(10K-10K)	E1C	CVTRT1P141C	1	
Q233	943216500020S	T.R, RT1N141C(10K-10K)	E1C	CVTRT1N141C	1	
Q680	943216500020S	T.R, RT1N141C(10K-10K)	E1C	CVTRT1N141C	1	
Q681	943229500020S	MOSFET, TPC6111(P-CH, U-MOSV)	E1C	CVTTPC6111	1	
RESISTOR GROUP						
R200-203	nsp	RES, CHIP(1005/5%/33ohm)	E1C	CRJ06J330T	4	
R204-209	nsp	RES, CHIP(1005/5%/0ohm)	E1C	CRJ06J0R0T	6	
R210	nsp	RES, CHIP(1005/5%/4.7Kohm)	E1C	CRJ06J472T	1	
R211	nsp	RES, CHIP(1005/5%/10Kohm)	E1C	CRJ06J103T	1	
R212,213	nsp	RES, CHIP(1005/5%/33ohm)	E1C	CRJ06J330T	2	
R214	nsp	RES, CHIP(1005/5%/22Kohm)	E1C	CRJ06J223T	1	
R215-220	nsp	RES, CHIP(1005/5%/33ohm)	E1C	CRJ06J330T	6	
R221-229	nsp	RES, CHIP(1005/5%/100Kohm)	E1C	CRJ06J104T	9	
R230	nsp	RES, CHIP(1005/5%/10Kohm)	E1C	CRJ06J103T	1	
R231	nsp	RES, CHIP(1005/5%/15Kohm)	E1C	CRJ06J153T	1	
R232	nsp	RES, CHIP(1005/5%/10Kohm)	E1C	CRJ06J103T	1	
R235	nsp	RES, CHIP(2012/5%/18ohm)	E1C	CRJ18AJ180T	1	
R236-238	nsp	RES, CHIP(1005/5%/10Kohm)	E1C	CRJ06J103T	3	
R240,241	nsp	RES, CHIP(1005/5%/10Kohm)	E1C	CRJ06J103T	2	
R243,244	nsp	RES, CHIP(1005/5%/10Kohm)	E1C	CRJ06J103T	2	
R246-254	nsp	RES, CHIP(1005/5%/10Kohm)	E1C	CRJ06J103T	9	
R256	nsp	RES, CHIP(1005/5%/10Kohm)	E1C	CRJ06J103T	1	
R257	nsp	RES, CHIP(1005/5%/10Kohm)	E1C	CRJ06J103T	1	
R260-262	nsp	RES, CHIP(1005/5%/10Kohm)	E1C	CRJ06J103T	3	
R263	nsp	RES, CHIP(1608/5%/10Kohm)	E1C	CRJ10DJ103T	1	
R264,265	nsp	RES, CHIP(1005/5%/1Kohm)	E1C	CRJ06J102T	2	
R267	nsp	RES, CHIP(1005/5%/100ohm)	E1C	CRJ06J101T	1	
R269-271	nsp	RES, CHIP(1005/5%/0ohm)	E1C	CRJ06J0R0T	3	
R273-277	nsp	RES, CHIP(1005/5%/0ohm)	E1C	CRJ06J0R0T	5	
R278,279	nsp	RES, CHIP(1005/5%/0ohm)	E1C	CRJ06J0R0T	2	
R280	nsp	RES, CHIP(1005/5%/33ohm)	E1C	CRJ06J330T	1	
R281-283	nsp	RES, CHIP(1005/5%/0ohm)	E1C	CRJ06J0R0T	3	
R284,285	nsp	RES, CHIP(1608/5%/1Kohm)	E1C	CRJ10DJ102T	2	
R286-289	nsp	RES, CHIP(1608/5%/10Kohm)	E1C	CRJ10DJ103T	4	
R290-293	nsp	RES, CHIP(1608/5%/4.7Kohm)	E1C	CRJ10DJ472T	4	
R294-297	nsp	RES, CHIP(1608/5%/10Kohm)	E1C	CRJ10DJ103T	4	
R299-304	nsp	RES, CHIP(1608/5%/10Kohm)	E1C	CRJ10DJ103T	6	
R312	nsp	RES, CHIP(1608/5%/1Mohm)	E1C	CRJ10DJ105T	1	
R313-316	nsp	RES, CHIP(1608/5%/15Kohm)	E1C	CRJ10DJ153T	4	
R317	nsp	RES, CHIP(1608/5%/100Kohm)	E1C	CRJ10DJ104T	1	
R318,319	nsp	RES, CHIP(1608/5%/150Kohm)	E1C	CRJ10DJ154T	2	
R320	nsp	RES, CHIP(1608/5%/1ohm)	E1C	CRJ10DJ1R0T	1	
R321	nsp	RES, CHIP(1608/5%/3.3ohm)	E1C	CRJ10DJ3R3T	1	
R323	nsp	RES, CHIP(1005/5%/8.2Kohm)	E1C	CRJ06J822T	1	
R324	nsp	RES, CHIP(1005/5%/47Kohm)	E1C	CRJ06J473T	1	
R326-336	nsp	RES, CHIP(1005/5%/4.7Kohm)	E1C	CRJ06J472T	11	
R337-340	nsp	RES, CHIP(1005/5%/33ohm)	E1C	CRJ06J330T	4	
R342	nsp	RES, CHIP(1005/5%/33ohm)	E1C	CRJ06J330T	1	
R343	nsp	RES, CHIP(1005/5%/0ohm)	E1C	CRJ06J0R0T	1	
R344-348	nsp	RES, CHIP(1005/5%/33ohm)	E1C	CRJ06J330T	5	
R349-354	nsp	RES, CHIP(1005/5%/0ohm)	E1C	CRJ06J0R0T	6	
R355	nsp	RES, CHIP(1608/5%/0ohm)	E1C	CRJ10DJ0R0T	1	
R358-361	nsp	RES, CHIP(1608/5%/0ohm)	E1C	CRJ10DJ0R0T	4	
R362-364	nsp	RES, CHIP(1005/5%/10Kohm)	E1C	CRJ06J103T	3	
R365,366	nsp	RES, CHIP(1005/5%/0ohm)	E1C	CRJ06J0R0T	2	
R367,368	nsp	RES, CHIP(1005/5%/33ohm)	E1C	CRJ06J330T	2	
R369	nsp	RES, CHIP(1608/5%/0ohm)	E1C	CRJ10DJ0R0T	1	
R370	nsp	RES, CHIP(1608/5%/10Kohm)	E1C	CRJ10DJ103T	1	
R371	nsp	RES, CHIP(1005/5%/10Kohm)	E1C	CRJ06J103T	1	
R377,378	nsp	RES, CHIP(6432/5%/1Kohm)	E1C	CRJ01HJ102T	2	
R379,380	nsp	RES, CHIP(6432/5%/100ohm)	E1C	CRJ01HJ101T	2	
R382	nsp	RES, CHIP(1608/5%/10Kohm)	E1C	CRJ10DJ103T	1	
R384-386	nsp	RES, CHIP(1608/5%/10Kohm)	E1C	CRJ10DJ103T	3	
R401,402	nsp	RES, CHIP(2012/5%/10ohm)	E1C	CRJ18AJ100T	2	
R403,404	nsp	RES, CHIP(2012/5%/47ohm)	E1C	CRJ18AJ470T	2	
R405	nsp	RES, CHIP(1608/5%/100ohm)	E1C	CRJ10DJ101T	1	
R406,407	nsp	RES, CHIP(1608/5%/1Kohm)	E1C	CRJ10DJ102T	2	
R408	nsp	RES, CHIP(1005/5%/1Kohm)	E1C	CRJ06J102T	1	
R409	nsp	RES, CHIP(1608/5%/1Kohm)	E1C	CRJ10DJ102T	1	

REF No.	Part No.	Part Name	Remarks	Q'ty	New	Ver
R410-416	nsp	RES, CHIP(1608/5%/4.7Kohm)	E1C	CRJ10DJ472T	7	
R417-420	nsp	RES, CHIP(1608/5%/3.3Kohm)	E1C	CRJ10DJ332T	4	
R421,422	nsp	RES, CHIP(1608/5%/4.7Kohm)	E1C	CRJ10DJ472T	2	
R423,424	nsp	RES, CHIP(1608/5%/470ohm)	E1C	CRJ10DJ471T	2	
R425-431	nsp	RES, CHIP(1608/5%/47ohm)	E1C	CRJ10DJ470T	7	
R432	nsp	RES, CHIP(1608/5%/10Kohm)	E1C	CRJ10DJ103T	1	
R433-436	nsp	RES, CHIP(1608/5%/27Kohm)	E1C	CRJ10DJ273T	4	
R439-446	nsp	RES, CHIP(1608/5%/33ohm)	E1C	CRJ10DJ330T	8	
R447,448	nsp	RES, CHIP(1608/5%/22Kohm)	E1C	CRJ10DJ223T	2	
R449	nsp	RES, CHIP(1608/5%/100Kohm)	E1C	CRJ10DJ104T	1	
R450	nsp	RES, CHIP(1608/5%/22Kohm)	E1C	CRJ10DJ223T	1	
R451	nsp	RES, CHIP(1005/5%/0ohm)	E1C	CRJ06J0R0T	1	
R462	nsp	RES, CHIP(1608/1%/18Kohm)	E1C	CRJ10DF1802T	1	
R463,464	nsp	RES, CHIP(2012/5%/10ohm)	E1C	CRJ18AJ100T	2	
R465	nsp	RES, CHIP(1005/5%/0ohm)	E1C	CRJ06J0R0T	1	
R466,467	nsp	RES, CHIP(1005/5%/33ohm)	E1C	CRJ06J330T	2	
R469	nsp	RES, CHIP(1005/5%/0ohm)	E1C	CRJ06J0R0T	1	
R470	nsp	RES, CHIP(1608/5%/680ohm)	E1C	CRJ10DJ681T	1	
R471	nsp	RES, CHIP(1608/5%/22Kohm)	E1C	CRJ10DJ223T	1	
R474-477	nsp	RES, CHIP(1608/5%/47Kohm)	E1C	CRJ10DJ473T	4	
R479,480	nsp	RES, CHIP(1608/5%/4.7Kohm)	E1C	CRJ10DJ472T	2	
R481	nsp	RES, CHIP(2012/5%/47ohm)	E1C	CRJ18AJ470T	1	
R483	nsp	RES, CHIP(2012/5%/47ohm)	E1C	CRJ18AJ470T	1	
R485	nsp	RES, CHIP(1005/5%/10Kohm)	E1C	CRJ06J103T	1	
R486-489	nsp	RES, CHIP(2012/1%/5.6ohm)	E1C	CRJ18AF5R60T	4	
R490	nsp	RES, CHIP(1608/5%/10Kohm)	E1C	CRJ10DJ103T	1	
R600	nsp	RES, CHIP(1608/5%/100ohm)	E1C	CRJ10DJ101T	1	
R601	nsp	RES, CHIP(1608/5%/47Kohm)	E1C	CRJ10DJ473T	1	
R602	nsp	RES, CHIP(1608/1%/330Kohm)	E1C	CRJ10DF3303T	1	
R607,608	nsp	RES, CHIP(1005/5%/4.7Kohm)	E1C	CRJ06J472T	2	
R610-612	nsp	RES, CHIP(1005/5%/10Kohm)	E1C	CRJ06J103T	3	
R615	nsp	RES, CHIP(1005/5%/0ohm)	E1C	CRJ06J0R0T	1	
R617-619	nsp	RES, CHIP(1005/5%/0ohm)	E1C	CRJ06J0R0T	3	
R621	nsp	RES, CHIP(1005/5%/0ohm)	E1C	CRJ06J0R0T	1	
R622-635	nsp	RES, CHIP(1608/5%/10Kohm)	E1C	CRJ10DJ103T	14	
R639	nsp	RES, CHIP(1608/5%/10Kohm)	E1C	CRJ10DJ103T	1	
R646	nsp	RES, CHIP(1608/5%/120Kohm)	E1C	CRJ10DJ124T	1	
R647	nsp	RES, CHIP(1608/5%/2.2Kohm)	E1C	CRJ10DJ222T	1	
R648	nsp	RES, CHIP(1608/5%/27Kohm)	E1C	CRJ10DJ273T	1	
R649	nsp	RES, CHIP(1608/5%/100ohm)	E1C	CRJ10DJ101T	1	
R650-652	nsp	RES, CHIP(1608/5%/33ohm)	E1C	CRJ10DJ330T	3	
R653,654	nsp	RES, CHIP(1608/5%/100ohm)	E1C	CRJ10DJ101T	2	
R658	nsp	RES, CHIP(1608/5%/0ohm)	E1C	CRJ10DJ0R0T	1	
R659	nsp	RES, CHIP(1608/1%/348Kohm)	E1C	CRJ10DF3483T	1	
R660	nsp	RES, CHIP(1608/0.5%/348Kohm)	E1C	CRJ10DD3483T	1	
R661	nsp	RES, CHIP(1608/0.5%/110Kohm)	E1C	CRJ10DD1103T	1	
R662	nsp	RES, CHIP(1608/5%/33ohm)	E1C	CRJ10DJ330T	1	
R664	nsp	RES, CHIP(1608/5%/0ohm)	E1C	CRJ10DJ0R0T	1	
R666	nsp	RES, CHIP(1608/5%/0ohm)	E1C	CRJ10DJ0R0T	1	
R667-669	nsp	RES, CHIP(1608/5%/33ohm)	E1C	CRJ10DJ330T	3	
R670	nsp	RES, CHIP(1608/5%/0ohm)	E1C	CRJ10DJ0R0T	1	
R680	nsp	RES, CHIP(1608/5%/47Kohm)	E1C	CRJ10DJ473T	1	
R681	nsp	RES, CHIP(1608/5%/0ohm)	E1C	CRJ10DJ0R0T	1	
R683,684	nsp	RES, CHIP(1608/5%/0ohm)	E1C	CRJ10DJ0R0T	2	
R685	nsp	RES, CHIP(1608/5%/100ohm)	E1C	CRJ10DJ101T	1	
R690	nsp	RES, CHIP(1608/5%/75Kohm)	E1C	CRJ10DJ753T	1	
R693,694	nsp	RES, CHIP(1608/5%/0ohm)	E1C	CRJ10DJ0R0T	2	
R695	nsp	RES, CHIP(1608/1%/348Kohm)	E1C	CRJ10DF3483T	1	
R696	nsp	RES, CHIP(1608/1%/76.8Kohm)	E1C	CRJ10DF7682T	1	
R697	nsp	RES, CHIP(1608/5%/0ohm)	E1C	CRJ10DJ0R0T	1	
R698	nsp	RES, CHIP(1608/1%/348Kohm)	E1C	CRJ10DF3483T	1	
R699	nsp	RES, CHIP(1608/1%/169Kohm)	E1C	CRJ10DF1693T	1	
R700	nsp	RES, CHIP(1608/1%/2Kohm)	E1C	CRJ10DF2001T	1	
R701-704	nsp	RES, CHIP(1608/5%/1Kohm)	E1C	CRJ10DJ102T	4	
R705-708	nsp	RES, CHIP(1608/5%/100Kohm)	E1C	CRJ10DJ104T	4	
R710-713	nsp	RES, CHIP(1005/5%/100ohm)	E1C	CRJ06J101T	4	
R720,721	nsp	RES, CHIP(2012/5%/47ohm)	E1C	CRJ18AJ470T	2	
RX91-94	943129501060S	RES, CHIP(3216/5%/1.5Mohm)	E1C	CRJ14CJ155T	4	
CAPACITORS GROUP						
C200-209	nsp	CAP, CHIP(1005, 25V/0.01uF, X7R) SAMSUNG	E1C	CCUI1E103KCS	10	
C210-221	nsp	CAP, CHIP(1005, 16V/0.1uF, X7R) SAMSUNG	E1C	CCUI1C104KCS	12	
C222	nsp	CAP, CHIP(1608, 50V/1000pF, X7R) SAMSUNG	E1C	CCUS1H102KCS	1	
C223	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	E1C	CCUS1H104KCS	1	
C227-230	nsp	CAP, CHIP(1608, 16V/1uF, X7R) SAMSUNG	E1C	CCUS1C105KCS	4	
C231,232	nsp	CAP, CHIP(1608, 50V/100pF, C0G) SAMSUNG	E1C	CCUS1H101JAS	2	
C233-236	nsp	CAP, CHIP(1608, 50V/120pF, C0G) SAMSUNG	E1C	CCUS1H121JAS	4	
C237	nsp	CAP, CHIP(1608, 50V/100pF, C0G) SAMSUNG	E1C	CCUS1H101JAS	1	
C238-241	nsp	CAP, CHIP(1005, 50V/100pF, C0G) SAMSUNG	E1C	CCUI1H101JAS	4	
C242,243	nsp	CAP, CHIP(1608, 50V/100pF, C0G) SAMSUNG	E1C	CCUS1H101JAS	2	
C244-246	nsp	CAP, CHIP(1608, 50V/1000pF, X7R) SAMSUNG	E1C	CCUS1H102KCS	3	
C255-257	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG	E1C	CCUS1H103KCS	3	
C258	nsp	RES, CHIP(1608/5%/0ohm)	E1C	CRJ10DJ0R0T	1	
C259	nsp	CAP, CHIP(1005, 25V/0.01uF, X7R) SAMSUNG	E1C	CCUI1E103KCS	1	
C260-265	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG	E1C	CCUS1H103KCS	6	
C266	nsp	CAP, CHIP(1608, 50V/0.047uF, X7R) SAMSUNG	E1C	CCUS1H473KCS	1	
C267	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG	E1C	CCUS1H103KCS	1	
C269,270	nsp	CAP, CHIP(1608, 50V/1000pF, X7R) SAMSUNG	E1C	CCUS1H102KCS	2	
C271	nsp	CAP, CHIP(1608, 50V/560pF, C0G) SAMSUNG	E1C	CCUS1H561JAS	1	
C273-282	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	E1C	CCUS1H104KCS	10	
C283,284	nsp	CAP, CHIP(1608, 50V/15pF, C0G) SAMSUNG	E1C	CCUS1H150JAS	2	
C285,286	nsp	CAP, CHIP(1608, 50V/18pF, C0G) SAMSUNG	E1C	CCUS1H180JAS	2	
C287	nsp	CAP, CHIP(1608, 50V/560pF, C0G) SAMSUNG	E1C	CCUS1H561JAS	1	
C288	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG	E1C	CCUS1H103KCS	1	
C289,290	nsp	CAP, CHIP(1608, 50V/470pF, C0G) SAMSUNG	E1C	CCUS1H471JAS	2	
C291-294	nsp	CAP, CHIP(1608, 50V/4700pF, X7R) SAMSUNG	E1C	CCUS1H472KCS	4	
C295	nsp	CAP, CHIP(1608, 50V/0.047uF, X7R) SAMSUNG	E1C	CCUS1H473KCS	1	
C297	nsp	CAP, CHIP(1608, 50V/0.068uF, X7R) SAMSUNG	E1C	CCUS1H683KCS	1	
C298-304	nsp	CAP, CHIP(1608, 50V/1000pF, X7R) SAMSUNG	E1C	CCUS1H102KCS	7	
C305	nsp	RES, CHIP(1608/5%/0ohm)	E1C	CRJ10DJ0R0T	1	
C306-311	nsp	CAP, CHIP(1608, 50V/1000pF, X7R) SAMSUNG	E1C	CCUS1H102KCS	6	
C315-323	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG	E1C	CCUS1H103KCS	9	
C324	nsp	CAP, CHIP(1608, 6.3V/4.7uF, X5R) SAMSUNG	E1C	CCUSQJ475KCS	1	
C325-328	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG	E1C	CCUS1H103KCS	4	
C332-364	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	E1C	CCUS1H104KCS	33	
C365	nsp	CAP, CHIP(1005, 16V/0.1uF, X7R) SAMSUNG	E1C	CCUI1C104KCS	1	
C366-368	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	E1C	CCUS1H104KCS	3	
C369	nsp	RES, CHIP(1608/5%/0ohm)	E1C	CRJ10DJ0R0T	1	
C370-372	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	E1C	CCUS1H104KCS	3	
C373	nsp	CAP, CHIP(2012, 16V/10uF, X5R) SAMSUNG	E1C	CCUC1C106KCS	1	
C374	943134503400D	CAP, ELECT(50V/2.2uF)-S	E1C	CCEA1HKS2R2T	1	
C375-377	943134503370D	CAP, ELECT(16V/10uF)-S	E1C	CCEA1CKS100TC	3	
C378	943134503390D	CAP, ELECT(16V/100uF)-S,105°C	E1C	CCEA1CKS101TS	1	
C379,380	00D2544577958	CAP, ELECT(16V/220uF),ELNA/RA3	E1C	CCEA1CRA3221T	2	

REF No.	Part No.	Part Name	Remarks	Q'ty	New	Ver
C381	943134502040D	CAP, ELECT(16V/100uF)-S	E1C	CCEA1CK5101TC	1	
C382	00D2544577958	CAP, ELECT(16V/220uF), ELNA/RA3	E1C	CCEA1CRA3221T	1	
C383	nsp	CAP, ELECT(16V/47uF)-S	E1C	CCEA1CK5470T	1	
C384,385	nsp	CAP, SMD ELECT(16V/22uF)	E1C	CCEC1CMVG220T	2	
C386	943134503370D	CAP, ELECT(16V/10uF)-S	E1C	CCEA1CK5100TC	1	
C387	943134503400D	CAP, ELECT(50V/2.2uF)-S	E1C	CCEA1HKS2R2T	1	
C388	943134503380D	CAP, ELECT(16V/10uF)-S,105°C	E1C	CCEA1CK5100TS	1	
C389,390	943134503370D	CAP, ELECT(16V/10uF)-S	E1C	CCEA1CK5100TC	2	
C391	00D2544577958	CAP, ELECT(16V/220uF), ELNA/RA3	E1C	CCEA1CRA3221T	1	
C392	943134502580M	CAP, ELEC SMD(LOW ESR, 150UF/10V, ENESOL)	E1C	CCEC1AVS151TL	1	
C393	943134502570M	CAP, ELEC SMD(6.3V/220uF, PVVZ Series, ESR,105°C)	E1C	CCEC0JPVWZ221T3	1	
C395,396	nsp	CAP,ALUMINUM ELECTROLYTIC (6.3V/220uF)	E1C	CCEC0JMYG221T	2	
C397	943134502580M	CAP, ELEC SMD(LOW ESR, 150UF/10V, ENESOL)	E1C	CCEC1AVS151TL	1	
C398	943134502570M	CAP, ELEC SMD(6.3V/220uF, PVVZ Series, ESR,105°C)	E1C	CCEC0JPVWZ221T3	1	
C400	943134502570M	CAP, ELEC SMD(6.3V/220uF, PVVZ Series, ESR,105°C)	E1C	CCEC0JPVWZ221T3	1	
C401	nsp	CAP, CHIP(2012, 6.3V/10uF, X5R) SAMSUNG	E1C	CCUC0J106KCS	1	
C402	nsp	CAP, CHIP(1608, 16V/1uF, X7R) SAMSUNG	E1C	CCUS1C105KCS	1	
C403	nsp	CAP,ALUMINUM ELECTROLYTIC CAPACITORS(16V/100uF)	E1C	CCEC1CMVG101T	1	
C406	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG	E1C	CCUS1H103KCS	1	
C407	943134502570M	CAP, ELEC SMD(6.3V/220uF, PVVZ Series, ESR,105°C)	E1C	CCEC0JPVWZ221T3	1	
C408,409	nsp	CAP, CHIP(3216, 100V/0.01uF, MURATA GRM31)	E1C	CCUMUP2A103JAM	2	
C410-413	nsp	CAP, CHIP(1005, 50V/18pF, C0G) SAMSUNG	E1C	CCU1H180JAS	4	
C430	nsp	CAP, CHIP(1608, 6.3V/4.7uF, X5R) SAMSUNG	E1C	CCUS0J475KCS	1	
C450,451	nsp	CAP, CHIP(3216, 100V/0.01uF, MURATA GRM31)	E1C	CCUMUP2A103JAM	2	
C600-611	nsp	CAP, CHIP(1005, 16V/0.1uF, X7R) SAMSUNG	E1C	CCU1C104KCS	12	
C612	nsp	CAP, CHIP(1005, 25V/0.01uF, X7R) SAMSUNG	E1C	CCU1E103KCS	1	
C613,614	nsp	CAP, CHIP(1005, 50V/1000pF, X7R) SAMSUNG	E1C	CCU1H102KCS	2	
C615,616	nsp	CAP, CHIP(1005, 50V/4700pF, X7R) SAMSUNG	E1C	CCU1H472KCS	2	
C621-625	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG	E1C	CCUS1H103KCS	5	
C626	nsp	CAP, CHIP(1608, 50V/1000pF, X7R) SAMSUNG	E1C	CCUS1H102KCS	1	
C627-629	nsp	CAP, CHIP(2012, 6.3V/22uF, X5R) SAMSUNG	E1C	CCUC0J226KCS	3	
C630,631	nsp	CAP, CHIP(1608, 50V/1000pF, X7R) SAMSUNG	E1C	CCUS1H102KCS	2	
C632-637	nsp	CAP, CHIP(1608, 6.3V/4.7uF, X5R) SAMSUNG	E1C	CCUS0J475KCS	6	
C638	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	E1C	CCUS1H104KCS	1	
C639	nsp	CAP, CHIP(1608, 6.3V/4.7uF, X5R) SAMSUNG	E1C	CCUS0J475KCS	1	
C640,641	nsp	CAP, CHIP(2012, 6.3V/22uF, X5R) SAMSUNG	E1C	CCUC0J226KCS	2	
C642	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	E1C	CCUS1H104KCS	1	
C643	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG	E1C	CCUS1H103KCS	1	
C644	nsp	CAP, CHIP(2012, 6.3V/22uF, X5R) SAMSUNG	E1C	CCUC0J226KCS	1	
C648	nsp	CAP, CHIP(1608, 6.3V/4.7uF, X5R) SAMSUNG	E1C	CCUS0J475KCS	1	
C653,654	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	E1C	CCUS1H104KCS	2	
C655	nsp	CAP, CHIP(1005, 16V/0.1uF, X7R) SAMSUNG	E1C	CCU1C104KCS	1	
C656	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	E1C	CCUS1H104KCS	1	
C658,659	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	E1C	CCUS1H104KCS	2	
C660	nsp	CAP, CHIP(1608, 50V/1000pF, X7R) SAMSUNG	E1C	CCUS1H102KCS	1	
C662	nsp	CAP, CHIP(2012, 6.3V/22uF, X5R) SAMSUNG	E1C	CCUC0J226KCS	1	
C663,664	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	E1C	CCUS1H104KCS	2	
C665	nsp	CAP, CHIP(1608, 50V/1000pF, X7R) SAMSUNG	E1C	CCUS1H102KCS	1	
C666	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG	E1C	CCUS1H103KCS	1	
C667	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	E1C	CCUS1H104KCS	1	
C671	nsp	CAP, CHIP(1005, 16V/0.1uF, X7R) SAMSUNG	E1C	CCU1C104KCS	1	
C672	nsp	CAP, CHIP(1608, 10V/1uF, X7R, X7S) SAMSUNG	E1C	CCUS1A105KCS	1	
C673	nsp	CAP, CHIP(1608, 50V/3.3pF, C0G) SAMSUNG	E1C	CCUS1H3R3JAS	1	
C674	nsp	CAP, CHIP(2012, 6.3V/10uF, X5R) SAMSUNG	E1C	CCUC0J106KCS	1	
C675	nsp	CAP, CHIP(2012, 6.3V/22uF, X5R) SAMSUNG	E1C	CCUC0J226KCS	1	
C676	nsp	CAP, CHIP(2012, 6.3V/10uF, X5R) SAMSUNG	E1C	CCUC0J106KCS	1	
C677	nsp	CAP, CHIP(1005, 16V/0.1uF, X7R) SAMSUNG	E1C	CCU1C104KCS	1	
C678	nsp	CAP, CHIP(2012, 6.3V/10uF, X5R) SAMSUNG	E1C	CCUC0J106KCS	1	
C679	nsp	CAP, CHIP(1608, 10V/1uF, X7R, X7S) SAMSUNG	E1C	CCUS1A105KCS	1	
C680	nsp	CAP, CHIP(1608, 50V/5pF, C0G) SAMSUNG	E1C	CCUS1H050CAS	1	
C681	nsp	CAP, CHIP(2012, 6.3V/22uF, X5R) SAMSUNG	E1C	CCUC0J226KCS	1	
C682	nsp	CAP, CHIP(2012, 6.3V/10uF, X5R) SAMSUNG	E1C	CCUC0J106KCS	1	
C683	nsp	CAP, CHIP(1005, 16V/0.1uF, X7R) SAMSUNG	E1C	CCU1C104KCS	1	
C684	nsp	CAP, CHIP(2012, 6.3V/10uF, X5R) SAMSUNG	E1C	CCUC0J106KCS	1	
C685	nsp	CAP, CHIP(1608, 10V/1uF, X7R, X7S) SAMSUNG	E1C	CCUS1A105KCS	1	
C686	nsp	CAP, CHIP(1608, 50V/5pF, C0G) SAMSUNG	E1C	CCUS1H050CAS	1	
C687	nsp	CAP, CHIP(2012, 6.3V/22uF, X5R) SAMSUNG	E1C	CCUC0J226KCS	1	
C688	nsp	CAP, CHIP(2012, 6.3V/10uF, X5R) SAMSUNG	E1C	CCUC0J106KCS	1	
C689	nsp	CAP, CHIP(1005, 16V/0.1uF, X7R) SAMSUNG	E1C	CCU1C104KCS	1	
C690	nsp	CAP, CHIP(2012, 6.3V/10uF, X5R) SAMSUNG	E1C	CCUC0J106KCS	1	
C691	nsp	CAP, CHIP(1608, 10V/1uF, X7R, X7S) SAMSUNG	E1C	CCUS1A105KCS	1	
C692	nsp	CAP, CHIP(1608, 50V/5pF, C0G) SAMSUNG	E1C	CCUS1H050CAS	1	
C693	nsp	CAP, CHIP(2012, 6.3V/22uF, X5R) SAMSUNG	E1C	CCUC0J226KCS	1	
C694	943134503370D	CAP, ELECT(16V/10uF)-S	E1C	CCEA1CK5100TC	1	
C695	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	E1C	CCUS1H104KCS	1	
C696	nsp	CAP, ELECT(10V/220uF)-S	E1C	CCEA1AKS221T	1	
C697	nsp	CAP, CHIP(2012, 6.3V/22uF, X5R) SAMSUNG	E1C	CCUC0J226KCS	1	
C698	nsp	CAP, CHIP(2012, 6.3V/10uF, X5R) SAMSUNG	E1C	CCUC0J106KCS	1	
C699-707	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	E1C	CCUS1H104KCS	9	
C708-711	nsp	CAP, CHIP(1005, 16V/0.1uF, X7R) SAMSUNG	E1C	CCU1C104KCS	4	
C712	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	E1C	CCUS1H104KCS	1	
C713	nsp	CAP, CHIP(1005, 16V/0.1uF, X7R) SAMSUNG	E1C	CCU1C104KCS	1	
C714,715	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	E1C	CCUS1H104KCS	2	
C720-726	nsp	CAP, CHIP(2012, 6.3V/22uF, X5R) SAMSUNG	E1C	CCUC0J226KCS	7	
C732	nsp	CAP, CHIP(1005, 16V/0.1uF, X7R) SAMSUNG	E1C	CCU1C104KCS	1	
C733,734	nsp	CAP, CHIP(1005, 50V/1000pF)	E1C	CCU1H102KC	2	
OTHER PARTS GROUP						
BK61	nsp	BRACKET , PCB	E1C	CMD1A629	1	
BK62	nsp	BRACKET , PCB M3	E1C	CMD1A834	1	
BK63	nsp	BRACKET , NETWORK A	E1C	CMD1A900	1	
BN16	nsp	WIRE ASS'Y (5PIN, P=2mm, 80mm, STRAIGHT, SHIELD)	E1C	CWB1B0050804700T	1	*
CN10	nsp	LOCKING TYPE , STRAIGHT WAFER, 2mm	E1C	CJP05GI236ZW	1	
CN62	nsp	LOCKING TYPE , STRAIGHT WAFER, 2.5MM	E1C	CJP03GI237ZW	1	
CN63	nsp	LOCKING TYPE , STRAIGHT WAFER, 2mm	E1C	CJP05GI236ZW	1	
CN65	nsp	WAFER, FCC, SMD(07P-1mm, STRAIGHT)	E1C	CJP07GA193ZY	1	
CN66,67	nsp	WAFER, 64pin (2 x 32 x 1.27mm) SMD TYPE	E1C	CJP64GA312PZ	2	
CN90	nsp	WAFER, 2P, 3.96mm	E1C	CJP02KA060ZY	1	
CN92	nsp	LOCK-WAFER/ANGLE/2.5MM PITCH/5PIN	E1C	CJP05GJ289ZY	1	
CN93	nsp	LOCKING TYPE , STRAIGHT WAFER , 2MM	E1C	CJP13GI236ZW	1	
! CX91	943134503220D	CAP, X2(275VAC, 0.22uF, 12mm, SEORUYONG)	E1C	CQCF2E224KZFS	1	
ET20,21	nsp	PLATE , EARTH(TRONIC ELECTRONICS)	E1C	CJT1A026	2	
! F901	943652500300M	FUSE, 215 SERIES, 4A, 250V	E1C	CBA2C4000TLHEY	1	*
FH91,92	nsp	HOLDER , FUSE	E1C	KJCF5S	2	
JK20	943643102900D	Terminal 2P Speaker(PUSH BK,RD)	E1C	CJ35N029Z	1	
EXPLODED_C5	943643102910D	Terminal 2P Speaker(PUSH RD,BK)	E1C	CJ35N028Z	1	
JK22	943643103110D	JACK, RCA (3PIN, WH/RD/BK, Ni PLATE, VERTICAL)	E1C	CJJ4S058Z	1	
EXPLODED_C6	943643102460D	JACK , USB ANGLE TYPE (BLACK 1.5A)	E1C	CJJ9X014Z	1	
JK60	943643102430S	JACK , RJ-45 W/TRANSFORMER	E1C	CJJ9L029Z	1	
! JK90	943641500240D	INLET , AC , NON-POL (250V/2.5A PCB MOUNT TYPE)	E1C	CJ38A019Z	1	

	REF No.	Part No.	Part Name	Remarks		Q'ty	New	Ver
	JW20,21 EXPLODED M4	nsp	SUPPORT , PCB	E1C	CDF1A035	2		
	L204	nsp	FERRITE CHIP BEAD(4516/60R)	E1C	CLZ9Z014Z	1		
	L205-208	nsp	FERRITE , CHIP BEAD(60ohm, 2012)	E1C	CLZ9R001Z	4		
	L209	nsp	BEAD , FERRITE (FCM2012KF-121T08 , 120 OHM)	E1C	CLZ9R010Z	1		
	L210-221	nsp	FERRITE , CHIP BEAD(60ohm, 2012)	E1C	CLZ9R001Z	12		
	L322	nsp	FERRITE CHIP BEAD(1608/60R,CB03YTYH600)	E1C	CLZ9R005V	1		
	L341	nsp	FERRITE CHIP BEAD(1608/60R,CB03YTYH600)	E1C	CLZ9R005V	1		
	L451-461	nsp	FERRITE CHIP BEAD(1608/60R,CB03YTYH600)	E1C	CLZ9R005V	11		
	L600,601	nsp	FERRITE , CHIP BEAD(60ohm, 2012)	E1C	CLZ9R001Z	2		
	L602	nsp	FERRITE CHIP BEAD(2012/220R, CB05YTYH221)	E1C	CLZ9R018V	1		
	L603	nsp	FERRITE , CHIP BEAD(60ohm, 2012)	E1C	CLZ9R001Z	1		
	L604	nsp	FERRITE CHIP BEAD(2012/220R, CB05YTYH221)	E1C	CLZ9R018V	1		
	L605-609	nsp	FERRITE , CHIP BEAD(60ohm, 2012)	E1C	CLZ9R001Z	5		
	L610,611	nsp	COMMON MODE FILTER (2012, 90ohm)	E1C	CLZ9Z174Z	2		
	L614	nsp	FERRITE CHIP BEAD(4516/60R)	E1C	CLZ9Z014Z	1		
	L615,616	nsp	FERRITE CHIP BEAD(2012/220R, CB05YTYH221)	E1C	CLZ9R018V	2		
	L617-619	nsp	FERRITE , CHIP BEAD(60ohm, 2012)	E1C	CLZ9R001Z	3		
	LF91	943111100490M	FILTER , LINE(DMC250)	E1C	CLZ9Z087Z	1		
	LF92	943111101310S	EOL item LINE, FILTER(5.0A/5.0mH)	E1C	CLZ9Z158Z	1		
	PF12	nsp	WAFER, FFC(27P-1.25mm, STRAIGHT)	E1C	CJP27GA115ZY	1		
	PF15	nsp	WAFER, FFC, SMD(11P-1mm, STRAIGHT)	E1C	CJP11GA193ZY	1		
	PF60	nsp	WAFER, FFC(25P-1mm, STRAIGHT)	E1C	CJP25GA117ZY	1		
	PF70,71	nsp	FEMALE HEADER (6P 2.54mm) , STRAIGHT TYPE	E1C	CJP06GA221ZB	2		
	PF72	nsp	FEMALE HEADER (12P 2.54mm) , STRAIGHT TYPE	E1C	CJP12GA221ZB	1		
	PF80	nsp	WAFER, FFC(19P-1mm, STRAIGHT)	E1C	CJP19GA117ZY	1		
	SW60	943662100180M	SW, TACT, VERTICAL (3.3mm)	E1C	CST1A032ZT	1		
	VT91	943251100070M	VARISTOR(560V, 14mm)	E1C	CRV5VC561D14A	1		
	WF22	nsp	WAFER, FFC, SMD(07P-1mm, STRAIGHT)	E1C	CJP07GA193ZY	1		
	WF23	nsp	WAFER, FFC, SMD(4pin, 1mm, STRAIGHT)	E1C	CJP04GA193ZY	1		
	WF60	nsp	WAFER, FFC(25P-1mm, STRAIGHT)	E1C	CJP25GA117ZY	1		
	X200	943141100610S	X-TAL, SMD 3.2X2.5, 12.000MHz, 10PF	E1C	COX120001100ST	1		
	X201	943141100620S	X-TAL, SMD 3.2X2.5, 24.576MHz, 12PF	E1C	COX245761120ST	1		

DAMP PCB ASS'Y

※Parts indicated by "nsp" on this table cannot be supplied.

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NOTE: The symbols in the column Remarks indicate the following destinations.

E3 : U.S.A. & Canada model E2 : Europe model E1C : China model E1 : Asia model JP : Japan model

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REF No.	Part No.	Part Name	Remarks	Q'ty	New	Ver
SEMICONDUCTORS GROUP						
D700,701	201310001503S	DIODE, ULTRA-HIGH SPEED		CVDKDS160RTKP	2	
IC70	00D2623503911	I.C , STEREO DIGITAL AMP		CVITAS5142DKDG4	1	
Q700	943215500140D	T.R,RT1P144C(10K-47K)		CVTRT1P144C	1	
Q701	943216500020S	T.R,RT1N141C(10K-10K)		CVTRT1N141C	1	
Q702	00D2730464901	T.R , CHIP , SOT-23		HVTKTC3875SYRTH	1	
Q703	00D9430058908	T.R , CHIP , SOT-23		HVTKTA1504SYRTH	1	
Q704	00D2730464901	T.R , CHIP , SOT-23		HVTKTC3875SYRTH	1	
Q705	00D9430058908	T.R , CHIP , SOT-23		HVTKTA1504SYRTH	1	
RESISTOR GROUP						
R700-703	nsp	RES, CHIP(1608/5%/0ohm)		CRJ10DJ0R0T	4	
R704,705	nsp	RES, CHIP(1608/5%/1Kohm)		CRJ10DJ102T	2	
R706-709	nsp	RES, CHIP(1608/5%/10Kohm)		CRJ10DJ103T	4	
R710	nsp	RES, CHIP(1608/5%/39Kohm)		CRJ10DJ393T	1	
R711-714	nsp	RES, CHIP(2012/1%/18ohm)		CRJ18AF18R0T	4	
R715,716	nsp	RES, CHIP(1608/5%/0ohm)		CRJ10DJ0R0T	2	
R719	nsp	RES, CHIP(1608/5%/1ohm)		CRJ10DJ1R0T	1	
R724	nsp	RES, CHIP(1608/5%/100Kohm)		CRJ10DJ104T	1	
R725	nsp	RES, CHIP(1608/5%/47Kohm)		CRJ10DJ473T	1	
R726,727	nsp	RES, CHIP(1608/5%/100Kohm)		CRJ10DJ104T	2	
R728	nsp	RES, CHIP(1608/5%/47Kohm)		CRJ10DJ473T	1	
R729	nsp	RES, CHIP(1608/5%/10Kohm)		CRJ10DJ103T	1	
R731	nsp	RES, CHIP(1608/5%/0ohm)		CRJ10DJ0R0T	1	
R734-736	nsp	RES, CHIP(1608/5%/0ohm)		CRJ10DJ0R0T	3	
R738	nsp	RES, CHIP(1608/5%/0ohm)		CRJ10DJ0R0T	1	
R739-742	nsp	RES, CHIP(1005/5%/100ohm)		CRJ06DJ101T	4	
CAPACITORS GROUP						
C700-709	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG		CCUS1H104KCS	10	
C710	nsp	CAP, CHIP(1608, 16V/1uF, X7R) SAMSUNG		CCUS1C105KCS	1	
C712	943132500660M	CAP, CHIP(1608, 100V/330pF, MURATA GRM18)		CCUMUS2A331JAM	1	
C713	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG		CCUS1H104KCS	1	
C714	nsp	CAP, CHIP(2012, 50V/1uF, X7R, X7S) SAMSUNG		CCUC1H105KCS	1	
C715,716	nsp	CAP, CHIP(2012, 50V/0.033uF, X7R) SAMSUNG		CCUC1H333KCS	2	
C721,722	nsp	CAP, CHIP(2012, 50V/1uF, X7R, X7S) SAMSUNG		CCUC1H105KCS	2	
C723	nsp	CAP, CHIP(2012, 50V/0.033uF, X7R) SAMSUNG		CCUC1H333KCS	1	
C724	nsp	CAP, CHIP(2012, 50V/1uF, X7R, X7S) SAMSUNG		CCUC1H105KCS	1	
C725,726	943132500660M	CAP, CHIP(1608, 100V/330pF, MURATA GRM18)		CCUMUS2A331JAM	2	
C727	nsp	CAP, CHIP(1608, 50V/1000pF, X7R) SAMSUNG		CCUS1H102KCS	1	
C729	943132500660M	CAP, CHIP(1608, 100V/330pF, MURATA GRM18)		CCUMUS2A331JAM	1	
C733-736	nsp	CAP, CHIP(2012, 25V/22uF, X7R) SAMSUNG		CCUC1E226KCS	4	
C737	943132100550D	CAP, CHIP(3216, 10uF/50V, X5R) SAMSUNG		CCUP1H106KCS	1	*
C739	943132100550D	CAP, CHIP(3216, 10uF/50V, X5R) SAMSUNG		CCUP1H106KCS	1	*
C740	nsp	CAP, CHIP(2012, 50V/0.01uF, X7R) SAMSUNG		CCUC1H103KCS	1	
C741-744	nsp	CAP, CHIP(2012, 100V/0.1uF, X7R) SAMSUNG		CCUC2A104KCS	4	
C745	nsp	OPEN DZ17-077			1	8
C746,747	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG		CCUS1H104KCS	2	
C748	943132100550D	CAP, CHIP(3216, 10uF/50V, X5R) SAMSUNG		CCUP1H106KCS	1	*
C749	nsp	CAP, CHIP(2012, 50V/0.033uF, X7R) SAMSUNG		CCUC1H333KCS	1	
C750	943133502190D	CAP,METAL-FILM(100V/0.47uF, TOSHIN MMSSDC Series)		CCME2A474KD30T	1	*
C752	943132100550D	CAP, CHIP(3216, 10uF/50V, X5R) SAMSUNG		CCUP1H106KCS	1	*
C753-755	00D9430101208	CAP, ELECT(16V/100uF),105°C		CCEA1CH101TS	3	
C756	943133502190D	CAP,METAL-FILM(100V/0.47uF, TOSHIN MMSSDC Series)		CCME2A474KD30T	1	*
C757,758	943134503410D	CAP, ELECT(UTWXZ , 50V/330uF, D18XL40),105°C		CCEA1HUTWXZ332	2	*
EXPLODED C32	nsp					
C760-762	nsp	CAP, CHIP(1608, 50V/1000pF, X7R) SAMSUNG		CCUS1H102KCS	3	
C763,764	00MOA22702520	CAP, ELECT(25V/220uF)		CCEA1EH221T	2	
C770-772	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG		CCUS1H104KCS	3	
OTHER PARTS GROUP						
JW71	nsp	WIRE ASS'Y(1P, 80MM,BLK,#22)		CWE5202080A	1	
L708,709	943115100620D	INDUCTOR, 10uH+20%(SAGAMI DLM1623 Series)		CLZ9Z189Z	2	*
L711	nsp	FERRITE , CHIP BEAD(60ohm, 2012)		CLZ9R001Z	1	
WF70,71	nsp	PIN SOCKET,SMD(06PIN,2.54mm,8.5mm Height,STRAIGHT)		CJP06GA300ZB	2	
WF72	nsp	PIN SOCKET,SMD(12PIN,2.54mm,8.5mm Height,STRAIGHT)		CJP12GA300ZB	1	
EXPLODED M1	nsp	SINK , HEAT(MCR510)		CMY1A400	1	
★	nsp	SCREW		CTB3+8JR	2	

CD PCB ASS'Y

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REF No.	Part No.	Part Name	Remarks	Q'ty	New	Ver
SEMICONDUCTORS GROUP						
D800-802	00D9430060501	DIODE , RECTIFIER	HVD1SR159-200	3		
D803	943209001080S	DIODE , CHIP , SWITCHING	CVD1SS355T	1		
D805,806	943209001080S	DIODE , CHIP , SWITCHING	CVD1SS355T	2		
IC80	943231101640S	IC, REGULATOR(1A, 8V)	CVILM7808RTRL	1		
IC81	943239006900S	I.C , 5-CH MOTOR DRIVE(REG,SSOP-28P)	CVIIP4001CRLTF C	1		
IC83	943245006980S	I.C , CD DSP(DSP,LQFP-80P)	CVITC94A92FG CU	1		
IC84	943231101630S	I.C REGULATOR 1.5V LDO,SOT-223	CVILM1117C-1V5	1		
Q800	00D9430058908	T.R , CHIP , SOT-23	HVTKTA1504SYRTK	1		
RESISTOR GROUP						
R800	nsp	RES, CHIP(1608/5%/4.7Kohm)	CRJ10DJ472T	1		
R801-803	nsp	RES, CHIP(1608/5%/47Kohm)	CRJ10DJ473T	3		
R804	nsp	RES, CHIP(1608/5%/91ohm)	CRJ10DJ910T	1		
R805	nsp	RES, CHIP(1608/5%/0ohm)	CRJ10DJ0R0T	1		
R806-813	nsp	RES, CHIP(1608/5%/10Kohm)	CRJ10DJ103T	8		
R814	nsp	RES, CHIP(1608/5%/1Mohm)	CRJ10DJ105T	1		
R815-816	nsp	RES, CHIP(1608/5%/100ohm)	CRJ10DJ101T	2		
R817	nsp	RES, CHIP(1608/5%/0ohm)	CRJ10DJ0R0T	1		
R818	nsp	RES, CHIP(1608/5%/15Kohm)	CRJ10DJ153T	1		
R819-822	nsp	RES, CHIP(1608/5%/10Kohm)	CRJ10DJ103T	4		
R824	nsp	RES, CHIP(1608/5%/220ohm)	CRJ10DJ221T	1		
R825-829	nsp	RES, CHIP(1608/5%/33ohm)	CRJ10DJ330T	5		
R832	nsp	RES, CHIP(1608/5%/330Kohm)	CRJ10DJ334T	1		
R833-836	nsp	RES, CHIP(1608/5%/39ohm)	CRJ10DJ390T	4		
R837	nsp	RES, CHIP(1608/5%/470ohm)	CRJ10DJ471T	1		
R840	nsp	RES, CHIP(1608/5%/470ohm)	CRJ10DJ471T	1		
R841	nsp	RES, CHIP(1608/5%/4.7Kohm)	CRJ10DJ472T	1		
R842-845	nsp	RES, CHIP(1608/5%/0ohm)	CRJ10DJ0R0T	4		
R847-849	nsp	RES, CHIP(1608/5%/100ohm)	CRJ10DJ101T	3		
R850-855	nsp	RES, CHIP(1608/5%/0ohm)	CRJ10DJ0R0T	6		
R862	nsp	RES, CHIP(1608/5%/51ohm)	CRJ10DJ510T	1		
R863	nsp	RES, CHIP(1608/5%/1Kohm)	CRJ10DJ102T	1		
R864	nsp	RES, CHIP(1608/5%/10Kohm)	CRJ10DJ103T	1		
R865-872	nsp	RES, CHIP(1608/5%/0ohm)	CRJ10DJ0R0T	8		
CAPACITORS GROUP						
C800	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	CCUS1H104KCS	1		
C802-804	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	CCUS1H104KCS	3		
C805-808	nsp	CAP, CHIP(1608, 50V/1000pF, X7R) SAMSUNG	CCUS1H102KCS	4		
C809-815	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	CCUS1H104KCS	7		
C816-819	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG	CCUS1H103KCS	4		
C820	nsp	CAP, CHIP(1608, 50V/5600pF, X7R) SAMSUNG	CCUS1H562KCS	1		
C822-827	nsp	CAP, CHIP(1608, 50V/0.01uF, X7R) SAMSUNG	CCUS1H103KCS	6		
C828-836	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	CCUS1H104KCS	9		
C838-852	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	CCUS1H104KCS	15		
C853,854	nsp	CAP, CHIP(1608, 50V/15pF, C0G) SAMSUNG	CCUS1H150JAS	2		
C855,856	nsp	CAP, CHIP(1608, 50V/0.015uF, X7R) SAMSUNG	CCUS1H153KCS	2		
C857-859	nsp	CAP, CHIP(1608, 50V/22pF, C0G) SAMSUNG	CCUS1H220JAS	3		
C860	nsp	CAP, CHIP(1608, 50V/2200pF, X7R) SAMSUNG	CCUS1H222KCS	1		
C861	nsp	CAP, CHIP(1608, 50V/0.033uF, X7R) SAMSUNG	CCUS1H333KCS	1		
C862	nsp	CAP, CHIP(1608, 50V/47pF, C0G) SAMSUNG	CCUS1H470JAS	1		
C863,864	nsp	CAP, CHIP(1608, 50V/470pF, C0G) SAMSUNG	CCUS1H471JAS	2		
C865	nsp	CAP, CHIP(1608, 50V/4700pF, X7R) SAMSUNG	CCUS1H472KCS	1		
C866	nsp	CAP, CHIP(1608, 50V/0.047uF, X7R) SAMSUNG	CCUS1H473KCS	1		
C868	nsp	CAP, CHIP(1608, 50V/0.047uF, X7R) SAMSUNG	CCUS1H473KCS	1		
C869-879	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	CCUS1H104KCS	11		
C880,881	90M-EJ000010R	CAP, ELECT(10V/100uF)-S	CCEA1AKS101T	2		
C883-886	943134503340D	CAP, ELECT(10V/100uF)	CCEA1AH101TC	4	*	
C887	943134501960D	CAP, ELECT(25V/47uF)-S	CCEA1EKS470TC	1		
C888	90M-EJ000010R	CAP, ELECT(10V/100uF)-S	CCEA1AKS101T	1		
C889,890	00D943010390S	CAP, ELECT(16V/470uF)	CCEA1CH471T	2		
C891,892	943134503350D	CAP, ELECT(10V/470uF)	CCEA1AH471TC	2	*	
C893	943134503360D	CAP, ELECT(16V/220uF)	CCEA1CH221TC	1	*	
C894	943134503340D	CAP, ELECT(10V/100uF)	CCEA1AH101TC	1	*	
C895	90M-EJ000010R	CAP, ELECT(10V/100uF)-S	CCEA1AKS101T	1		
C896-901	nsp	CAP, CHIP(1608, 50V/0.1uF, X7R) SAMSUNG	CCUS1H104KCS	6		
OTHER PARTS GROUP						
CN80	nsp	WAFER , STRAIGHT(DVD LOADER)	CJP06GA19ZY	1		
CN81	nsp	LOCKING TYPE , STRAIGHT WAFER , 2mm	CJP05GI236ZW	1		
CN82	nsp	WAFER , STRAIGHT	CJP05GA19ZY	1		
JK80	nsp	PLATE , EARTH(TRONIC ELECTRONICS)	CJT1A026	1		
JW80	nsp	WIRE ASS'Y(1P, 80MM,BLK,#22)	CWE5202080A	1		
L800-802	nsp	FERRITE CHIP BEAD(4516/60R)	CLZ9Z014Z	3		
L803	90M-LU000220R	INDUCTOR CHIP 10UH (3225 PKG)	HLQ10E100KRZ	1		
WF80	nsp	WAFER, FFC(19P-1mm, STRAIGHT)	CJP19GA117ZY	1		
WF81	nsp	WAFER, FFC(16P-1mm, STRAIGHT)	CJP16GA117ZY	1		
X800	943141001190S	X-TAL, 16.934MHz, HC-49/SMD, 12pF, 25PPM	COX16934E120S	1		

EXPLODED

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REF No.	Part No.	Part Name	Remarks		Q'ty	New	Ver
C1	943639101980D	RCD-N9 SMPS PCB ASSY	E2, E1C	COP12676B	1	*	2
C1	943639101990D	RCD-N9 SMPS PCB ASSY	JP	COP12676C	1	*	2
C4	nsp	RCD-N9 DAMP PCB ASSY		COP12675B	1	*	
C34	nsp	RCD-N9 MAIN PCB ASSY	E2, JP	COP12674B	1	*	
C34	nsp	RCD-N9 MAIN PCB ASSY	E1C	VOP12906E	1	*	5
└C22	-	AC INLET PCB ASSY		CUP12674Z	1	*	
└C23	-	NETWORK/WIFI PCB ASSY		CUP12674Z	1	*	
└C25	-	USB PCB ASSY		CUP12674Z	1	*	
└C35	-	SUPPORT PCB		CUP12674Z	1	*	
C24	nsp	RCD-N9 FRONT PCB ASSY		COP12673B	1	*	
└C26	-	H/P PCB ASSY		CUP12673Z	1	*	
└C28	-	KEY PCB ASSY		CUP12673Z	1	*	
└C29	-	TUNER/DIGITAL PCB ASSY		CUP12673Z	1	*	
C30	nsp	RCD-N9 CD PCB ASSY		COP12677B	1	*	
C36	943189101050D	CY920 MODULE ASSY See Procedure after Replacing the Microprocessor, etc..	E2, E1C JP common	RCDN9E2AS	1	*	4
└C27-WF14	C36 SET	MODULE, NFC (AMOTECH, Stiffener=0.35mm, 4P)		-	1	*	
└C37 PF80-WF80	C36 SET	Module.Network(BT,WiFi,USB), ANT 2EA Only RCDN9		-	1	*	
C7 PF12-WF11	943606502660D	CABLE, CARD (27P, 1.25mm, 200mm, B TYPE, SHIELD)		CWC6F4A27B200B0	1	*	
C8 PF13-WF13	943606502670D	CABLE, CARD (5P, 1mm, 80mm, B TYPE)		CWC4F4A05A080B0	1	*	
★ PF80-WF80	943606502680D	CABLE, CARD (19P, 1mm, 50mm, B TYPE)		CWC4F4A19A050B0	1	*	
★ PF15-WF15	943606502690D	CABLE, CARD (11P, 1mm, 80mm, B TYPE)		CWC4F4A11A080B0	1	*	
★ PF60-WF60	943606502700D	CABLE, CARD (25P, 1mm, 50mm, B TYPE, SHIELD)		CWC6F4A25A050B0	1	*	
★ WF81-CD	943606502710D	CABLE, CARD (16P, 1mm, 100mm, A TYPE)		CWC4F4A16A100A0	1	*	2
C9 BN16-CN16	nsp	WIRE ASSY LOCKING TYPE (5P, 2mm, 50mm)		CWB1B00505047	1	*	
C9 BN93-CN93	nsp	ROCKING TYPE WIRE ASSY(13P, 180MM, 2.0MM)		CWB1B01318047	1	*	
C10 BN10-CN10	nsp	WIRE ASSY (5PIN, 2mm PITCH, 150mm, UL TUBE)		CWB1B0051504700	1	*	
C11 BN62-CN62	nsp	WIRE ASSY (3PIN, 2.5mm PITCH, 80mm, ANGLE)		CWB1D00308059	1	*	
C12 BN63-CN63	nsp	WIRE ASSY (5PIN, 2mm PITCH, 180mm, SHIELD)		CWB1C9051804600	1	*	
C13 BN92-CN92	nsp	WIRE ASSY (5PIN, 2.5mm PITCH, 280mm, STRAIGHT)		CWB1D00528058	1	*	
C14 BN90-CN90	nsp	WIRE ASSY (3PIN, 3.96mm PITCH, 50mm, STRAIGHT)		CWB4D003050VZ	1	*	
C15 BN91-CN91	nsp	WIRE ASSY (5PIN, 2.5mm PITCH, 120mm, STRAIGHT)		CWB1D0051205800	1	*	
C16 BN81-CN81	nsp	WIRE ASSY LOCKING TYPE (5P, 2mm, 50mm)		CWB1B00505047	1	*	
C17 CN82-CD	nsp	WIRE ASSY(LOCKING, 5P, 150MM, 2.0MM)		CWB1B005150EG00	1	*	
C18 CN80-CD	nsp	WIRE ASSY		CWB5A906080EG	1	*	
M5	nsp	BOTTOM CHASSIS		CUA3A346	1	*	
M6	nsp	CHASSIS, FRONT		CUF1A026	1	*	
M7	nsp	SHIELD, COVER(TOP)		CMC2A449	1	*	
M8	nsp	COVER, SHIELD OLED		CMC1A448	1	*	
M9	nsp	PLATE, SPEAKER		CMC1A467	1	*	
M10	nsp	PANEL, REAR CHASSIS	E2	CKF1A488Z	1	*	
M10	nsp	PANEL, REAR CHASSIS	JP	CKF1A488Y	1	*	
M10	nsp	PANEL, REAR	E1C	VKF1A488U	1	*	5
P1	943402105160D	FRONT PANEL (BK)	BK	CGW1A561ZR12	1	*	
P1	943402105170D	FRONT PANEL (WT)	WT	CGW1A561ZR11	1	*	
P2	943402105180D	SIDE PANEL (BK)	BK	CKD1A095R12	2	*	
P2	943402105190D	SIDE PANEL (WT)	WT	CKD1A095R11	2	*	
P3	943402105260D	PANEL, REAR MOLD	BK	CGP1A044R12	1	*	
P3	943402105270D	PANEL, REAR MOLD	WT	CGP1A044R11	1	*	
P4	943418100540D	LOADER PANEL (BK)	BK	CGR1A581R12	1	*	
P4	943418100550D	LOADER PANEL (WT)	WT	CGR1A581R11	1	*	
P5	943416101450D	WINDOW		CGU1A488Z	1	*	
P6	943403101200D	TOP PANEL (BK)	BK	CKD1A093Y	1	*	
P6	943403101210D	TOP PANEL (WT)	WT	CKD1A093Z	1	*	
P7	943403101220D	TOP PANEL INNER (BK)	BK	CKD1A094RH	1	*	
P7	943403101230D	TOP PANEL INNER (WT)	WT	CKD1A094R25	1	*	
P8	nsp	HOLDER, OLED		CMH1A346	1	*	
P9	nsp	INSULATOR, POWER		CMX1A329	1	*	
P10	943407100570D	FOOT		CKL1A102	4	*	2
P11	943407100580D	RUBBER, FOOT		CHG1A297	4	*	2
P12	nsp	INSULATOR, SMPS		CMX1A328	1	*	
P13	943302100130D	CJDKT690 CD MECHA ASSY DCD720		CJDKT690EJ	1	*	
└★	900302100200S	CD MECHANISM (Traverse)		CJD5C6201Z	1	*	
└★	30201005100AD	LM BELT	For LOADING	CDV1A011	1	*	2
P14	nsp	SUPPORT, MECA - R		CMH1A363	1	*	
P15	nsp	SUPPORT, MECA - L		CMH1A364	1	*	
P19	943411103390D	BUTTON, CURSOR ASSY	BK	CBT1A1201XR12A	1	*	
P19	943411103400D	BUTTON, CURSOR ASSY	WT	CBT1A1201XR11A	1	*	
P20	943411103410D	BUTTON, ENTER	BK	CBT1A1202XR12	1	*	
P20	943411103420D	BUTTON, ENTER	WT	CBT1A1202XR11	1	*	
P21	943411103430D	BUTTON, POWER ASSY	BK	CBT1A1206R12A	1	*	
P21	943411103440D	BUTTON, POWER ASSY	WT	CBT1A1206R11A	1	*	
P22	943411103450D	BUTTON, VOLUM UP ASSY	BK	CBT1A1199XR12A	1	*	
P22	943411103460D	BUTTON, VOLUM UP ASSY	WT	CBT1A1199XR11A	1	*	
P23	943411103470D	BUTTON, VOLUM DOWN ASSY	BK	CBT1A1199YR12A	1	*	
P23	943411103480D	BUTTON, VOLUM DOWN ASSY	WT	CBT1A1199YR11A	1	*	
P24	943411103490D	BUTTON, SELECT ASSY	BK	CBT1A1200XR12A	1	*	
P24	943411103500D	BUTTON, SELECT ASSY	WT	CBT1A1200XR11A	1	*	
P25	nsp	INSULATOR, NETWORK		CMX1A351	1	*	
P26	943411103510D	BUTTON, Eject ASSY	BK	CBT1A1199ZR12A	1	*	
P26	943411103520D	BUTTON, Eject ASSY	WT	CBT1A1199ZR11A	1	*	
★	nsp	RUFFER, FL CRX-E320		CHG1A364	1	*	
★	nsp	SHEET, LIGHTING		CMX1A359	1	*	
S2	nsp	SCREW		CTB3+6JR	10	*	
S3	nsp	SCREW		CTB3+6JFZR	17	*	
S4	nsp	SCREW		CTB3+10JFZR	24	*	
★	nsp	SCREW		CTB3+6FFZR	3	*	
★	nsp	SCREW		CTB3+6FR	5	*	
★	nsp	SCREW		CTB3+8JR	2	*	
★	nsp	SCREW		CTS3+8JFZR	8	*	

PACKING

※Parts indicated by "nsp" on this table cannot be supplied.

※The parts listed below are only for maintenance. Therefore they might differ from the parts used in the unit in appearances or dimensions

NOTE: The symbols in the column Remarks indicate the following destinations.

E3 : U.S.A. & Canada model E2 : Europe model E1C : China model E1 : Asia model JP : Japan model

BK : Black model SP : Premium Silver model WT : White model

REF No.	Part No.	Part Name	Remarks		Q'ty	New	Ver
1	54111123100AD	QUICK MANUAL (E2)	E2	CQX1A1863Z	1	*	
1	54111123300AD	QUICK MANUAL (JP)	JP	CQX1A1864Z	1	*	
1	54111146200AD	QUICK MANUAL	E1C	VQX1A2011Z	1	*	5
2	943533102830D	CUSHION TOP		CPS1A1004	1	*	
3	943539100910D	SHEET, TOP		CQE1A717Z	1	*	
5	943533102840D	CUSHION CENTER		CPS1A1006	1	*	
!	943693100510D	CORD, POWER EUR(H03VVH2-F 2X0.75MM, TIE WHT)	BKE2	CJA2B108YV	1	*	
!	943611501020D	AC CORD WT (E2)	WTE2	CJA2B146ZL	1	*	
!	943611009390S	CORD, POWER JPN(VCTFK 2X0.75MM, TIE WHT)	JP	CJA2J116YV	1	*	
!	943611500440S	CORD, POWER CHINA(RVV 300/300V 2X0.75MM, TIE WHT)	E1C	CJA2N078X	1	*	5
7	963116100070S	ANT, AM LOOP(9.5uH/5T)		CSA1A039Y	1		
8	943116100170D	FM 1 POLE ANT (UL TYPE)		CSA1A044Z	1		
9	nsp	BAG, ZIPPER POLY(A5)		CPB1A227Z	1		
10	943533102850D	CUSHION BOTTOM		CPS1A1005	1	*	
11	nsp	BATTERY, AAA 2PCS IN PACK		CABR03PPB	2		
12	30701021000AD	REMOCON TRANSMITTER ASS'Y (RCD-N9 BK Ver.)	BK	CARTRCDN9BK	1	*	
12	30701021100AD	REMOCON TRANSMITTER ASS'Y (RCD-N9 WT Ver.)	WT	CARTRCDN9WT	1	*	
13	943531104650D	BOX, OUT CARTON EUROPE	E2	CPG1A1034Z	1	*	
13	943531104870D	BOX, OUT CARTON JAPAN	JP	CPG1A1034Y	1	*	
13	943531106190S	BOX, OUT CARTION	E1C	VPG1A1034X	1	*	5
14	544110091014M	LABEL, WHITE M1 SG	WT	CQB1A908Z	1		
15	nsp	CONTROL, LABEL		CQB1A993Z	1		
17	-	INSTRUCTION MANUAL ASS'Y EUR	E2	CQXRCDN9WTE2	1		
17	-	INSTRUCTION MANUAL JPN	JP	CQXRCDN9W	1		
17	-	INSTRUCTION MANUAL ASS'Y	E1C	VQXRCDN9BKE1C	1	*	5
17-1	nsp	BAG, ZIPPER POLY(A5)		CPB1A227Z	1		
17-2	35201036500AD	INSTRUCTION MANUAL (E2)	E2	CFT1A159ZA	1	*	2
17-2	54111123400AD	INSTRUCTION MANUAL (JP)	JP	CQX1A1883Z	1	*	2
17-2	54111146100AD	MANUAL, INSTRUCTION	E1C	VQX1A2012Z	1	*	5
17-3	nsp	SAFETY INSTRUCTION		CQE1A750Z	1		
17-4	nsp	NOTES ON RADIO		CQE1A749Z	1		
19	nsp	SET SHEET (750*750, NO PRINT)		CPB2A215	1		
19	nsp	BAG, POLY		CPB1A008Z	1		
@	nsp	China Tuner Isolator, SGLBF-6B	E1C	CLR9Z001Z	1		5
@	nsp	WARRANTY CARD, CHINA	E1C	VQE1A473V	1		5
@	nsp	CARD FOR CHINA IDENTIFICATION	E1C	VQE1A450Z	1		5